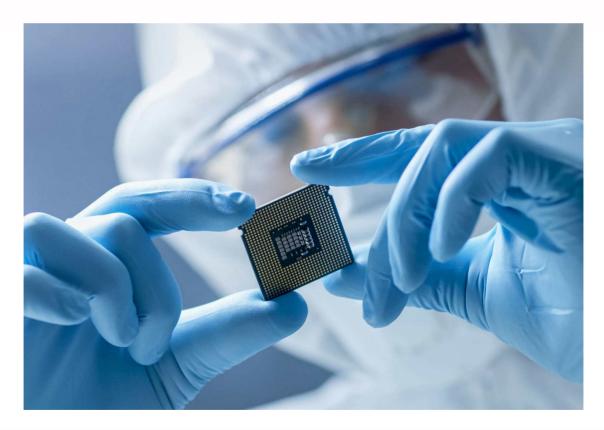
MATERIALS SCIENCE AND ENGINEERING

Dr. Usman Pasha Dr. Pulleparthi Naidu





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CHAPTER 1

APPLICATION OF THE DEFORMATION OF MATERIALS

Dr. Usman Pasha, Associate Professor, Department of Physics, Presidency University, Bangalore, India, Email Id-mahaboobpasha@presidencyuniversity.in

ABSTRACT

In the field of materials science and engineering, the concept of material deformation is crucial. This process entails a material changing in size or shape as a result of external forces or tensions. Designing and creating different products and constructions requires a thorough understanding of the behavior of materials under deformation. The deformation of materials, including the various kinds of deformation mechanisms and the variables affecting material response, are covered in this abstract. We go over the ideas of elasticity, plasticity, and viscoelasticity, which control how materials deform. We also stress the significance of researching material deformation using a variety of experimental and computational methods. A key concept in materials science and engineering is the deformation of materials, which refers to the transformation of a material's size or shape in response to applied forces. This abstract gives a general review of how materials deform, emphasizing the many modes of deformation, the elements that affect deformation behavior, and the importance of comprehending and managing deformation in a variety of applications. Different forms of deformation, such as elastic deformation, plastic deformation, and fracture, can take place. When the applied force is withdrawn, elastic deformation is reversible, and the material returns to its original shape. A permanent change in size or shape is referred to as plastic deformation, which is defined by the movement of dislocations inside the crystal structure of the material. When the material's strength is exceeded by the amount of applied stress, a fracture takes place and the material separates.

KEYWORDS

Deformation, Metals, Plastic, Slip, Stress, Twinning.

INTRODUCTION

Introduction length can be as per the nature of the topic. Hence it can be prepared as per the discretion of the author.Deformation of materials refers to the alteration of their shapes or dimensions as a result of applied forces. Deformation in a material can be caused by a variety of physical and physico-chemical processes, such as changes in the volume of individual crystallites during phase transformations or as a result of temperature gradients, as well as by the mechanical action of external forces. In everyday use, all materials typically experience some deformation due to the application of external loads. This kind of distortion is what we are mostly worried about. Deformations fall into one of two categories: Temporary deformations are those that are (i) recoverable or elastic after the removal of an external force or applied load, and permanent deformations are those that are non-recoverable, plastic or visco-elastic and persist even after the removal of the deforming force or applied load. Both of these deformations have the potential to be independent of time or time-dependent. Even at room temperature, metals show less elastic but more plastic deformation, whereas steady flow predominates at higher temperature ranges.

Displacements are represented by the difference between a metallic body's geometrical coordinates in its loaded and unloaded positions. These displacements are evidence of the body's deformation in a material body. When simply a length change, such as an increase or reduction, occurs, the deformation is referred to as longitudinal. On the other hand, the deformation is referred to as angular when the angles between the various body faces

vary.initial volume, or change in density, and the initial stage, or change in distortion, are what make up a material body's deformation. It is obvious that the entire deformation can be divided into distortional and volumetric components[1], [2].

Elastic Deformation

Numerous solid materials respond elastically, or deform when loaded but return to theiroriginal size and shape, or position, when the force or load is removed. Metals, ceramics, rubbers, and polymers all exhibit this kind of behavior. A solid can experience elastic deformation as a result of pressure changes, the application of force or load, or both. According to what we've read, elasticity is a property of solids that depends on both their chemical bonds and their internal structures because it derives from forces between the atoms of the solid. However, crystalline flaws like vacancies and dislocations have no effect on a material's elastic characteristics. Fig. 1 presents an illustration of elastic deformation.

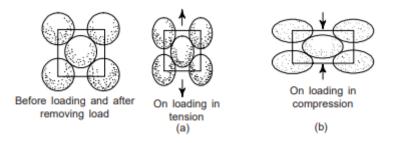


Fig.1 shows elastic deformation in solid material(newagepublishers.com)

The deformation is described as an ideal deformation because it occurs instantly when a force or load is applied and fully vanishes when the force or load is removed. Such material deformations adhere to Hooke's law (Stress & Strain). The strain caused by this tension shouldn't be greater than 1% of the material's original length. The elastic deformation of other non-crystalline materials, such rubber, is several hundred times greater than that of metals, which is just approximately one percent. It is important to highlight that perfect deformation can occur with very small deformation forces, which can keep working stresses within the elastic limit.

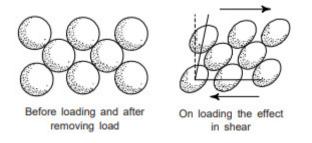


Fig.2 shows elastic shear strain(newagepublishers.com)

The crystal structures of materials are also subjected to shearing loads in engineering practice. In a material, a shearing stress created by the shearing load causes one plane of atoms to move in relation to nearby planes of atoms (Fig. 2). Obviously, shear stress causes the atoms in one layer to slip past those in the next. Shear is not directly affected by the modulus of elasticity. However, the elastic shear strain and shear stress are directly related. The relationship between the shear strain and shear stress is constant up to the elastic displacement limit.

Plastic Deformation

Only strains of approximately 0.005 for elastic deformation to continue for the majority of metallic materials. Beyond this point, Hooke's law no longer holds true, meaning that stress is

no longer proportionate to strain and permanent, irreversible, or plastic deformation takes place. The tensile stress-strain behaviour into the plastic zone for a typical metal is shown in Fig.3. The yield strength y and the proportional limit P have been calculated using the 0.002 strain offset method[3]. For the majority of metals, the change from elastic to plastic occurs gradually; at the start of plastic deformation, there is some curvature; this curvature grows more quickly with increasing stress. Tensile, compressive, and torsional stresses can all result in plastic deformation. Applied stress, strain rate, and temperature control all affect how quickly plastic deformation occurs. Ductility is the term used to describe a metal's capacity for plastic deformation. A change in shape happens along with a number of other changes when a metal is plastically deformed; cold deforming, in particular, makes a metal stronger. A metal's ductility ensures the structural integrity of its constituent parts under load and counteracts the effects of stress concentrations. Plastic deformation is purposefully used in processes including rolling, forging, extrusion, spinning, pressing, drawing, stamping, and others. We should remember that the fluidity of the metals completely determines their machinability and wear resistance[3], [4].Plastic deformations are based on the irreversible displacement of atoms through significant distances from their equilibrium from an atomic perspective. Since several atoms or molecules shift in relation to one another when under stress, it stands to reason that plastic deformation corresponds to the breaking of bonds with original atom neighbors and subsequently reconstructing of bonds with new neighbors. For crystalline and amorphous materials, this deformation has a different mechanism. Deformation of crystalline solids is performed through a procedure termed slip, which involves the movement of dislocations. Viscose flow is a mechanism that causes plastic deformation in non-crystalline solids and liquids.

DISCUSSION

Mechanism of Plastic Deformation

Let's take a single crystal as an illustration and investigate the mechanism of plastic deformation. When tangential stresses exceed the critical value (cr), they work to shear one region of the crystal relative to another, causing plastic deformation in the single crystal. Two main types of shear, namely slip and twinning, cause plastic deformation of a single crystal (Fig. 3). In the former scenario, a crystal's one portion is sheared or displaced parallel to its other portion along a plane. The most common type of shear in metals and alloys is slip. According to Fig. 3, deformation via twinning is essentially the rearranging of a crystallographic section into a new position that is mirror-symmetrical to the undamaged portion. The twinning plane is the name given to the plane of mirror symmetry. The atomic planes of a crystal are offset parallel to the twinning plane by various amounts in a twinning plane. The deformation twin is the area of the crystal where the crystal lattice has been reoriented as a result of twinning. Slip has a greater impact than twinning. Twining becomes more important when slip is hindered. Twinning is only seen in BCC and FCC metals at low temperatures or rapid deformation rates. Under typical conditions, deformation in HCP metals can happen by both slip and twinning[5], [6].

Deformation by slip

Slip is the word used to describe the process through which dislocation motion results in plastic deformation. Plastic deformation is the microscopic equivalent of the mobility of dislocations in response to an externally imposed shear stress. The movement of dislocations, or slip, in response to an applied shear stress is what causes macroscopic plastic deformation, which is just persistent deformation.

On particular crystallographic planes and only inside these planes in particular directions does slip happen. Operable slip systems depend on the material's crystal structure. A slip system is a slip plane-slip direction combination.

Factors Affecting Critical Shear Stresses

- (i) The critical stress value is lower for pure metals, i.e., the critical stresses are decreased by metal purity.
- (ii) The critical shear stress is significantly increased by surface phenomena, such as surface deposits.
- (iii) As temperature rises, critical shear stress drops but thermal mobility increases.
- (iv) The critical shear stress can also be increased by the rate of deformation and the degree of initial distortion.
- (v) Polycrystalline materials exhibit a tad more complex deformation and slide. The direction of the slide varies from one grain to another as a result of the multiple grains' variable crystallographic orientations.

Characteristics of Dislocation

According to what we've read, the process by which dislocation motion results in plastic deformation is known as slip. Dislocation motion is comparable to a caterpillar's manner of locomotion. All metals and alloys have some dislocations that were added during the solidification or the plastic deformation processes. Fast cooling causes thermal strains as a result of deformation and deformation itself. The total dislocation length per unit volume, or alternatively, the number of dislocations that intersect a unit area of a random section, is used to express the number of dislocations, or dislocation density, in a material. Per square millimeter is how dislocations are measured. Metals that have undergone significant deformation may have densities as high as 109 to 1010/mm2. A deformed metal specimen can have its density reduced to between 105 and 106 / mm2 by applying heat to it. Between 102 and 104 /mm2 is the usual dislocation density for ceramic materials. Dislocations are surrounded by strain fields, which have an impact on both their mobility and their capacity to proliferate. A little portion of the deformation energy (about 5%) is stored internally and the majority is released as heat when metals are plastically deformed. The majority of this energy is present as strained energy linked to dislocations. The number of dislocations drastically rises during plastic deformation[7], [8].

Effects of Dislocation on Cold Working

It has been discovered that interactions between different types of dislocations can render a dislocation immobile or at best decrease its mobility. Because more contacts result from an increase in density, the mobility of the dislocations diminishes as density rises. It goes without saying that a material's dislocation density affects its yield stress. A crystalline substance can be plastically deformed to raise the dislocation density. The impact of deformation on the steel's tensile properties, including tensile strength, yield point, hardness, and elongation. But cold working, which involves deforming a material at room temperature or lower, strengthens and hardens it. The amount of elongation that a specimen can withstand before breaking is reduced by cold working.

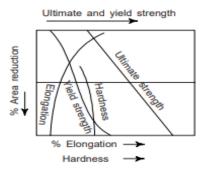


Fig. 3 Shows effect of cold working on tensile properties(steel)(newagepublishers.com)

All of these occurrences can be explained by the decrease in dislocating mobility brought on by raising the dislocation density. For hardness, it is discovered that penetration depends on dislocation mobility and entails persistent deformation.

Deformation by Twining

Twinning is the division of a lattice into two symmetrical but otherwise unrelated portions as a result of atoms moving around within it. A mirror image is created across the twin plane because the amount of movement of each plane in the twinned region is proportional to its distance from the twinning plane.

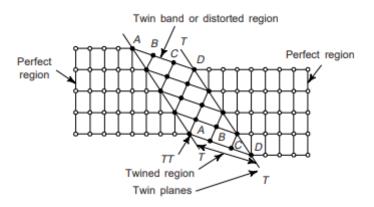


Fig. 4 shows deformation in crystal by twinning (newagepublishers.com)

Similar to slip, twinning almost often occurs in specialized aircraft referred to as twinning planes. Similar to slip aircraft, twinning planes have a large fixed portion. The twinning plane is the plane in the FCC lattice (111), the plane in the BCC lattice (112) and the plane in the HCP lattice (112). Fig. 4 shows deformation in crystal by twinning. The twinning plane in Fig. 5 is the (111) plane, and the twinning direction is ML.

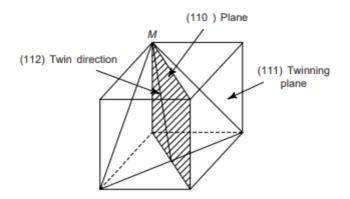


Fig. 5 shows twin plane and twin direction (newagepublishers.com)

Except in cases where we are concerned with low temperature areas or rapid forming processes, twinning is not typically a relevant deformation mechanism for cubic metals. Twining becomes more noticeable and is seen in HCP metals and can be seen at room temperature. In HCP crystals, twinning occurs on the (1 012) plane in the direction of (1 011). The crystal area between the twin planes is reoriented by twinning and consequently by putting the planes of potential slip in an orientation that is more suitable for dislocation slide, enables further slip. The contour of the surface can also be altered through twinning. Considering that twinning occurs suddenly and is accompanied by sound. In most cases, impact, thermal treatment, and plastic deformation result in twinning. Similar to annealing, the motions of twin boundaries during heat treatment are important. However, for ductile HCP crystals, the maximum amount of distortion caused by twinning may be a few

percent[9], [10]. Twins can occur as a result of annealing after plastic deformation or mechanical deformation. Mechanical twins are the first kind of twins, and annealing twins are the second. Mechanical twins are created in BCC and HCP metals when shock loading and temperature is reduced at a quick rate. However, FCC metals are not typically thought to deform by mechanical twinning, despite the fact that low-temperature gold-silver alloys twin quite easily. Copper mechanical twins have been created at 4 K.

Neumann bands

According to what we've read, twinning typically results from impact, thermal treatment, and plastic deformation. When the applied stress is greater than necessary due to strain or low temperature, thin lamellar twins become visible. Neumann bands are what they are known as. When BCC iron and its alloys are rapidly loaded at lower temperatures, these bands become visible.Fig. 6 shows Neumann bands.

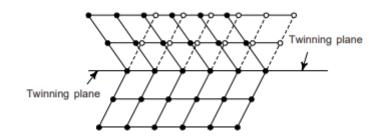


Fig. 6 shows Neumann bands (newagepublishers.com).

Plastic Deformation of Polycrystalline Materials

In comparison to single crystals, deformation and slide are a little more complicated in polycrystalline materials. The direction of slip changes from one grain to another, as is the case, for example, in brass, due to the random crystallographic orientations of the many grains and the influence of nearby atoms. Because they are composed of numerous tiny crystals or grains, ordinary metals are polycrystalline aggregates. We may observe that the crystal's geometric regularity is what allows the slip mechanism to work. Dislocation motion happens along the slip system that has the most advantageous orientation for each.

A polycrystalline specimen's overall plastic deformation is equivalent to the same distortion of the individual grains caused by a slip. The grain boundaries often do not separate or open up during deformation because mechanical integrity and coherency are maintained along the boundaries of the grains. Because of this, each grain has some limitations on the possible shapes that it can take from its neighbors. The grains are equi-axed, or roughly the same size in all directions, before deformation occurs. The grains elongate along the direction that the specimen was expanded for this specific deformation. Since polycrystalline metals are more robust than their single-crystal counterparts, more pressures are needed to cause slide and the ensuing yielding. This is mostly a function of the geometrical restrictions placed on the grains during deformation. Even if a single grain may be slippably orientated with the given stress, it cannot deform until the nearby grains, which are less slippably oriented, are also able to slip, which necessitates a greater applied stress level. The following are the properties of polycrystalline metals:

(i) During the loading of polycrystalline metals, different grains have unpredictable orientations that can cause slide.

(ii) Because of the random orientations, more force is needed, and as a result, the resolved shear stress is not constant but changes with grain orientation.

(iii) All of a polycrystalline metal's crystals are perfectly elastic under load. A crystal contains a number of slip planes. Deformation is caused by significant structural changes.

(iv) Polycrystalline metals exhibit elastic aftereffects, in contrast to single crystals. This effect is used in the hardening of work.

(v) After elastic deformation, metal polycrystalline crystals can exhibit a sizeable degree of persistent deformation as well as a sizeable amount of yielding.

Season Cracking

The result is metal breakdown. Season cracking is brought on by the interaction of intercrystalline corrosion and internal tension. This phrase is typically used to describe metals like brass. A specimen may still contain internal tensions with a very high intensity after cold processing. If metals are stored for a long time, these pressures might cause corrosion in certain metal parts. In ammonia-containing environments, internal tensions make alpha brass highly prone to inter-granular cracking. The occurrence of corrosive substances like seawater, industrial air, etc., speeds up the formation of cracks. By annealing the brass at 200–300°C, this flaw can be fixed. It's noteworthy to notice that greater zinc or alloying content causes an aggressive reaction to inter-granular assault along the grain boundaries, which enhances the likelihood of brass cracking.

Bauschinger effect

This is the directionality of straining, which states that it is simpler to bend a material in the opposite direction if strain hardening occurs as a result of applying stress in a specific direction. We can also observe that a material will exhibit a yield point in compression at Y, where Y is smaller than Y, if it exhibits a yield point stress of Y in tension and continues to deform from tension to compression in the same cycle. The primary cause of this effect is that, on a certain slip plane, reversing slip direction requires less stress than maintaining slip in the origin direction.

Anelasticity

We've assumed up to this point that elastic deformation is time independent, meaning that an applied stress causes an immediate elastic strain that stays constant throughout the duration of the stress's maintenance. We have also presumptively assumed that the strain is fully healed after the load is released, or that it immediately goes back to zero. However, a timedependent elastic strain component will be present in the majority of engineered materials. It goes without saying that elastic deformation will continue after the tension is applied, and after the load is released, a certain amount of limited time is needed for full recovery. Anelasticity is the term used to describe this time-dependent elastic behaviour, in which the strain follows the tension. This is a result of time-dependent microscopic and atomistic deformation-related processes. Because it is often insignificant for metals, the anelastic component is disregarded. Its magnitude is large for some polymeric materials though, and in this situation it is referred to as viscoelastic behaviour. A considerable amount of energy will be lost due to anelasicity in an anelastic material if the load repeats cyclically. This energy dissipation will increase the materials' ability to dampen vibrations, which is necessary for those materials to absorb the vibration. Other materials may experience unwanted heating as a result of this energy loss.

Yield Point Phenomenon and Related effects

Most constructions are designed by engineers such that when a stress is applied, only elastic deformation will occur. Knowing the stress level at which plastic deformation starts or where the phenomena of yielding happens is desirable. The point of yielding, also known as the

proportional limit, can be identified for metals that go through this slow elastic-plastic transition as the first departure from linearity of the stress-strain curve, as shown by point P. In such circumstances, it could be difficult to pinpoint the exact location of the point P. A straight line is drawn parallel to the elastic part of the stress-strain curve at a specific strain off set, often 0.002, in order to precisely determine point P. The yield strength y (here, "strength" is used in place of stress) is the stress that corresponds to the point on the stress-strain curve where it intersects this line as it bends over the plastic zone. Yield strength is measured in MPa.

The strain offset approach is useless for materials that have a non-linear elastic region. The standard procedure in such a circumstance is to define the yield strength as the stress necessary to create a certain amount of strain, for example, = 0.005. A sample of mild steel was loaded, and some steels and other materials display the stress-strain diagram that resulted. It is extremely well understood that the elastic plastic transition occurs suddenly in a phenomena known as the yield point. With a real reduction in stress, plastic deformation begins at the upper yield point. The lower yield point, or continuous deformation, swings slightly around some fixed stress value. However, as the strain grows, stress too does. The average stress associated with the lower point for metals that exhibit this effect is regarded to be the yield strength. It goes without saying that for these materials, the strain offset approach is not necessary.

We should be aware that a metal's resistance to plastic deformation is reflected in the size of the yield strength for that metal. Yield strengths can range from 35 MPa for aluminium with low strength to more than 1400 MPa for steel with high strength. Yield points have also been noted for polycrystalline metals including molybdenum and aluminium alloys in addition to iron and steel. The yield point phenomenon is crucial for a number of forming procedures, including stamping and drawing thin sheets for making automotive parts, among others. The Luders bands and stretcher strains, strain ageing, blue brittleness, and orange peel effect are all linked effects of yield point.

(i) Luders Bands: These reflect the surface markings on a tensile test sample that are created at the stress concentration sites, much like fillets. When many bands are generated, the stressstrain curve is erratic during yield point elongation, and these bands are typically at 45° to the tensile axis. When separating the yielding from the non-yielding sections of the sample, luders bands are used. These bands develop as a result of jogs. Formation of these indicates the appearance of the higher yield point. At several locations on the sample, such as both ends of the gauge length, luder bands can be seen. The flow will grow as the strain increases when Luder bands spread out and cover the entire length. Here the yield point elongation is completed. Luders bands produce a rough look on the surface of the metal sheet during drawing and stamping operations, and they must be avoided on the finished goods. Prior to prevent this uneven yielding effect. This aids in eradicating the occurrence of yield points.

(ii) Strain Ageing: This term, which is connected to the yield point phenomena, describes how an overstrained alloy's characteristics evolve over time. If the test sample that has been overstrained is left to rest or age after plastic deformation, the yield point must be removed since it will reappear with higher stress. However, the yield point will appear if the specimen is unloaded and rested without ageing because of weak dislocation effects from the environment of carbon and nitrogen atoms. New interstitials are created and the dislocations are anchored by carbon and nitrogen atoms. Because nitrogen is more soluble and diffuses more easily than carbon, it is more significant in the strain ageing of iron. Hardening caused by an increase in stress value occurs along with strain ageing, also known as strain-agehardening. The aforementioned phenomena is seen when the yield point from the test reappears after the sample has been unloaded, rested, or aged for a while. Commercial steel and iron exhibit this tendency. The analysis of the fatigue and creep behaviour of particular metals is significantly impacted by this.

(iii) Blue Brittleness: The yield point becomes less pronounced and the blue brittleness effect is developed as the test temperature range is raised. The temperature range for ordinary carbon steel is 200 to 370°C. On the other hand, this impact is visible between 160 and 300 °C. It is clear that the section of the stress vs. strain diagram displays a steeper curve with the rapid creation of subsequent yield points as a result of these effects.

(iv) Orange Peel Effects: Metals develop these stains when they are stretched. This characteristic of surface roughening is seen in low-temperature forming processes of coarsegrained metals. Grain refining gets rid of this impact. If interstitial atoms (C, O, H, and N) build up on dislocations and lock them, creating segregations or cottrell atmospheres, they can significantly contribute to the strengthening effect. Higher stresses are needed to release a dislocation in such atmospheres, which anchor the dislocations. The value of this stress, however, ought to correlate to higher yield points. Free dislocations lower the yield point, as we may observe.Stress-strain diagrams demonstrate the yield point and blue brittleness of Cottrell atmospheres.

CONCLUSION

Materials deformation is a complicated phenomenon that is crucial to many engineering and manufacturing processes. Researchers and engineers can create materials and structures that can withstand and respond to a variety of external stresses by understanding the behavior of materials under diverse loading circumstances. Elastic deformation is appropriate for applications requiring reversible deformation because it enables materials to revert to their original shape after the applied load is withdrawn.

Materials' mechanical characteristics, such as strength, hardness, and ductility, as well as the amount of stress applied, the temperature, and the rate of loading, all have an impact on how they deform. Depending on their crystal structure, composition, and past processing, several materials display unique deformation mechanisms, such as slip, twinning, and dislocation motion. For molding and forming materials into desired configurations, plastic deformation, on the other hand, entails irreversible changes in shape. Viscoelastic behavior exhibits time-dependent reactions to applied stresses and incorporates properties of both elasticity and plasticity.

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CHAPTER 2

AN ANALYSIS OF THE OXIDATION AND CORROSION

Dr. VeerabhadrappaJagadeesha, Assistant Professor, Department of Physics, Presidency University, Bangalore, India, Email Id-jagadeeshaangadi@presidencyuniversity.in

ABSTRACT

Natural processes like corrosion and oxidation take place when materials interact with their surroundings. The performance, longevity, and structural integrity of different materials and structures may be adversely affected by these processes. For reducing their impacts and creating more durable materials, it is crucial to understand the mechanisms and variables affecting oxidation and corrosion. We give an overview of oxidation and corrosion in this abstract and emphasize the importance of these processes in various industries. We go into the underlying mechanics, such as electrochemical reactions and corrosion product production. Additionally, we investigate the numerous variables, including temperature, humidity, pH, and the presence of corrosive materials, that affect the rate and severity of oxidation and corrosion. The integrity and performance of materials can be dramatically impacted by the destructive processes of oxidation and corrosion. This abstract examines the mechanics of oxidation and corrosion as well as the causes, risk factors, and mitigation strategies for both. The term "oxidation" describes the reaction that takes place when an object comes into contact with oxygen and produces oxide molecules. Contrarily, corrosion refers to the degradation of materials brought on by chemical or electrochemical interactions with the environment. The mechanical, electrical, and chemical properties of materials can deteriorate as a result of either process.

KEYWORDS

Alloys, Corrosion, Galvanic, Metal, Surface, Stress.

INTRODUCTION

The majority of materials come into contact with a variety of distinct surroundings to varying degrees. A material's usefulness is frequently reduced by such interactions with the environment because its mechanical properties, such as ductility and strength, other physical attributes, or appearance, deteriorate. The three types of materials have been determined to have various deteriorative mechanisms. Metals really lose material, either through corrosion (dissolution) or oxidation (creation of non-metallic scale or film). It has been discovered that ceramic materials are comparatively resistant to degradation, which typically happens at high temperatures or in quite harsh settings. Corrosion is another term widely used to describe the process. When it comes to polymers, the mechanisms and results of degradation are different from those for metals and ceramics. When exposed to a liquid solvent, polymers may dissolve or absorb the solvent and swell. Additionally, electromagnetic radiation (especially UV radiation) and heat may affect the molecular structure of polymers.

The following types of corrosions are significant: (i) Direct corrosion, (ii) Electrochemical corrosion, (iii) Galvanic corrosion, and (iv) High temperature oxidation corrosion.

Corrosion-Resistant Materials

In addition to the appropriate mechanical capabilities, structural materials suitable for use in aggressive conditions must have a good corrosion resistance. Metals and alloys are the materials that are most sensitive to corrosion, which is understandable given their high chemical activity and high electrical conductivity. The accidental and harmful attack on a metal is known as corrosion of metals. It usually starts at the surface and is electrochemical in

nature. Corrosion's effects are all too often. Auto body panels, radiator, and exhaust system parts rusting are common examples of metals corroding. The spontaneous decomposition of metals caused by chemical or electrical interaction with the environment is known as corrosion. Metals and alloys that are corrosion-resistant may survive the corrosive action of a medium, meaning that corrosion processes occur in them slowly. The two main types of corrosion are typically distinguished as electrochemical and chemical. Corrosion is affected by the following factors: (i) internal structure; (ii) chemical composition; (iii) environment or working conditions, such as stresses, temperature, or concentration; (iv) surface film; (v) the presence of dirt, dust, or other foreign matter; (vi) the distribution of secondary phases; (vii) blow holes, inclusions, and trapped gases; (viii) eddy electric currents; and (ix) the type of engineering application[1], [2].

Electrochemical Corrosion

This type of corrosion forms in aqueous solutions of salts, alkalies, and acids, as well as in wet soil and environment, salt water, and fresh water. When a metal interacts electrochemically with an electrolyte, it dissolves and an electric current appears. This is known as electrochemical corrosion. Electrons are moved from one chemical species to another. In what is referred to as an oxidation reaction, metal atoms often lose or give up electrons. When a metal is submerged in an electrolyte, its electrochemically inhomogeneous surface causes the creation of micro-galvanic corrosion cells. An overall electrochemical reaction will be the product of at least one oxidation and one reduction. We should take note that the individual reduction and oxidation reactions are frequently referred to as half-reactions. The entire rate of oxidation and reduction must be equal in order for there to be no net electrical charge accumulation from the electrons and ions. It goes without saying that reduction must eat up every electron produced by oxidation.

Electrode Potentials

Some of the metal ions leave the crystal and enter solution when the iron rod is submerged in a polar solvent like water. In other words, they get hydrated and establish bonds with the polar water molecules. A net negative charge accumulates in the metal as more and more electrons are held back as the metal continues to disintegrate. Similar to this, the presence of too many positive ions causes the solution next to it to become positively charged. The metal is prevented from further dissolving in the solvent by these opposing electrical layers. (However, not every metallic substance oxidises to create ions with equal ease. Without any net influx of metal ions into the solution, a dynamic equilibrium is evidently quickly reached. A characteristic of the metal that forms the electrode is the voltage that it develops when it is in equilibrium.The reactions are brought on by the disparity in potential between the electrodes. The type of the electrolyte and temperature affect the electrode potential. With a pure metal serving as the electrode and an electrolyte holding a unit concentration of the same metal's ions, this potential is measured under normal conditions[3], [4].

Galvanic (two-metal) Corrosion

When a metal and an electrolyte come into contact, a reaction occurs that releases metal ions into the electrolyte. However, very quickly an equilibrium is reached, and the reaction is stopped in its tracks. Now, if a different metal forms a second electrode, this electrode will also reach the same equilibrium. The equilibrium is now upset if the circuit is finished to permit current flow. Let's imagine that water serves as the electrolyte, with copper (Cu) serving as the first electrode and zinc (Zn) serving as the second electrode. This configuration is known as a galvanic cell.

Rapid corrosion occurs when different metals come into touch with one another, much like in a galvanic cell. Anodic metal won't corrode if we can keep dissimilar metals from coming into direct touch with one another. Because of this, it is preferred that in fabrication operations, the electrodes used for welding and the rivets used for riveting have the same chemical makeup as the base metal. Due to the steel's preference for brass screws over unprotected steel, galvanic corrosion has also been observed on unprotected steel in ships. An underground pipe line that travels through porous sand in some areas and impenetrable clay in others may corrode in the clay zone. In the same metal, various residual stresses might result in the formation of a galvanic cell. In comparison to a region that is not under stress, the stressed region is more active and anodic. Stress cells are a particular subset of galvanic cells. When grain borders are anodic to the interior of the grains in a cold wrought metal or polycrystalline metal, these types of cells can form between regions of variable dislocation density. It's interesting to note that a bent wire is more likely to corrode where it has been plastically distorted, at the bend[5], [6].

DISCUSSION

The Galvanic Series

No voltages are given, but the alloys towards the top of the chart are cathodic and inert whereas those near the bottom are mostly anodic. It's interesting to note that the most relative places of pure base metals exhibit a high degree of correlation when the standard emf and galvanic series are compared. Most metals and alloys are susceptible to oxidation or corrosion to varying degrees in a wide range of conditions, i.e., they are more stable in an ionic state than as metals. The thermodynamic transition from metallic to oxidized states results in a net loss of free energy. Because of this, almost all metals are found in nature as compounds, such as oxides, hydroxides, carbonates, silicates, sulphides, and sulphates. Gold and platinum are two significant exceptions. Both of these two metals may exist in nature in the metallic state because oxidation for these two metals is typically not advantageous.

These steps can be performed to lessen the consequences of galvanic corrosion:

(i) If coupling of dissimilar metals is required, two metals that are close to one another in the galvanic series may be chosen.

(ii) The anode area should be as large as possible and a negative anode-to-cathode surface area ratio should be avoided.

(iii)Metals should be electrically isolated from one another.

(iv)Electrically join the third metal to the first two.

(v) Cathodic protection is what is used in this.

High Temperature Oxidation or Dry Corrosion

High temperatures cause ferrous alloys to corrode and produce oxides and scales. By adding alloying elements that have good qualities for high temperature service and are resistant to oxidation in some metals, one can stop this corrosion. High temperature corrosion also happens when liquid metals pass other metals. In essence, a corrosion reaction is a mass transfer mechanism that is not fueled by the potentials of the local cell. Actually, the tendency of the solid to dissolve in the liquid metal up to the solubility limit at a certain temperature is what causes corrosion. We should be aware that the liquid-metal attack may result in the selective extraction of one of the component metals from a solid alloy, a simple solution of the solid metal, a chemical compound, or both. When there is a gradient in the solid-liquid system's temperature or concentration, this happens. Heat exchangers using (Bi and Na) liquid coolants have been observed to suffer severe damage from liquid-metal assault. As the solid container, often copper tubing, approaches equilibrium with the liquid-metal coolant in the hot zone of the heat exchanger, some of the solid dissolves into the

liquid. As the liquid flows to the colder part of the heat exchanger, the particles try to deposit on the tubes' walls.Evidently, the hot zone is continuously eroded, and the deposited corrosion products clog the cold zone. By adding certain inhibitors to the liquid alloy to create protective layers that stop high temperature corrosion, one can extend the lifespan of heat exchangers[7], [8].

Passivity

There are several ordinarily reactive metals and alloys that, when exposed to certain environmental factors, lose their chemical reactivity and are exceedingly inert. Chromium, iron, nickel, titanium, and a number of their alloys exhibit this behaviour known as passivity. This passive behaviour is the result of a thin, very adhesive oxide coating developing on the metal surface. To prevent additional corrosion, this layer acts as a barrier of protection. Stainless steels are highly corrosion-resistant in a variety of atmospheric conditions as a result of passivation. They have an iron content of at least 11% chromium, which prevents rust from forming by acting as a solidsolution alloying element in iron. Instead, a protective surface film develops in oxidising environments. We should be aware that stainless steels are not necessarily "stainless" because they can corrode in particular environments.

The current density first rises when the voltage of a metal electrode is increased. When the current density reaches a critical point, it may suddenly drop to a considerably lower value and hold still for a brief period of potential growth. Passivation is the usual name for this syndrome. The essential current density for chromium is around 200 A/m2 right before passivation. After passivation, the current is less than 0.1 A/m2. Clearly, the current density has decreased significantly. The simultaneous development of a thin oxide layer on the metal surface and this significant decrease in current density are related. An important method of preventing corrosion is provided by this occurrence of passivation. Aluminium also passivates, which makes it very corrosion resistant in a variety of situations. The protective film often heals quite quickly if it is injured. A passivated material, however, may revert to an active state if the environment changes, for as when the concentration of an active corrosive species changes. A preexisting passive film may sustain further degradation as a result.

Environmental Effects

The corrosion properties of the materials in contact with the corrosion environment can be impacted by factors in the environment, such as fluid velocity, temperature, and composition. It has been found that, in the majority of cases, increased fluid velocity accelerates corrosion because of erosive effects. The majority of chemical processes in corrosion cases speed up as the temperature rises. In many instances, a higher concentration of the corrosive species—for example, H+ ions in acids—produces a more faster rate of corrosion.

Raising the corrosive concentration, however, may cause an active-to-passive shift in materials that may passivate, leading to a significant decrease in corrosion.

Metals that are plastically malleable or that can be cold worked are typically employed to make them stronger. While deformation processes are used to create the head and point of a nail, a coldworked metal is more prone to corrosion than the same material in an annealed state. These sites are obviously anodic relative to the shank area. We might observe that when a corrosive environment may be encountered during service, differential cold working on a structure should be taken into account[9], [10].

Specific Forms of Corrosion

Corrosion can be readily categorised based on how it presents itself. Typically, there are eight different types of metallic corrosion: uniform, galvanic, crevice, pitting, intergranular, selective leaching, erosion-corrosion, and stress corrosion. There is also hydrogen

embrittlement. In actuality, hydrogen embrittlement is more of a failure than a corrosion. However, hydrogen created during corrosion reactions frequently results in hydrogen embrittlement.

(i) **Uniform Corrosion**:

This type of electrochemical corrosion happens when the metal's entire surface corrodes to the same extent and when the environment and metal surface are both uniform. Scale or deposits are frequently left behind by this kind of corrosion. In these circumstances, it is simple to estimate the useful life of a given material and unexpected failure need not be feared. By choosing the right materials, consistent corrosion attack can be easily controlled. Such rusting is uncommon in real life. In most cases, uniform corrosion is seen in metals like Zn, Pb, and Al.

(ii) **Crevice Corrosion**:

Between two sections of the same metal piece and as a result of ion or dissolved gas concentration differences in the electrolyte solution, electrochemical corrosion can also happen. Corrosion occurs in the local with the lowest concentration for such a concentration cell. Some excellent instances of this form of corrosion include corrosion that takes place in cracks and fissures, behind dirt or corrosion products, or where the solid solution becomes stagnant and there is localised depletion of dissolved oxygen. Crevice corrosion is the name for corrosion that preferentially develops in these locations. The crevice must be sufficiently wide for penetration and sufficiently narrow for stagnation. We can observe that the breadth is often a few thousandths of an inch.

(iii) **Pitting Corrosion:**

When the metal surface and surroundings are uniform, the metal surface is uniformly corroded, and this type of very localized corrosion attack occurs. The metal surface will develop little pits or holes due to this sort of corrosion assault. They often extend downward in a direction that is almost vertical from the top of a horizontal surface. Pitting corrosion happens for one of the two reasons listed below: A small spot on the surface that is continuously anodic with current flowing from it at a relatively high density is one of the following: (a) localized difference in the composition of the metal surface, or its smoothness; (b) inhomogeneous external environment; (c) insoluble corrosion product; (d) protective films on the metal surface that were not uniformly perfect; (e) crystallographic directions that were not equal in reactivity.

(iv) Inter-granular Corrosion:

For some metals and in some particular situations, this form of corrosion preferentially develops along grain boundaries. This happens when the grain boundaries and the reminder of the alloy exhibit a clear variation in reactivity. Some stainless steels are especially prone to this kind of corrosion.

These alloys become sensitive to inter-granular attack when heated to temperatures between 500 and 800°C for long enough periods of time. The chromium and carbon in the stainless steel react during this sort of heat treatment, forming minute precipitate particles of chromium carbide (Cr23C6). Both the chromium and the carbon must diffuse to the grain boundaries in order for the precipitates to form. As a result, a zone close to the grain border is chromium-depleted. Corrosion is very likely to occur in this grain boundary area. Selective corrosion attack between the grains of metals and alloys may happen because of possible differences established up there when: (a) there is precipitation in the grain boundaries and/or (b) even because of different grain orientation.

(v) Selective Leaching or Corrosion and De-zinfication

When one element or constituent is preferentially eliminated as a result of corrosion processes, this form of corrosion, which is typically found in solid solution alloys, takes place.Brass is de-zincified through selective corrosion, which is the most frequent instance. In this kind of corrosion, the copper becomes a spongy mass with almost no strength once the zinc atoms are dissolved from the solid solution. Since only a porous mass of copper is left in the de-zincified area, the mechanical characteristics of the copper-brass zinc alloy are significantly reduced. Additionally, the substance's color shifts from yellow to red or copper. It is discovered that additional alloy systems that contain Al, Fe, Co, Cr, and other elements that are susceptible to preferred removal may also experience selective leaching.

(vi) Atmospheric Corrosion

On ferrous materials, this sort of corrosion occurs quite frequently. This type of corrosion is mostly caused by rainwater and air humidity, which serve as electrolytes. This type of corrosion is primarily brought on by moisture and electrochemical attack on the exposed metal, which results in the production and disintegration of films. The oxygen-absorption mechanism is obviously followed in this. It has been noted that the film's fissures and breaks allow corrosion cells to develop on newly exposed surfaces.

(vii) Erosion- Corrosion

The combined effects of chemical assault and mechanical abrasion or wear as a result of fluid motion cause this form of corrosion. The impingement of confined gases or the turbulent flow of liquids both result in mechanical abrasion. Typically, all metal alloys are prone to erosion-corrosion to some extent. Because it mechanically eliminates the protective layer that typically forms on the corroding surface, erosion-corrosion speeds up assault. It goes without saying that alloys that passivate by producing a protective surface coating are particularly vulnerable to this type of corrosion. Erosion-corrosion may be severe when the coating is unable to act as a protective barrier constantly and quickly. Localized pitting cells are created by this kind of corrosion action. This kind of corrosion is frequently linked to the creation of cavities in the metal by swiftly moving liquids. This type of corrosion assault can also damage relatively soft metals like copper and lead.

(viii) Stress Corrosion

Stress corrosion is another name for this type of corrosion. When a metal is subjected to both mechanical stress and a corrosive environment, cracking results. This type of corrosion is most common in metal components utilized in corrosive environments that include internal tensions (which may be caused by cold operation or another factor). In fact, when a stress is applied, some materials that are essentially inert in a specific corrosive solution become susceptible to this type of corrosion. In cold-worked metals, a buildup of dislocations near grain boundaries increases the energy in those areas and, under certain conditions, creates anodes in the structure. Failure may eventually happen as a result of tiny cracks that start to form and spread perpendicular to the tension. A few well-known instances of stress corrosion include season cracking in brass, particularly when moisture and ammonia traces are present, and caustic embrittlement of steel when exposed to sodium hydroxide-containing solutions.

In particular settings, particularly at moderate stress levels, the majority of alloys are vulnerable to stress corrosion. Stress corrosion is largely resistant to pure metals. Eliminating tensile stress from the component part or reducing the amount of stress is the most efficient way to control stress corrosion. Reduce the external load or increase the cross-sectional area perpendicular to the applied stress to accomplish this. In addition, any residual thermal strains may be eliminated by a suitable heat treatment.

The stretched area of cold-worked metal is where corrosion occurs. The metal atoms are not in their lowest energy state in the strained region. As a result, the electrode potential in the stressed part of the metal is higher than in the strain-free area. The strained area acting as the anode and the unstrained area working as the cathode give rise to a type of galvanic cell known as a stress cell when corrosive conditions are present. Naturally, corrosion begins at the stressed area due to the cell's electrochemical action.

(ix) Corrosion Fatigue

This kind of failure happens when a chemical attack and cyclic stress are present at the same time. It is now widely accepted that corrosion leads to cracking, whereas fatigue may result in crack propagation. Even under static pressures, a corrosion crack can spread. It is important to remember that the combined effects of corrosion and repeated stresses are much more damaging than any of these two causes operating alone. Corrosion fatigue is another term for the decrease in a material's fatigue strength brought on by the presence of a corrosive media. The alternates slip that occurs at the granular legal level produces very small patches of high strain energy that have a tendency to become anodic in comparison to the surrounding low strain energy regions. The mechanical stress concentration caused by the corrosion fracture will cause the fatigue strength to decrease. In heat exchangers where changing strains are produced by thermal expansion and contraction, the influence of corrosion fatigue is plainly visible. We might argue that the material is in its most vulnerable state when exposed to corrosive environments and fatigue loading.

(x) Fretting: Fretting corrosion is a type of corrosion that develops at the interface of two surfaces of a material when there is a minor slippage. This kind of corrosion typically develops when two closely spaced metal surfaces, such as bolted or riveted joints or press-fit hubs on shafts, are vibrated. The initial stage involves molecular plucking of the surface particles, which oxidise to generate a detritus. This debris resembles red rust when it comes to steel. Fretting corrosion is influenced by metallurgical parameters, load, temperature, humidity, and other variables. By adding compressive tensions, heat treatment, and preventing relative motion between the two surfaces, one can decrease the impacts of this type of corrosion. Corrosion of the frets decreases at high humidities and increases in the presence of oxygen. It decreases with the decrease in temperature. It is found to be more in soft materials than that in hard materials.

(xi) Hydrogen Embrittlement: When atomic hydrogen (H) permeates several metal alloys, in particular some steels, a considerable decrease in ductility and tensile strength is seen. Common names for this phenomenon include hydrogen embrittlement, hydrogen-induced cracking, and hydrogen stress cracking. In reaction to applied or residual tensile stresses, hydrogen embrittlement is a form of failure, according to this definition. In brittle fracture, cracks quickly spread and enlarge, causing catastrophic failure. It's interesting to note that hydrogen diffuses internally through the crystal lattice in its atomic form (H) as opposed to its molecular form (H2), and concentrations as low as a few parts per million can cause breaking. We should remark that although intergranular fracture is seen in some alloy systems, hydrogen-induced cracks are typically transgranular. Numerous methods, the majority of which are based on the interference of dislocation motion by the dissolved hydrogen, have been proposed to explain hydrogen embrittlement.

Stress corrosion and hydrogen embrittlement are pretty similar. On the basis of how these two phenomena interact with applied electric currents, one can differentiate between the two phenomena. While cathodic protection may induce hydrogen embrittlement to begin or intensify, it may also lessen or stop stress corrosion. There must be a supply of hydrogen and the potential for the production of its atomic species in order for hydrogen embrittlement to take place. These circumstances include pickling (the process of removing surface oxide

scale from steel by dipping it in a vat of hot, diluted sulfuric or hydrochloric acid), electroplating, and the presence of hydrogen-bearing atmospheres (including water vapour) at elevated temperatures, such as during welding and heat treatments. Additionally, the presence of toxins like sulphur, or H2S, and arsenic compounds speeds up the embrittlement of hydrogen. These compounds lengthen the period that atomic hydrogen spends on the metal surface by delaying the production of molecular hydrogen. The most aggressive poison is probably hydrogen sulphide, which is present in petroleum fluids, natural gas, oil-well brines, and geothermal fluids. High-strength steels have been discovered to be vulnerable to hydrogen embrittlement, and increasing the material's strength tends to make it more susceptible. It has been discovered that martensitic steels are particularly prone to this kind of failure. Steels that are bainitic, ferritic, or spheroiditic are discovered to be more robust. Due to their naturally high ductilities, FCC alloys (austenitic stainless steels and alloys of copper, aluminium, and nickel) are found to be relatively resistant to hydrogen embrittlement. The propensity of certain alloys to embrittlement may increase as a result of strain hardening. Some of the frequently employed methods include lowering the alloy's tensile strength through a heat treatment, eliminating the hydrogen source, "baking" the alloy at a high temperature to drive out any dissolved hydrogen, and switching the alloy out for one that is more resistant to hydrogen embrittlement.

Corrosion Prevention and Control

Once we have characterized the corrosive environment, choosing the right materials may be the most popular and simple method of preventing corrosion. Standard corrosion references are useful in this regard. Prior to using a material that offers the best corrosion resistance, one must first consider its economic viability. For instance, noble metals can only be used in a very small number of applications, such as ornaments and sensitive scientific instruments. The materials would need to be completely uniform, with no compositional or structural heterogeneities, and the atmosphere would need to be uniform as well in order to manage corrosion.

The following techniques are frequently employed for corrosion control and prevention:

- (i) Adding alloys and high-purity metals
- (ii) Effective corrosion-prevention design
- (iii) Adequately altering corrosive environments (iv) Using protective coatings

Utilising inhibitors (v) (vi) Protection from cathodes (i) Adding High-Purity Metal and Alloys: By eliminating galvanic couples and keeping designs to one metal, one can increase the corrosion resistance of a particular metal. This isn't always possible, though. In particular situations, one may prevent the cells by choosing suitable electrically insulating metals of differing compositions or by alloy addition. The majority of metals can be alloyed with the proper alloying elements to boost their corrosion resistance. By raising the energy level of the solution, lowering the driving emf in the galvanic cell, using protective coatings, and restricting the mobility of the corrosive ions, alloying may boost corrosion resistance. However, alloying could be useful in the following ways:

(i) To prevent carbon precipitation during heating.

(ii) Making high chromium content steels. Notably, chromium corrodes less quickly. To create steels with powerful carbide formers (iii). These elements include tantalum and titanium. It's interesting that these substances prevent carbon from precipitating at grain boundaries. These techniques lessen the corrosion between metal grains. This method is primarily applied to stainless steel, which needs to be created through welding.

(iii) Design Against Corrosion: To prevent the formation of a galvanic pair, it is possible to eliminate direct physical contact between different metals. Additionally, in the event of a shutdown, the design must to permit complete drainage as well as simple washing. Since it has been shown that dissolved oxygen may increase how corrosive various solutions are, any design should, if at all possible, account for the exclusion of air. One can make sure of the following things to prevent:

(i) Avoid contracts involving different metals as much as you can. If it is necessary to make contact with different metals, care should be taken to ensure that the metal used to create the anode does not have a tiny surface area in comparison to the cathode.

(ii) Cathodic protection is required.

(iii) Sharp corners and recessed areas must be avoided.

(iv) Avoiding overconcentration by using the right manufacturing.

(v) Airtight joints are necessary to avoid liquid retention.

(vi) Surfaces must be free of foreign materials, such as dust, grime, and soot, and they must be clean.

(vii) Corrosion-resistant materials must be used whenever practicable.

(viii) We might make sure the two distinct metals are as near together as feasible.

(iii) Modification of Corrosive Environment: It has been discovered that, if at all possible, altering the nature of the environment can have a major impact on corrosion. If materials are employed in less corrosive conditions, significant cost savings can be realized. In most cases, lowering fluid temperature and/or velocity aids in slowing the rate of corrosion. A good outcome may result from repeatedly raising or lowering the concentration of a certain species in the solution, for example, the metal may passivate. The following are some possible changes to the environment:

(i) Reducing the temperature, pressure, concentration, velocity, etc.

(ii) The chemical composition of the environment can be changed by adjusting humidity, oxygen content, oxidizing agents, and solid impurities. It has been discovered that a pure and dry environment around the structure reduces corrosion.

(iii) By introducing inhibitors, or those compounds that lessen the environment's ability to corrode, into it in little amounts. For instance, alkaline neutralizers are employed to counteract the acidic nature of corrosive situations in order to prevent the corrosive effect of the environment. Vacuum and inert gases are also found to be helpful in preventing the corrosion of ferrous metals and alloys at high temperatures.

Naturally, the particular inhibitor is dependent on the alloy and the corrosive environment.

(iv) Utilizing Protective Surface Coatings Many surfaces have physical barriers applied to them in the form of films and coatings. Many different metallic and non-metallic coating materials are available. It is crucial that the coating maintain a high level of surface adhesion while in use and have adequate corrosion resistance, which unquestionably calls for some pre-application surface treatment.

In a number of situations, the coating must be nearly impervious to corrosion and resistant to mechanical damage that would otherwise expose the naked metal to the environment. In general, coatings for metals are made of all three material types: metals, ceramics, and polymers.

CONCLUSION

The durability and dependability of materials and structures are severely hampered by oxidation and corrosion. For the creation of successful prevention and mitigation strategies, it is essential to comprehend these processes. When a substance combines with oxygen in the presence of heat or another catalyst, oxidation takes place, resulting in the creation of oxides. This process is frequent in metals and alloys, where it may lead to the loss of functionality and deterioration of mechanical qualities. Contrarily, corrosion is the term for the degradation of materials caused by electrochemical reactions with their surroundings, which frequently involve the presence of moisture or corrosive elements. Numerous factors affect how quickly and severely corrosion and oxidation occur. Temperature is important since these activities are frequently accelerated by greater temperatures. The integrity and performance of materials can be dramatically impacted by the destructive processes of oxidation and corrosion. This abstract examines the mechanics of oxidation and corrosion as well as the causes, risk factors, and mitigation strategies for both. The term "oxidation" describes the reaction that takes place when an object comes into contact with oxygen and produces oxide molecules. Contrarily, corrosion refers to the degradation of materials brought on by chemical or electrochemical interactions with the environment. The mechanical, electrical, and chemical properties of materials can deteriorate as a result of either process. The rate of corrosion can also be considerably impacted by humidity and the presence of corrosive elements like acids or salts. The type and severity of corrosion can also be influenced by the environment's pH.

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CHAPTER 3

FEATURES OF THERMAL AND OPTICAL PROPERTIES OF MATERIALS

Dr. Krishnappa Venkatesharaju, Assistant Professor, Department of Environmental Science And Engineering, Presidency University, Bangalore, India, Email Id-venkateshraju.k@presidencyuniversity.in

ABSTRACT

numerous scientific, technological, and industrial applications heavily rely on the thermal and optical properties of materials. Designing and creating materials with specialized thermal and optical behavior requires an understanding of and characterization of these features. The thermal and optical properties of materials are briefly discussed in this abstract, along with their significance and important ideas and measurement methods. Thermal properties include characteristics that affect how heat is transferred and stored in materials, such as thermal conductivity, specific heat capacity, and thermal expansion. Thermal management systems, energy storage systems, and thermal barrier coatings all benefit from these characteristics in terms of effectiveness and performance. Contrarily, optical characteristics refer to phenomena like absorption, reflection, transmission, and refractive index that are connected to a material's interaction with light. These characteristics have effects on technology related to optics, photonics, solar energy, and displays.

KEYWORDS

Energy, Expansion, Heat, Materials, Thermal, Temperature.

INTRODUCTION

It is crucial to research how a material responds to heat application. A solid's temperature and size grow as a result of absorbing heat-based energy. If there is a temperature gradient, the specimen's absorbed heat energy may be transferred to cooler areas, where it may eventually melt. There are a few extremely significant properties of solids that are frequently crucial in practical and engineering applications, including heat capacity, thermal expansion, and thermal conductivities comprehending the significant differences in thermal behavior among the many classes of solid materials is made easier by comprehending the theory of lattice vibrations, which includes the study of phonons and the band theory of electrons. A succinct description of thermal characteristics is given in this section.

Heat Capacity

The rise in temperature that occurs when a solid material is heated indicates that some energy has been absorbed. A solid material's heat capacity is a parameter that reveals how well it can absorb heat from its environment; it quantifies the amount of energy needed to reach a given temperature rise.

Depending on the conditions surrounding the transport of heat, there are two techniques to estimate a body's heat capacity. Both the heat capacity at constant volume (Cv = (Q/T)v) and the heat capacity at constant external pressure (Cp) are examples of this. Even though the difference between Cp and Cv is always higher, it is quite small for the majority of solid materials at ambient temperature and below. Since the former can be calculated right away using the system's energy, the heat capacity at constant volume (Cv) is more useful than the heat capacity at constant pressure (Cp). The mass of the body, its chemical makeup, its thermodynamic state, and the type of heat transmission technique used all affect the heat capacity[1], [2].

Vibrational Heat Capacity

Most solids assimilate thermal energy primarily through a rise in atomic vibrational energy. It is well known that solid-state atoms vibrate continuously at extremely high frequencies and small amplitudes. Despite the fact that atoms' vibrations are not completely independent of one another, the atomic connection between nearby atoms causes their vibrations to be coupled. Travelling lattice waves are created as a result of the coordination of the atoms' vibrations within a solid. These lattice waves, which have small wavelengths and extremely high frequencies and move through crystal at the speed of sound, can be conceptualized as elastic waves or just as sound waves. These elastic waves, which have a variety of distributions and frequencies, make up the series of elastic waves that make up the vibrational thermal energy for a material. A single quantum of vibrational energy is known as a phonon, and when only particular energy values are permitted, the energy is said to be quantized. The lowest unit of energy of a vibration related to a sound wave, or phonon, is obviously a quantum of sound. A phonon is comparable to a photon or a quantum of light. On occasion, phonons are used to describe the lattice vibrational waves themselves.

The idea of a gas of phonons may be utilized to explain the heat capacity, which makes the concept of phonon particularly helpful in defining the properties of solids. Due to collisions with impurity atoms and among themselves via the phonon-phonon interaction, phonons in a solid have a mean free path. In insulators, phonons carry heat, and the mean free pathways of the phonons control how much thermal conductivity is present. In some substances, the electron-phonon interaction is crucial for producing an attractive connection between electron pair that results in superconductivity. A phonon is a bundle of sound waves that has the energy and momentum of a massless particle, where h is Planck's constant, is the vibration's frequency, and is its wavelength. V is the proper sound velocity, and the product of equals V. We may observe that because h and h are so small, this particle-like characteristic only matters at the atomic level. For common occurrences, it is unimportant[3], [4].

DISCUSSION

Other Heat Capacity Contributions

The total heat capacity of a solid may also be increased by additional energy-absorbing processes. However, in the majority of cases, these are negligible in comparison to the phonon contribution's vibrational magnitude. In that electrons absorb energy by increasing their kinetic energy, there is an electronic contribution.

However, only free electrons—those that have been stimulated from filled to empty states above the Fermi energy—are able to do this. Only electrons in states close to the Fermi energy in metals are capable of making these transitions, and even then, they make up a very small portion of all electrons.

We should point out that in insulating and semiconducting materials, excitations of electrons occur in even lower proportions. Obviously, unless at temperatures close to zero degrees Celsius, this electrical contribution is usually negligible.

Additionally, other energy-absorptive processes in some materials take place at particular temperatures, such as the randomization of electron spins in a ferromagnetic material when it approaches its curie temperature TC. The heat capacity vs. temperature curve exhibits a significant spike at the temperature of this transformation. We now assess Cv theoretically and contrast the resulting value with the outcomes of experiments. Let's take a look at a N-atom crystal that is held together by a periodic arrangement. We can assume that these atoms are free to vibrate around their equilibrium sites while being constrained by forces that roughly follow Hooke's rule.

Thermal Expansion

Specific heat and melting point of solids are connected to the thermal coefficient of expansion of certain materials. According to empirical evidence, the total volume change of an element when it is heated from absolute zero to melting point is essentially constant. Metals having higher melting points will undoubtedly have lower coefficients of expansion. As a result, the expansion of metals with deep potential wells or energy curves that are more symmetric about the central line that passes through the minimum energy point will be less as the temperature rises. Such metals will, of course, have higher bond energies and, as a result, melt at higher temperatures. We observe that metals like tin have a low melting point and expand quickly as the temperature rises. A metal with a high M.P., such as platinum, has a low rate of thermal expansion. Except for silica (SiO2) and zirconia (ZrO2), the majority of commercial oxides are found to have consistent thermal expansion. These oxides exhibit erratic expansion as a result of polymorphism changes. Because they soften at lower temperatures than metals, organic polymers like plastics and rubber have thermal coefficients of expansion that are several times larger. As a result, it is challenging to manufacture objects made of these materials to very tight tolerances (0.025 mm). Metals often have such limits. Because of this, applications for synthetic resins used as cements are somewhat limited. The thermal expansivity of plastics can be decreased by adding filler components with lower expansivity, like glass fibre, asbestos, and inorganic powders like alumina. In fabric reinforced plastics, the filler and matrix materials' intermediate expansion coefficient values can be obtained. In such materials, the expansion occurs in the plane of the reinforcement. It is feasible to create some plastics, such as phenolic and polysters, with expansion coefficients that are close to those of metals through correct compounding with filters[5], [6].

Metals

For certain common metals, alpha-ranges from around $5*10^{-6}$ to $25*10^{-6}$ /°C. A high level of dimensional stability with temperature fluctuations is necessary for several technical applications. As a result, a series of Fe-Ni and Fe-Ni-Co alloys with $1*10^{-6}$ /°C have been developed. When linked to Pyrex and exposed to temperature changes, one finds that thermal stresses and potential fracture at the junction are avoided. One such alloy, called Kovar has been created to have expansion characteristics similar to those of Boro-silicates (or Pyrex) glass. Both Invar and Super-invar are additional low expansion alloys.

Ceramic

There are numerous ceramic materials that include relatively strong interatomic bonding forces. This is evident in the relatively modest levels, which typically fall between 0.5 to 15 10^{-6} /°C. Isotropic ceramics include those with cubic crystal formations and non-crystalline ceramics. If not, it is anisotropic; in practice, some ceramic materials expand in some crystallographic orientations while contracting in others when heated depends on the composition for inorganic glass. Has a low value of $0.4*10^{-6}$ /°C for fused silica (high purity SiO2 glass). This can be explained by a low atomic packing density, which results in very minor macroscopic dimensions changes caused by interatomic expansion. Ceramic materials must have relatively small and isotropic coefficients of thermal expansion in order to withstand temperature changes. In any other case, thermal shock-induced non-uniform dimensional changes may cause these brittle materials to shatter.

Polymers

Some polymeric materials undergo very significant thermal expansions when heated, as seen by values that fall between $50*10^{-6}$ and $400*10^{-6}$ /°C. Due to the weak secondary intramolecular bonds and low cross-linking, linear and branched polymers exhibit the highest -values. With more crosslinking, the expansion coefficient's magnitude decreases. The

thermosetting network polymers, such as phenol-formaldehyde, where the linking is almost totally covalent, have the lowest values[7], [8].

Superconductors

The electronic conduction of superconductors decreases below their critical temperature, TC. At sufficiently low temperatures, the thermal conductivity is entirely caused by lattice waves and resembles the thermal conductivity of an insulating material. Fig. 1 illustrates the relationship between lead's thermal conductivity and temperature; Kn represents the thermal conductivity in the material's normal state and Ks represents the superconducting state.

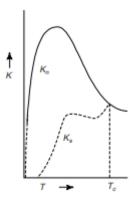


Fig. 1 illustrates temperature dependence of thermal conductivity of lead (newagepublishers.com).

Refractories

Refractories are substances that can tolerate the effects of heat without significantly deforming or softening. Naturally, the temperature at which the refractory material softens is used to gauge this feature. Refractories' softening or fusion temperatures are often measured while they are under load. High temperatures can be withstood by refractories. Most refractories that are commercially accessible are complex solids. Typically, Si, Al, Mg, Ca, and Zr are used to make them. There may be additional elements as contaminants. The modern industries mostly rely on crystalline oxides, carbides, borides, and sulphides in addition to oxide refractories. Ceramics are the end product of combining these elements with metals.We will now examine a variety of refractory materials:

Ceramics: Refractory ceramics stand out for their ability to tolerate high temperatures without melting or decomposing as well as their ability to remain inert and unreactive in harsh settings. Additionally, ceramics' capacity for insulation is frequently a significant role. Although refractory materials are sold in a number of forms, bricks are by far the most popular. Furnace linings for glass manufacturing, metallurgical heat treatment, and power generation are a few common uses for these refractories.

Fireclay Refractories

High quality fireclays, alumina and silica mixes that typically comprise 25 and 45 Wt% alumina are the main components of these. The greatest temperature that can be reached over this composition range without the formation of a liquid phase is 1587°C. Mullite and silica (cristobalite) are the equilibrium phases that exist below this temperature. During refractory service use, a tiny amount of a liquid phase might be acceptable without affecting mechanical integrity.

Fireclay bricks are primarily employed in the construction of furnaces, where they are utilized to contain hot environments and thermally insulate structural parts from extreme temperatures.

Silica Refractories

Silica is the main ingredient in them. These materials can withstand high temperatures and are frequently used in the arched ceilings of furnaces used to make steel and glass. For these applications, temperatures as high as 1650 °C may be reached. A tiny piece of this block will truly be liquid under these circumstances. These refractory materials can also withstand acid slags, also known as silica-rich slags, which are typically utilized as containment vessels for them.

Basic Refractories

The term "basic" refers to refractories that are high in periclase, commonly known as magnesia (MgO), and they may also contain Ca, Cr, and Fe compounds. Their performance at high temperatures suffers when silica is present. These refractories are particularly resistant to assault from slags with high Mgo and CaO contents. These are heavily utilised in various open hearth furnaces used for manufacturing steel[9], [10].

Special Refractories

Other ceramic materials are available, such as relatively high-purity oxide compounds utilised in specialised refractory applications. It is possible to synthesise many of these oxides with very low porosity. Alumina, silica, magnesia, beryllia (BeO), zirconia (ZrO2), and mullite (3Al2O3-2SiO2) are among the oxides that fall under this category. Other materials besides carbon and graphite include carbide compounds. Although carbon and graphite are extremely refractory, they only have a few applications since they can oxidise at temperatures higher than roughly 800°C. Silicon carbide (SiC) has been utilised for crucible material, electrical resistance heating elements, and internal furnace components. These specialty refractories come at a fair price.

Thermal Stresses

These are the tensions that temperature fluctuations cause in a material body. Fracture or undesired plastic deformation may result from these forces. Let's suppose a homogeneous, isotropic solid rod that is heated or cooled uniformly, i.e., no temperature gradients are imposed, in order to comprehend the causes and nature of thermal stresses. The rod won't experience any tension during free expansion or contraction. Thermal stresses will be introduced if the rod's axial motion is restricted by rigid end supports, though.

Thermal Fatigue

Alternate thermal gradients and correspondingly shifting stresses are produced when the temperature of a specimen's body is changed. The specimen becomes thermally fatigued as a result of these shifting tensions. Temperature changes frequently result in high magnitude strains that cause plastic deformation. Low cycle thermal fatigue causes the material to fail under these circumstances. The negative effects of temperature on mechanical strength further speed up the material's demise.

Thermal Shock

Thermal shock is the result of abrupt and extreme temperature fluctuations that generate considerable stress. Since cooling places tensile tensions on the surface, it produces thermal shocks that are significantly more harmful than those produced by heating. Any material's surface is weaker than its interior surface for a variety of reasons. Plastic deformation can be used to reduce thermally generated stresses in ductile metals and polymers. The likelihood of brittle fracture from these loads is increased by the non-ductility of the majority of ceramics. Material that is brittle is weak under tension.

Melting Point

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Applications of Optical Phenomena

(i) Luminescence: There are substances that are capable of absorbing energy and reemitting visible light. This type of light emission cannot be explained just by the temperature of the emitting body. This occurrence is known as luminescence. Different types of luminescence are frequently distinguished based on the energy source that stimulates the emission. Chemiluminescence is the term for an emission of light that is caused by a chemical reaction, such as the gradual oxidation of phosphorus at room temperature. Bioluminescence is the term used to describe an emission when the luminous chemical reaction takes place in a living system, such as the glow of the firefly. In some instances, some of the chemical reaction's energy is transformed into light. There are also certain kinds of luminescence that begin when energy enters the body from the outside. Cathodoluminescence, radioluminescence, or roentgenoluminescence are terms used to describe luminescences that by electron bombardment, x-rays, or gamma rays, are excited respectively. Photoluminescence is used to describe luminescences that are excited by ultraviolet, visible, or infrared radiation, and electroluminescence is used to describe luminescences that are excited by the application of an electric field. Similar names can be created to describe luminescence excited by various agents by prefixing the word luminescence with an appropriate suffix. The division of luminescence phenomena into various groups is purely for practical reasons and makes no real distinctions. Additionally, luminescence is categorised based on how much time passes between absorption and reemission occurrences. Reemission is referred to as fluorescence or phosphorescence depending on how long it lasts. If it lasts longer than one second, it is referred to as reemission. A variety of substances, including certain sulphides, oxides, tungstates, and a few organic substances, can be induced to fluoresce or phosphoresce. These phenomena are not typically seen in pure materials, thus impurities must be supplied at specific concentrations to bring them about.

The use of luminescence in commerce is widespread. Fluorescent lights have a glass housing that is inside covered in tungsten states or silicates that have been specifically produced. UV light is produced within the tube from a mercury glow discharge, which causes the coating to fluoresce and radiate white light. The result of luminescence is the image that can be seen on a television screen. An electron beam inside the picture tube swiftly passes the interior of the screen while being coated with a substance that fluoresces. Using the fact that some phosphorus emits visible light or glows when added to an otherwise invisible radiation beam, one can also detect x-rays and gamma-rays.

(ii) **Photoconductivity**: In semiconductors and insulators, photoconductivity is the increase in electrical conductivity brought on by the stimulation of extra free charges carried by sufficiently bright light. A photoconductor can be used for a number of light and particle detecting applications, as well as a light-controlled switch, and is essentially a radiationcontrolled electrical resistance. Television cameras (vidicons), conventional silver halide emulsion photography, and the enormous area of electro-photographic reproduction are other significant applications in which photoconductivity plays a key role. The processes associated with photoconductivity have also contributed significantly to our understanding of electrical behaviour and crystallographic flaws in a wide range of materials. Solar cells, which also use semiconductors, can convert sunlight directly into electrical energy. In a way, these gadgets work in the opposite direction from LEDs. When photo-excited electrons and holes are pulled away from the junction in opposite directions and join an external current, a P-N junction is utilized.

(iii) **Laser**: An acronym for light amplification by stimulated emission of radiation, "laser" stands for this technology. It is a source of a powerful, very pure beam of light. Atoms, molecules in gases, liquids, solids, and flames, as well as ions, can all be subject to laser action. The laser source's emission ranges from the radio frequency to the ultraviolet spectrum, with output powers ranging from a few mW to MW. While some lasers produce waves continuously, others do so in pulses.

(iv) **Optical Fibers in Communication:** An optical fiber is a cylinder-shaped, extremely thin, flexible media. A fiber is divided into three main parts: the core, the cladding, and the jacket. The term "core" refers to the innermost glass or plastic component. The cladding is the glass or plastic covering that surrounds the core. The cladding's optical characteristics are distinct from the jacket's. It shields the structure from moisture, abrasion, mechanical shocks, and other environmental risks and is constructed of plastic or polymer and other components.

Atomic and Electronic Interactions

Atoms, ions, and/or electrons interact with electromagnetic radiation to produce optical phenomena in solid materials. Electronic polarisation and electron energy transitions are two of the most significant of these interactions A rapidly varying electric field, E, is one element of an electromagnetic wave. With each change in the direction of the electric field component, this electric field interacts with the electron cloud surrounding each atom in its path in a way that causes electronic polarisation, or shifts the electron cloud with respect to the atom's nucleus, for the visible range of frequencies. This electrical polarisation has two main effects: (i) some of the radiation energy may be absorbed, and (ii) light waves travel through the medium at a slower speed. Refraction is the second consequence that shows up. Electron transitions from one energy level to another may occur during the electromagnetic radiation's absorption and emission. Let's have a look at an isolated atom whose electron energy curve is shown in Fig.2. By absorbing a photon of energy, an electron can be stimulated from the occupied state E1 to the higher-lying, unoccupied state E2.

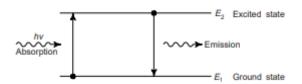


Fig. 2 Shows atomic transitions(newagepublishers.com).

Optical Properties of Metals

Because electrons are excited into unoccupied energy states above the Fermi energy by incident radiation with frequencies within the range of possibilities (Fig. 3) metals are opaque. As a result, incident radiation is absorbed according to Eq. (6). Only metallic films thinner than 0.1 m are able to transmit visible light because the total amount of absorption within the metal is contained within a very thin outside layer, which is typically less than 0.1 m. Due to the continually present empty electron states, which allow for electron transitions as seen in Fig. 3, a metal can absorb all visible light frequencies. In reality, metals are opaque to all electromagnetic radiations at low frequencies, including radio waves, infrared, visible light, and ultraviolet (UV) radiation that is about in the middle of the frequency spectrum. Metals, however, are transparent to high-frequency radiations like X- and rays. The majority

of the radiation that is absorbed by metal surfaces is reemitted as visible light with the same wavelength, which is visible as reflected light (Fig.3). The majority of metals have reflectivities that range from 0.90 to 0.95. Heat is released as a small amount of the energy from electron decay.

The observed colour is controlled by the wavelength distribution of the radiation and not absorbed because metals are opaque and highly reflecting. When a metal with a bright silvery appearance is exposed to white light radiations, we observe that the metal is highly reflective across the entire visible spectrum, meaning that the frequency and number of the reemitted photons are roughly the same as those of the incident beam of light. These reflected actions are displayed by A1 and Ag. Because some of the energy associated with light photons with short wavelengths is not reemitted as visible light, copper and gold, respectively, appear redorange and yellow.

Absorption: Non-metallic substances may be transparent to visible light or opaque to it. They frequently appear colourful if they are transparent. In essence, two mechanisms in these materials absorb light radiations, and each of these mechanisms has an impact on how well these non-metals transmit light. The electrical polarisation of these mechanisms is one of them. This mechanism only plays a significant role when light frequencies are close to the relaxation frequency of the constituent atoms. Transitions between valence band and conduction band electrons make up the second mechanism. The material's electron energy band configuration affects this action. A photon of light may be absorbed by the excitation or promotion of an electron from the nearly full valence band into an empty state within the conduction band across the band gap; this results in the creation of a free electron in the conduction band and a hole in the valence band.

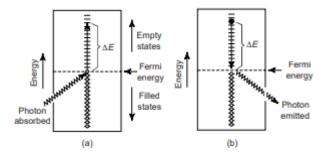


Fig. 3 shows mechanism of photon absorption for metallic materials (newagepublishers.com).

Several dielectric materials that are intrinsically transparent may be made translucent or even opaque because of interior reflection and refraction. As a result of multiple scattering events, a transmitted light beam is deflected in direction and appears diffuse. When the scattering is so extensive that virtually none of the incident beam is transmitted, undeflected, to the back surface, opacity results.

There are several different sources which may cause this internal scattering. Normally, polycrystalline specimens in which the index of refraction (n) is anisotropic appear translucent. A diversion in the incident beam takes place due to reflection and refraction occuring at grain boundaries.

This results from a small difference in the index of refraction between adjacent grains which do not have the same crystallographic orientation. Scattering of light also takes place in twophase materials. In these materials one phase is finely dispersed within the other. When there is a difference in the refractive index for the two phases, the beam dispersion occurs across phase boundaries and greater this difference, the more efficient is scattering. Many ceramic pieces, as a consequence of fabrication or processing contain some residual porosity in the form of finely dispersed pores. These pores also scatter light radiation effectively. The degree of translucency is influenced primarily by the extent of crystallinity for intrinsic polymers (without additives and impurities). As a result of different indices of refraction, some scattering of visible light occurs at the boundaries between crystalline and amorphous regions. This degree of scattering for highly crystalline specimens is extensive and this leads to translucency, and, in some cases, even opacity. We may note that highly amorphous polymers are completely transparent.

CONCLUSION

Numerous technological developments and applications depend on the thermal and optical properties of materials. The capacity to regulate and improve these characteristics enables the creation of materials that satisfy particular specifications in a variety of disciplines. For efficient heat management in a variety of systems, such as electronics, aircraft components, and thermal energy storage, it is essential to understand thermal characteristics. It is possible to increase heat transfer efficiency, lower thermal stress, and boost system performance by developing materials with high thermal conductivity or low thermal expansion. The integrity and performance of materials can be dramatically impacted by the destructive processes of oxidation and corrosion. This abstract examines the mechanics of oxidation and corrosion as well as the causes, risk factors, and mitigation strategies for both. The term "oxidation" describes the reaction that takes place when an object comes into contact with oxygen and produces oxide molecules. Contrarily, corrosion refers to the degradation of materials brought on by chemical or electrochemical interactions with the environment. The mechanical, electrical, and chemical properties of materials can deteriorate as a result of either process.For the development of objects like lenses, screens, and solar cells, optical qualities are essential. It is possible to alter light in ways that permit effective energy conversion, imaging, and communication by creating materials with desired absorption, reflection, and transmission properties.

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CHAPTER 4

ELECTRICAL AND MAGNETIC PROPERTIES OF MATERIALS

Ms. Meenakshi Jhanwar, Assistant Professor, Department of Environmental Science, Presidency University, Bangalore, India, Email Id-meenakshi@presidencyuniversity.in

ABSTRACT

Scientific research and a wide range of technological applications depend heavily on the electrical and magnetic characteristics of materials. For the creation of cutting-edge magnetic materials, power systems, and electronic gadgets, understanding these qualities is crucial. In this study, we look into the underlying theories that underlie the electrical and magnetic properties of various materials. We investigate the connection between resistivity, electrical conductivity, and the inherent characteristics of materials. In addition, we study phenomena like diamagnetism, para-magnetism, and ferromagnetism as well as the magnetic behavior of materials. We learn more about how materials behave when exposed to electric and magnetic fields using experimental methods and theoretical models. The findings lay a foundation for additional improvements in electrical and magnetic technology as well as for our understanding of material science as a whole. From electronic devices and power systems to magnetic storage and sensing technologies, the electrical and magnetic properties of materials are crucial in a wide range of technological applications. This abstract gives a general review of the electrical and magnetic properties of materials, emphasizing the underlying concepts, methods of measurement, and relevance to contemporary technologies. The ability of a substance to conduct, resist, store, or produce electrical charges or currents is referred to as its electrical characteristics. The behavior of electrons inside the atomic or molecular structure of the material affects these characteristics. Conductivity, resistivity, dielectric constant, and electrical breakdown strength are important electrical qualities.

KEYWORDS

Conductivity, Dielectric, Electrical, Electrons, Insulators, Materials.

INTRODUCTION

The electrical and magnetic behavior of things is controlled by the electrons in the atoms' outermost shell. The emergence of more practical solid state devices has been spurred by recent advances in the study of the electrical structure of substances. This chapter's main goal is to examine materials' electrical and magnetic properties. Over 27 orders of magnitude, the electrical conductivities of solid materials display an astounding variety; it's likely that no other physical parameter is subject to such a wide range of variation. In actuality, one approach to categories solid materials is based on how easily they conduct an electric current. Materials can be categorized using this system into three general groups: Conductors, Semiconductors, and Insulators are listed in order. The conductivity of metals and their alloys is good. The best electrical conductors are copper, silver, and gold, followed by aluminum, iron, and nickel. This category also includes several semimetals, such as graphite.

According to the free electron theory, a substance is often a metal and a good conductor of electricity when the outer orbit of an atom contains less than half of the maximum 8 electrons. Conductivities in metals are on the order of 10^{-7} m. A conductor's electrical resistivity can range from 10^{-9} to 10^{-4} (m).At zero degrees Celsius, semiconductors function as insulators, but when the temperature increases, a noticeable increase in electrical conductivity is seen. The electrical conductivity of a semiconductor is intermediate between that of a conductor and an insulator at room temperature. The electrical conductivity of semiconductors ranges from around 105 to 10-7 (-m)-1, whereas the electrical conductivity of

good conductors is on the scale of 107 (- m)-1, and the electrical conductivity of good insulators is at least 10-15 (- m)-1. Semiconductors serve as the building blocks for many different electronic devices. The two most frequently used common semiconductors are germanium and silicon. Free electron theory states that a substance has both metal and non-metal properties and typically has semiconducting features when the outer orbit of an atom contains precisely one-half the maximum eight electrons. It is important to remember that a semiconductor's electrical resistivity often depends heavily on temperature. Additionally, materials with conductivities as low as 10-10 to 10-20 (-m)-1 exist. Electrical insulators are what these are. Among the insulators, there are materials like bakelite, mica, PVC, rubber, and PVC[1], [2].

Electronic and Ionic Conduction

As we've seen, electrically charged particles move as a result of the pressures exerted on them by an externally applied field, creating an electric current. Negatively charged particles are accelerated in the direction opposite to the electric field direction, while positively charged particles are accelerated in the direction of the electric field. Electronic conduction is the process by which a current develops within the majority of solid materials as a result of the movement of electrons. Additionally, it is conceivable for ionic materials to have a net motion of charged ions that results in an electric current; this is known as ionic conduction.

Band structure in solids

A solid can be imagined as being made up of many, say N, originally separated atoms that are then brought together and chemically bound to form the ordered atomic arrangement displayed by the crystalline substance. Each atom is independent of the other atoms at relatively high separation distances since it will have its own set of atomic energy levels and electron configuration. However, as the atoms in a solid get closer together, their electrons are disturbed by the nuclei and electrons of nearby atoms. Due to this influence, each unique atomic state may split into a number of closely spaced electron states in the solid, resulting in the formation of what is known as an electron energy band. Since the outermost electron shells are the first to be disturbed as the atoms merge, they are where the splitting of atomic states begins. The magnitude of this splitting relies on the interatomic spacing. The energy levels are separate within each band, yet the distance between adjacent states is incredibly small. The electron subshells closest to the nucleus may not form bands at the equilibrium separation.Fig. 1 shows a schematic plot of electron energy vs interatomic separation of an aggregate of 12 atoms.

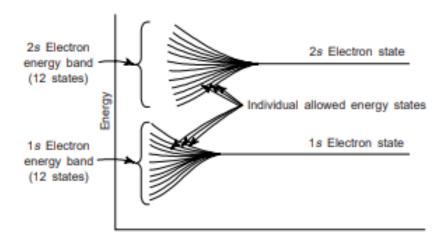


Fig. 1 shows a schematic plot of electron energy vs interatomic separation of an aggregate of 12 atoms.(newagepublishers.com)

DISCUSSION

Conduction in terms of band and atomic bonding models

As we've seen, only the upper energy bands (valence bands) are relevant to solid state theory because electrons at lower energy levels essentially don't participate in atomic interactions. This means that in the presence of an electric field, only electrons with energies larger than the Fermi energy (the Fermi energy is the energy corresponding to the greatest filled electron filled state at 0 K in metal and is denoted by EF) may be acted on and accelerated. These are the so-called free electrons, which take part in the conduction process. A hole, a different type of charge entity, is present in semiconductors and insulators, as was previously explained. Holes take role in electrical conduction and have energies lower than Fermi energy (EF). The discussion that follows shows that the quantity of free electrons and holes directly affects the electrical conductivity. We should also point out that the number of these free electron and hole charge carriers differs in conductors, semiconductors, and insulators[3], [4].

DISCUSSION

Semiconductors and Insulators

As we have shown, semiconductors and insulators do not have any unoccupied states close to the top of the filled valence band. Promoting electrons into empty states at the base of the conduction band and over the energy band gap will allow them to become free. Only by giving an electron the energy difference between these two states—roughly equal to the band gap energy, Egcan this be accomplished. The breadth of the energy band gap and temperature have an impact on how many electrons are thermally stimulated, or heated, and moved into the conduction band. There are very few conduction electrons at a given temperature because the bigger the band gap energy Eg, the smaller the likelihood that a valence electron will be promoted into an energy state within the conduction band. This implies that the electrical conductivity decreases with increasing band gap size at a given temperature. Evidently, the band gap width, which is tiny for semiconductors and comparatively wide for insulators, is what distinguishes semiconductors from insulators. The thermal energy that is available for electron excitation increases as the temperature rises Obviously, this results in a promotion of more electrons into the conduction band and an increase in conductivity.

Now that we have an understanding of atomic bonding models, let's look at the conductivity of insulators and semiconductors. Interatomic bonding in electrically insulating materials is ionic or strongly covalent. The valence electrons are obviously closely connected to or shared with the specific atoms. This indicates that these electrons are incredibly localized and are not at all free to roam the crystal. The bonding is covalent (or primarily covalent) and rather weak in semiconductors. This indicates that in semiconductors, the valence electrons are not as tightly bonded to the atoms. Because of this, these electrons can be released by thermal stimulation more readily than they can in insulators[5], [6].

Factors affecting Resistivity

Temperature Influence: Any increase in temperature of a conductor (which contains trace levels of impurities) causes the metallic ions to bounce more violently about their mean location. This decreases the mean free route and prevents free electron mobility, lowering the metal's conductivity and raising the metal's resistivity.

Influence of Impurities:Impurity or solute atoms have an additional impact that shortens the mean free route of electrons. The atoms of the solute cause the normal crystalline structure to shatter, which hinders the motion of the electron waves. Even though both individual components have higher conductivities than the alloy, a solid solution alloy will always have lower conductivity than its pure components.

Influence of Plastic Deformation: Due to an increase in the number of electron-scattering dislocations, plastic deformation also increases electrical resistance.

Effect of Pressure: At room temperature, metal generally behaves in a way that initially decreases as pressure increases and may even pass through a minimum. The initial decline results from pressure's ability to reduce the amplitude of lattice vibrations.

Electrical characteristics of alloys used for commercial purposes

Because of its electrical and other characteristics, copper is the most often used metallic conductor. Copper with a very low oxygen and other impurity levels, known as oxygen-free-high-conductivity (OFHC) copper, is produced for numerous electrical applications. Aluminum is also extensively employed as an electrical conductor despite having a conductivity that is around half that of copper. Silver has a better conductivity than either copper or aluminum, but its use is limited due to its extremely high price when compared to copper and aluminum. On occasion, it is required to increase a metal alloy's mechanical strength without noticeably reducing its conductivity. A trade-off must be made between conductivity and strength because both solid solution alloying and cold working increase strength at the expense of conductivity. The most common way to increase strength is to add a second phase that has less of a negative impact on conductivity is still lowered by around a factor of 075 compared to high purity Cu[7], [8].

Mechanism of strengthening in metals

Designing alloys with high strengths and some ductility and toughness is a common requirement; typically, ductility is sacrificed when an alloy is strengthened. Almost all strengthening methods are based on the straightforward idea of making a material harder and stronger by limiting or obstructing dislocation motion. The following are the single-phase metals' strengthening mechanisms:

(i) Grain-size Reduction Strengthening Since the former has a larger total boundary area to restrict dislocation motion, a fine-grained material (one with small grains) is tougher and stronger than one with coarse grains. According to the equation y = o + kyd-1/2 (19) where d is the average grain diameter and o and ky are constants for a specific material, the yield strength y changes with grain size for various materials. The Hall Petch equation (19) is referred to as such. It's important to notice that Eq. (19) is invalid for both extremely fine and very large grain polycrystalline materials. The toughness and strength of many alloys are both enhanced by the reduction in grain size.

(ii) Solid-Solution Strengthening: Alloying with impurities that enter either a substitution or interstitial solid solution is another method for strengthening and hardening metals. The term "solid-solution strengthening" describes this. Due to the solute atoms in solid solutions, alloying elements or impurities raise the resistivity of materials. The atoms in the solute obstruct the movement of electrons. Cu atoms in a Cu-Ni alloy do not obstruct the motion of free electrons, whereas Ni atoms do. High-purity metals are always softer and weaker than alloys made of the same base metal, it should be noted. Tensile and yield strength rise in tandem with an increase in impurity content. Because impurity atoms that enter solid solution typically impose lattice strains on the surrounding host atoms, alloys are stronger than pure metals.

(iii) Strain Hardening, Work Hardening, or Cold Working: This is the process by which a ductile metal hardens and strengthens when it is deformed plastically. It is also known as work hardening or cold working since the temperature at which deformation occurs is "cold" in comparison to the metal's absolute melting point. Most metals undergo room-temperature strain hardening. Because cold work alters the crystal structure of the metal and causes

localized strain to interact with electron mobility, the metal becomes more resistive. But further annealing reduces the resistance. Therefore, hand drawn copper wire is more resistive than annealed copper.

Insulators

Almost no free electrons are available for electrical conduction in a perfect insulator because all of the valence electrons are involved in bond formation. So an electrical material known as an insulator, which has a relatively large energy band gap and a filled valence band at 0 K. As a result, the electrical conductivity at ambient temperature is extremely low less than 10⁻¹⁰. The resistivity of a good insulator may reach 10¹⁴ (m). Polyethylene, bakelite, lucite, mica, PVC, rubber, porcelain, and other materials are frequently used as electrical insulators. At normal temperature, most polymers and ionic ceramics act as insulators. A material's ability to insulate is negatively impacted by thermal agitation and flaws, yet in real materials, there are always a few free electrons available to carry electricity. Ionic and covalent connections hold non-metallic crystals together, and valence electrons are considerably more intimately linked to their atoms than in a metallic bond. In general, insulators are those substances that have huge energy gaps while simultaneously having all of the electrons in the Brillouin Zone entirely filled.

As temperature rises, more and more conducting electrons are released, increasing the conductivity of insulators. The materials that are insulators at zero degrees Celsius but generate considerable conductivities at normal temperature, on the other hand, turn into semiconductors. A high electrical resistivity is desirable since, of course, many insulating materials are utilized because of their capacity to insulate.Electrical, mechanical, thermal, and chemical requirements for good insulating materials can all be categorized. The insulating material's electrical properties should be high resistivity to prevent leakage current and strong dielectric strength to enable it to endure higher voltage without being damaged. Additionally, there shouldn't be much dielectric loss in the insulator. Because insulators are utilized based on volume rather than weight, a low density is preferable. For liquid insulators, homogeneous viscosity and electrical and thermal properties are guaranteed.

Transformer oil, hydrogen, and helium are examples of liquid and gaseous insulators that are used for insulation and cooling. It goes without saying that excellent thermal conductivity is a desired attribute for such materials. The insulator should also have minimal thermal expansion to avoid mechanical damage. Additionally, it should be self-extinguishing or non-ignitable if it can catch fire. Chemically, the insulating materials ought to be impervious to acids, alkalies, liquid gas fumes, and oils[9], [10]. Additionally, since water reduces insulation resistance and dielectric strength, the insulator shouldn't absorb water particles. Depending on their intended function, insulators should possess specific mechanical qualities. As a result, insulators used to insulate electric machinery need to be strong enough mechanically to endure vibration. In these circumstances, good heat conductivity is also preferred. Insulating materials with high electronic and ionic polarizabilities and consequently high permittivity are utilized to create dielectric capacitors. One such substance has a permittivity of 100, which is titanium oxide. We should highlight that the potential for significant dielectric losses at high frequencies makes it undesirable to use molecules having a permanent dipole moment.

Dielectrics

These are the insulators or materials that have the special ability to hold electric charge. As the atoms are joined together, the electrons in these substances become localised. It goes without saying that solids or gases with dielectric or insulating qualities are produced by covalent, ionic, or combinations of the two types of bonds, as well as by Vander Waals bonding between atoms with closed shells. With the exception of air, which serves as the insulating substance between the bare conductors of the overhead electric grid system, dielectric materials can be gases, liquids, or solids. Liquid dielectrics are primarily utilised as filling and cooling medium for transformers and circuit breakers as well as impregnants for high voltage paper insulated cables and capacitors. The most typical characteristics of dielectric materials are: (i) the dielectric constant; (ii) the dielectric strength; (iii) the insulation resistance; (iv) the surface resistivity; (v) the loss factor; (vi) the tangent of the loss factor in terms of a capacitor or phase difference; and (vii) the presence of polar and non-polar materials.

When moisture and impurities are eliminated from materials that can separate electrical conductors and circuit breakers, such as silicon, oils, and liquid dielectrics, they exhibit high dielectric constants, high resistance, and high dielectric strength. They can dissipate heat at a rapid rate and suffer the fewest dielectric losses. They have a dielectric constant above one. The following materials are crucial from an engineering perspective: Mica is a common insulating material used in electrical heating devices including irons, hot plates, and switch gear armature windings. Additionally, it is utilised in high frequency capacitors. An inorganic substance called mica is made up of soda potash, magnesia, and aluminum silicates. It is naturally crystalline and readily separates into incredibly thin, flat sheets. Muscovite and phlogopite are the two main varieties of mica. Mica has strong mechanical and dielectric strength. Its loss tangent ranges from 0.0003 to 0.015, its dielectric constant is between 5 and 7.5, and its dielectric strength is between 700 and 1000 kV/mm.

Paper, tape, fabric, and board all contain asbestos and are used as insulators. In panel boards, insulating tubes, and cylinders used in air cooled transformer construction, asbestos is frequently employed. An inorganic substance known as asbestos is used to describe a class of naturally occurring fibers. Asbestos has good mechanical and dielectric properties. Inorganic non-metallic compounds such as silicates, aluminates, oxides, carbides, borides, nitrides, and hydroxides are common in ceramics. Alumina, porcelains, ceramics, titanates, and other types of ceramics can be generically categorized as ceramics used as dielectrics. These have superior mechanical and dielectric qualities. Most frequently used ceramics have dielectric constants between 4 and 10. These are utilised in vacuum type ceramic metal seals, thermocouples, cathode heaters, plug holds, switches, and other devices. Ceramic capacitors may be shaped into any shape and size and can work at extreme temperatures.

Ceramics of the electric grade are employed in the production of insulators, terminal blocks, plates, frames, coils, etc. Low losses and effective insulating qualities are required. Electricgrade porcelain, which has decent electric characteristics, is used to create insulators for use at low frequencies. Its poor strength and substantial losses, which spike at temperatures beyond 200°C, are disadvantages. Steatite, a talc-based substance, is used primarily in the construction of insulating components for high frequency operation. Steatites maintain their characteristics at temperatures up to 100°C and don't contain any dangerous contaminants. They are useful for manufacturing items where accurate dimensions and a dense yet porous structure are required since they are easily pressurized and only shrink by 2% to 1% when burned. Steatite may be sliced relatively readily (after burning), in contrast to other types of ceramics. Their shortcomings include cracking when subjected to abrupt temperature changes and various challenges associated with burning.

An inorganic insulating substance called glass is made up of a complicated system of oxides. The most crucial component of many commercially used glasses is silica (SiO2). It is fused with some base (such as lime, lead oxide, etc.) and alkali (such as potash, soda, etc.). The best insulating substance is silica glass, which has 100% SiO2. Glass has a dielectric constant that ranges from 3.7 to 10, a loss tangent of 0.0003 to 0, and a dielectric strength of 2.5 to 50 kV/mm. Electric bulbs, X-ray tubes, mercury switches, and electronic valves all use glass as an insulating medium. It serves as the dielectric material in capacitors as well. Organic

polymers known as resins can be either natural or artificial. Artificial means are used to make the synthetic resins.

Polyethylene, polystyrene, polyvinyl chloride, acrylic resins, teflon, nylon, etc. are examples of synthetic resins that are frequently used. These have good mechanical and dielectric qualities. Resins' dielectric constant ranges from 2 to 4.5, their loss tangent from 0.0002 to 0.04, and their dielectric strength is relatively high. High frequency capacitors are utilized in transformers. These are also utilised in d.c.capacitors as a dielectric material.

Rubber

These organic polymers might be either natural or artificial. Due of its tolerance to both high and low temperatures, natural rubber derived from rubber trees is only used in a restricted number of applications. The artificially created synthetic rubbers are made by copolymerizing isobutylene and isoprene. These have good thermal and electrical characteristics. Rubber has a dielectric constant that ranges from 2.5 to 5, and a loss tangent between 0.01 and 0.03. Electric wires, tapes, cables, coatings, motor windings, transformers, etc. are all made of rubber, which serves as an insulating material. Nitrogen, hydrogen, and other gaseous dielectrics have a dielectric constant of 1.0. Polystyrene, polycarbonate, polyethylene, polymide, mineral oil, pure alumina, and pure silica are the best dielectric materials.

Polar and non-polar materials

Some molecules have permanent dipole moments due to an uneven arrangement of positively and negatively charged areas. Polar molecules are those that fit this description. For instance, in the HCl molecule the hydrogen atoms electron moves around the Cl atom more frequently than it does the H atom. As a result, the center of positive and negative charges do not overlap, and the molecule possesses a dipole moment that points from the Cl atom to the H atom. In other words, we may write H+ Cl-. The HCl molecule's electric dipole has a p value of 3.43 10⁻³⁰ C-m. The electric dipole moment in the CO molecule, is only mildly asymmetrical and is only approximately $0.4*10^{-30}$ C-m, with the carbon atom corresponding to the positive and the oxygen atom to the negative end of the molecule. There will also be Vander Waals interactions between nearby polar molecules. It's important to note that these bonding energies are far higher than they are for bonds involving induced dipoles. The hydrogen bond, the strongest secondary bonding type, is an example of polar molecule bonding. We discover that it happens in molecules when hydrogen is covalently bound to fluorine, oxygen, and nitrogen (as in the HF, H2O, and NH3 molecules). The one hydrogen electron is shared with the other atom in each H-F, H-O, or H-N bond.Unscreened and positively charged, a positively charged bare proton is what the hydrogen end of the bond is fundamentally.(Any electrons form a hydrogen bond in the H atom. This molecule's extremely positively charged end can exert a powerful attractive attraction on a nearby molecule's negatively charged end. It is obvious that this one proton connects two negatively charged atoms. The strength of the hydrogen bond can reach up to 0.52 eV/molecule (= 51 kJ/mol), which is often higher than the other secondary bond types. Due to hydrogen bonding, we discover that the melting and boiling points of hydrogen fluoride and water are unnaturally high given their modest molecular weights.

Polarization

A material's field strength interacts with the electric field when it is exposed to an electric field for instance, between the condenser's plates. When an applied electric field is applied to a wire, some of the free electrons simply shift to the side closest to the positive electrode until they completely cancel it out. No field is left in the material, of course. Equilibrium is created when charged particles are almost simultaneously displaced.Electrons can only be shifted locally in insulating or non-conducting materials since they are attached to the individual

atoms. However, this localized electron movement is sufficient to polarize the material. Each atom experiences a displacement of the negative electron cloud with respect to the positive nucleus, resulting in a tiny induced dipole with a negative pole facing the positive side of the electric field. This electrical polarizations affects all dielectric materials.

Ionic materials also experience induced polarization. For instance, in an ionic crystal, the negative ions are drawn to the positive side and vice versa. A good illustration of ionic polarization is NaCl. It has an order of 10-29 C-m dipole moment and an interionic spacing of 0.1 nm. Due to the asymmetric nature of their atomic structures, many molecule structures feature permanent electric dipoles. These molecules include H₂O, HCl, polyvinyl chloride, etc. as a few examples. Additionally, certain molecules have stable charges that cause dipole moments in the individual molecules. Glasses contain dipoles and this sort of polymer is very common. In such materials, the permanent molecular dipoles can spin about their axis of symmetry to line up with an applied field that causes a torque in them. The term "orientation polarizations" describes this. Because of thermal fluctuations, not all of the dipoles can align with the applied field in this sort of polarizations, which makes it rarely ideal.

Non-polar Materials

Most hydrocarbons do not have polarity. The molecules in non-polar materials can be visualized as positive nucleus of charge q surrounded by a symmetrically distributed negative electron cloud of charge -q. These molecules are typically diatomic and made up of two atoms of the same kind. The centers of gravity for the positive and negative charge distributions coincide in the absence of an applied electric field. When molecules are exposed to an external electric field, electric forces between the positive and negative charges tend to push them apart in the direction of the external electric field. Since restoring forces, which increase with increasing displacement, limit the displacement, the distance moved is relatively small (10-10 m). The molecules are considered to be polarized when the centers of positive and negative charges no longer coincide.

Insulation Resistance

This prevents a significant flow of electric current across several conductors that are separated from one another at various electrical potentials. The potential difference may result in current leakage via two channels, namely (i) across the insulation surface and (ii) through the solid material of the insulators. Due to the composition of the material, we may observe that the resistance provided along the aforementioned two pathways is not the same. The former is caused by the material's surface resistivity, whilst the later is brought on by the material's volume resistivity. The insulating resistance of the material is the result of two combined effects. The resistance between the two opposing edges of a square of one unit area of insulation surface can be used to define surface resistivity. The resistance a material of unit cross section and unit length presents to the flow of an electric current at absolute zero is known as the volume resistivity.

Real dielectrics have the following resistance characteristics: (i) Mobility under potential action, which allows any conducting species to move.

(ii) Temperature fluctuation of conductivity explains why a dielectric's conductivity changes exponentially with temperature.

(iii) To examine the frequency or time variation of conductivity, as well as the time response of dielectrics.

(iv) It is important to know the breakdown voltage or maximum voltage a dielectric can withstand when designing a piece of equipment.

Ferro-electricity

Ferroelectrics are a class of dielectric materials that exhibit spontaneous polarization, or polarization without an electric field. In a sense, ferroelectrics are ferromagnets' electric equivalents, which have the potential to exhibit persistent magnetic behavior. An external electric field can alter and even reverse the polarization in ferroelectric materials. Because a ferroelectric crystal's structure can be created by tiny ion displacements from a non-polarized structure, the spontaneous polarization is reversible. The majority of ferroelectric crystals undergo a phase transition from the polarized phase (ferroelectric phase) into the un-polarized phase (para-electric phase) when heated above a critical temperature, known as the ferroelectric Curie temperature (Tc). The spontaneous polarization at Tc may vary continuously or abruptly. Various ferroelectric crystal forms have Tc values that range from a few degrees absolute to a few hundred degrees absolute. Practically speaking, there are two classes of ferroelectrics: (i) Only one crystal axis can be polarised in this first class of ferroelectrics, such as Rochelle salt, KH2PO4, (NH4)2 SO4, guanidine aluminium sulphate hexahydrate, glycine sulphate, colemanite, and thiourea. (ii) In this second class of ferroelectrics, spontaneous polarisation can happen along a number of axes that are equivalent in the paraelectric phase, such as in ferroelectrics of the BaTiO3 type (or perovskite type), Cd2Nb2O7, PbN2O6, and certain alums like (NH4)2 - Cd3(SO4)3. Ferroelectrics can also be divided into appropriate and inappropriate types. In appropriate ferroelectrics, such as Rochelle salt, BaTiO3, and KH3PO4, the spontaneous polarization serves as the order parameter. The spontaneous polarisation in unsuitable ferroelectrics might be viewed as a by-product of another structural phase transition.

CONCLUSION

For the advancement of numerous technical disciplines, the research of materials' electrical and magnetic properties is essential. We have learned critical lessons about the behavior of materials in electric and magnetic fields as a result of our work. We have discovered that a material's intrinsic qualities, such as the quantity and mobility of charge carriers, determine its electrical conductivity and resistance. The ability of a material to conduct electric current is measured by its conductivity. It depends on elements like the concentration and mobility of free charge carriers (such ions or electrons). Because delocalized, free-moving electrons are present, conductors like metals have high conductivities. Conversely, insulators have limited conductivity because they contain few or no free charge carriers. The alignment and interaction of magnetic moments also results in a variety of magnetic behavior in materials, such as ferromagnetism, para-magnetism, and diamagnetism. These discoveries have ramifications for the creation of magnetic materials, power systems, and electronic gadgets. Our research also emphasizes the value of theoretical models and experimental methods in comprehending and forecasting the electrical and magnetic properties of materials. We can better understand material behavior and direct the design and optimization of diverse devices by fusing theoretical frameworks with experimental measurements.

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CHAPTER 5

APPLICATIONS OF AN OVERVIEW OF THE SEMI-CONDUCTORS

Dr.Pulleparthi Naidu, Associate Professor, Department of Physics, Presidency University, Bangalore, India, Email Id-mohankumar.p@presidencyuniversity.in

ABSTRACT

Scientific research and a wide range of technological applications depend heavily on the electrical and magnetic characteristics of materials. For the creation of cutting-edge magnetic materials, power systems, and electronic gadgets, understanding these qualities is crucial. In this study, we look into the underlying theories that underlie the electrical and magnetic properties of various materials. We investigate the connection between resistivity, electrical conductivity, and the inherent characteristics of materials. In addition, we study phenomena like diamagnetism, para-magnetism, and ferromagnetism as well as the magnetic behavior of materials. We learn more about how materials behave when exposed to electric and magnetic fields using experimental methods and theoretical models. The findings lay a foundation for additional improvements in electrical and magnetic technology as well as for our understanding of material science as a whole. A vital class of materials that have changed modern technology are semiconductors. This abstract gives a general review of semiconductors, emphasizing their special qualities, uses, and importance across a range of industries. Between conductors and insulators in terms of electrical conductivity are materials known as semiconductors. They can display unusual electrical behavior because of their small energy bandgap. At absolute zero, the conduction band is empty and the valence band is completely filled with electrons. By gaining enough energy as the temperature rises, electrons can shift from the valence band to the conduction band and transform into mobile charge carriers. Intrinsic and extrinsic semiconductors are the two main classifications for semiconductors. Pure substances like silicon (Si) and germanium (Ge), which derive their electrical properties from the natural behavior of their atomic structures, are examples of intrinsic semiconductors. Extrinsic semiconductors have their conductivity altered by purposeful doping with impurities, which involves introducing foreign atoms into the crystal lattice. Doping can produce either n-type (with extra electrons) or p-type (with extra holes) semiconductors.

KEYWORDS

Band, Electrons, Holes, Impurity, Semiconductors, Semiconductors.

INTRODUCTION

Although the electrical conductivity of semiconductors is lower than that of metals, they nonetheless have several distinctive electrical properties that make them very valuable. An insulator like diamond has an electrical conductivity of roughly 10^{-10} Siemens/m at ambient temperature compared to a metal's approximate value of 108 Siemens/m. A semiconductor has an electrical conductivity that ranges from 10^5 to 10^{-4} Siemens/m. Even minute impurity concentrations have a significant impact on the electrical characteristics of semiconductors. The following additional characteristics of semiconductors are present.

(i) The resistance of semiconductors reduces with increasing temperature and vice versa for pure (intrinsic) semiconductors, which have a negative temperature coefficient of resistance. This behavior of semiconductors is in opposition to a metal's positive temperature coefficient of resistance.

(ii) A semiconductor will display a photo-voltage or a change in resistance when exposed to light.

(iii) Semiconductors have a high thermoelectric power of both positive and negative signs in comparison to a metal.

(iv) There are typically two categories of semiconductors. Those that produce electrons and holes by heat activation are referred to be intrinsic or pure semiconductors, examples of which include silicon and germanium. Extrinsic semiconductors are another type in which the current carriers, holes or free electrons, are created by the addition of very minute amounts of Group III or Group V elements to the periodic table. Depending on whether electrons or holes are the major charge carriers, extrinsic semiconductors can either be n- or p-type. Impurities in the donor introduce extra electrons, whereas impurities in the acceptor introduce extra holes. It has ractification properties when a p-type and n-type semiconductor are combined.

(v) Semiconducting materials' electrical conductivity is highly sensitive to temperature, impurity type, and impurity content.

A semiconductor has a narrower band gap than an insulator. Semiconductors have a fully filled valence band at absolute zero degrees Celsius, which is separated from an empty conduction band by a typically less than 2 eV wide forbidden gap. In contrast to an insulator like diamond, which has a band gap of 6 V, semiconductors have a band gap that ranges from 0.2 to 2.5 eV. In a semiconductor, the reduced band gap causes thermal excitation of electrons from the valence band to the conduction band at room temperature. This explains why an intrinsic (pure) semiconductor has a higher electrical conductivity than an insulator. Si and Ge are the two fundamental semiconductors, with band gap energies of roughly 1.1 and 0.7 eV, respectively. Both are covalently bound and can be found in Group IVA of the periodic table. For the majority of the earliest solid state devices, Ge served as the primary semiconducting material. Si has since taken its place in a number of applications. Si is more commonly available, has sophisticated technology, and has superior thermal stability. In addition to Ge and Si, a variety of compound semiconducting materials, such as gallium arsenide (GaAs), indium phosphide (Inp), indium antimonide (InSb), indium arsenide (InAs), lead sulphide (PbS), cadmium sulphide (CdS), lead telluride (PbTe), zinc telluride (Zittel), mercury (II) These semiconductor materials have also been employed in a number of electronic devices, such as the transistors, lasers, microwave, and millimeter wave devices made of GaAs, the infrared detectors made of PbS and PbTe, the light meters made of CdS, the nuclear radiation detectors made of CdTe, and so on. Amorphous semiconductors are a significant area of scientific and technological interest. The atomic arrangement in an amorphous substance contains some short-range organization but no long-range order. Selenium, germanium, and silicon in their amorphous phases, as well as arsenic and germanium chalcogenides, including ternary systems like Ge-As-Te, are representative amorphous semiconductors. A suitable quenching technique can be used to create some amorphous semiconductors from melt. Vapour deposition can be used to create amorphous films. Semiconducting compound alloys are used in a variety of significant applications. For instance, indium gallium arsenide (In1-xGaxAs) is used in microwave and optoelectronic devices, gallium arsenide phosphide (Ga Asx P1-x) is used in light-emitting diodes (LED), cadmium mercury telluride (CdxHg1-xTe) is used in infrared detectors, etc[1]-[4].

Intrinsic Semiconductors

A semiconductor is referred to as intrinsic (or pure) if its electrical conductivity is entirely caused by the motion of charge carriers (electrons and holes) that are generated by thermal excitations from the valence band to the conduction band, i.e. as a result of thermal disruption of covalent bonds. In intrinsic semiconductors, the ratio of electrons to holes is constant. If a semiconductor contains more than one impurity per 100 million pieces of semiconductor, it is

not genuinely intrinsic. Two significant elemental semiconductors are Ge and Si. A Ge crystal contains four valence electrons on each atom. The Ge atom's inner ionic core has an electrical charge of +4 units, which is positive. The four valence electrons are bound together by covalent connections with the four Ge atoms that are closest neighbours. In the absence of any heat breakage of chemical bonds at 0 K, the valence electrons are not available for electrical conduction since they bind one atom to another. A pure or intrinsic semiconductor behaves obviously like an insulator at 0 K. According to the band diagram, the valence band is entirely full and the conduction band is entirely empty at zero degrees Celsius.

Some of the valence electrons have sufficient thermal energy at normal temperature to rupture their valence or covalent bonds. As a result, these electrons are now free to flow wherever in the crystal. About 1.1 eV in silicon and 0.72 eV in ge are required to break a covalent bond at ambient temperature (Eg). Every time an electron departs from a covalent connection, a void or hole is left in the place where it was. A little circle represents a hole created by a free electron in a covalent bond. A hole is a void or electron shortage like this. According to the energy band diagram, the electrons in the valence band are thermally energised to move into the conduction band, where they are liberated. Thusly created holes are voids in the valence band. A hole is equivalent to an electron's net positive charge.

Free electrons and holes are always produced in pairs in semiconductors because every time a free electron is produced, a hole is produced concurrently at its original location. In an inherent semiconductor, the concentration of free electrons and holes will always be equal. Thermal generation is the name given to this particular form of free electron-hole pair production in semiconductors.Due to their thermal energy, the electrons in the valence band and conduction band travel randomly within the crystal. The random thermal motion of the charge carriers, or electrons and holes, is superimposed with a drift velocity when an external field is applied to the semiconductor. An electric current is created by the drift of holes in the valence band and electrons in the conduction band. Since the electron carries a negative charge and the hole a positive charge, the currents created by the movement of electrons and holes in opposite directions. As a result, the conventional current moves from the positive electrode to the negative electrode inside the semiconductor. A hole's energy is calculated from the top of the valence band downward.

It is possible to think of the movement of the valence band electrons as being equivalent to the movement of the holes in the opposite direction. Of course, the conductivity is also affected by the perforations. When an electronhole pair is formed thermally, a nearby atom's valence electron may have enough thermal energy to move into the hole's location and rebuild the covalent connection. The electron does this by leaving a hole in its starting location. The hole actually shifts from one position to the other. As a result, the holes move in the polarity opposite of the valence electrons. Because of this, a hole acts like a free space equivalent to the electrical charge in positive charge. Compared to the electrons that drive the motion of the holes in the valence band, the electrons in the conduction band travel more readily. As a result, the conduction band electrons contribute more to the electric current than the valence band holes do. The following can be used to summarise the key characteristics of an intrinsic semiconductor:

(i) The number of holes in the valence band equals the number of electrons in the conduction band. When two systems are in equilibrium, their electron and hole concentrations are equal, or $n = p = n_i$, where n_i stands for intrinsic concentration.

(ii) The Fermi level (EF = Eg/2) is located exactly in the energy void between the valence and conduction bands.

(iii) The electrons' contribution to the electric current exceeds that of the holes.

(iv) In an intrinsic semiconductor, around 1 atom out of every 103 atoms contributes to conduction.

(v) A hole and an electron can act as a pair that is bound to one another. A bonded pair like that is typically referred to as an exciton. Due to its electrical neutrality, an exciton is not a participant in electrical conduction[5]–[8].

DISCUSSION

Effective Mass

The charge carriers, or electrons and holes, are subject to forces from both the externally applied field and the internal periodic field created by the crystal when an external field is applied to a semiconductor. If the internal field has the effect of changing the carriers' mass, the carriers will respond to the external field by having a changed mass that complies with classical mechanics if the internal field is substantially weaker than the external field. The term "effective mass of the carriers" refers to this modified mass of the carriers, which is typically indicated by the letter m*.

The electronic mass (m) in a vacuum is typically different from m*. By avoiding the quantum aspect of the issue, the effective mass approximation enables us to investigate the impact of external fields or forces on the charge carriers, i.e., on the electrons or holes inside the crystal, using classical mechanics.

Extrinsic Semiconductors

Due to their extremely low conductivity, or the fact that only 1 atom in 10^9 participates in electrical conduction, intrinsic semiconductors are not very useful in real-world applications. In intrinsic semiconductors, one would need to apply a very large electric field, which is not practical, in order to reach an acceptable current density. However, it is discovered that the conduction of Ge and Si is dramatically altered by the presence of impurities, even to the amount of 1 in 10^9 . The impurities employed have well-known characteristics. They can be purposefully introduced in precisely calibrated dosages.

As a result, any predefined conductivity semiconductor can be obtained. For instance, the addition of 10 parts per million of boron increases the conductivity of Si by a thousand times. The subsequent conduction is known as impurity conduction and is crucial to a semiconductor device's functionality. Doping is the addition of an impurity to an inherent semiconductor. The additional impurity is known as a dopant. The accessible quantum states are changed when these impurity or foreign atoms are added to the semiconducting structure; one or more new energy levels may develop in the semiconductor's band structure. As a result, semiconductor characteristics undergo considerable alterations. Doped, impure, or extrinsic semiconductor is the term used to describe the resulting substance.

Extrinsic semiconductors can be divided into two categories: those in which the impurity adds extra electrons to the conduction band and those in which it adds extra holes to the valence band. Group V impurities like phosphorous (P), antimony (Sb), and arsenic (As) when added to Ge or Si result in an excess of free electrons, whereas group III impurities like indium (In), boron (B), aluminium (Al), and gallium (Ga) result in an excess of holes. Tellurium (group VI element) and zinc (group II element) both produce surplus free electrons and holes in a compound semiconductor, such as InSb. We can observe that when small amounts of tetravalent or pentavalent impurities—roughly one part in 107—are added to a semiconductor during crystallisation, the impurity atoms lock into the crystal lattice because they are not significantly larger than Ge or Si atoms, and the crystal is not unduly distorted. A semiconductor that is extrinsic can be of two types, depending on the impurities: the N- and P-type.

N-type Semiconductor

Tetravalent elements are silicon and germanium. Penta-valent or trivalent impurity atoms, or those from groups V and III of the periodic table, are two possible types of impurity atoms. If a small amount of a pentavalent impurity—one with five electrons in the outer orbit—such as arsenic (As), antimony (Sb), or phosphorus (P) is added to germanium. While the fifth valency electron is free to migrate from one atom to another, each of the four out of the impurity's five valency electrons, such as those of arsenic, enters into covalent connections with germanium. Due to its ability to give electrons, the impurity is known as a donor impurity and the crystal as an N-type semiconductor. Germanium gains billions of free electrons from a small quantity of arsenic (an impurity), greatly enhancing its conductivity. Electrons make up the majority of charge carriers in N-type semiconductors, whereas holes make up the minority. This is due to the fact that when donor atoms are given to a semiconductor, the additional free electrons give the semiconductor more free electrons than it would otherwise have. Additionally, donor electrons do not create holes, in contrast to the electrons that are liberated as a result of thermal agitation. As a result, negative electrons make up the majority of the current carriers in a semiconductor doped with penta-valent impurities[9], [10].

There are five valence electrons on the impurity atom. It has a +1 surplus charge after donating one electron. It subsequently transforms into an immobile, positively charged ion. It's crucial to realize that although while electrons (negative charges) make up the bulk of carriers in N-type semiconductors, the semiconductor that has been doped with impurities maintains an electrically neutral state. Due to thermal energy, free electrons and holes are produced in pairs, and the positive charge of the stationary ions exactly balances the negative charge of the electrons provided by impurity atoms. They should be taken into account as a continuous structure that covers the entire background. The distribution of the fixed or immobile ions inside the crystal structure is regular. Due to their freedom of movement, the electrons and holes are demonstrated to be randomly dispersed at all times.

P-type Semiconductor

When a germanium intrinsic semiconductor is supplemented with a trivalent impurity (one with three electrons in the outermost orbit), such as indium (In), boron (B), or gallium (Ga), the impurity atoms will displace some of the germanium atoms during the crystal's development. Only three of the four potential covalent bonds are filled in this instance, leaving the fourth bond empty and acting as a hole. As a result, whenever an electron switches from one bond to another, a hole goes in the opposite direction of the electron. There are billions of holes introduced into the crystal by this trivalent impurity, also known as the acceptor or P-type impurity, and these holes, which serve as the majority carriers of the charge, are what make the crystal conduct. These crystals are referred to as P-type semiconductors or P-type crystals for this reason. P-type semiconductors have a different energy band diagram from pure superconductors. Since there are more holes than there are electrons, which are drawn to them, they help initiate current flow. In turn, this causes the acceptor energy level to be a little higher than the valence band's. It is lower than the donor level, though. Although not quite as easily as N-type semiconductors, P-type semiconductors conduct more readily than pure semiconductors.

Effect of temperature

The number of electron-hole pairs will increase when the temperature of an N-type semiconductor rises as a result of thermal excitations from the valence band to the conduction band. The donor atoms are already ionized, thus the quantity of electrons coming from that level will not change. The concentration of free electrons from the valence band produced thermally will, of course, be considerably higher at very high temperatures than the

concentration of free electrons provided by the donors. At this point, the semiconductor will behave like an intrinsic one since the concentrations of holes and electrons will be almost equal. The same argument can be used to claim that a P-type semiconductor will operate similarly to an intrinsic semiconductor at extremely high temperatures. Generalizing, we can state that an extrinsic semiconductor becomes an intrinsic semiconductor as its temperature rises.

Semiconductor devices

A semiconductor device is a component that is made entirely or mostly of semiconducting materials and has applications in electronic devices and solid-state research. Transistors, integrated circuits (Ic), semiconductor diodes (P-N junction), and other types of semiconductor devices are examples. The most often utilised materials for creating semiconductor devices are Si, Ge, and GaAs. provides a convenient summary of these semiconductors' features. A single crystal semiconductor containing two or more semiconductor devices. In devices containing two, three, or more separate areas, the difference in the electric fields and carrier densities associated with differently doped regions, known as junctions, permit a wide range of fundamentally nonlinear conductivity effects. The most basic of these junctions, known as the P-N junction, which is a system of two semiconductors in physical contact, one with excess electrons (N-type) and the other with excess holes (P-type), can explain the majority of semiconductor devices.

P-N junction

P-N junctions are created when two semiconductors of different types come into touch with one another when crystallization is occurring. This junction possesses crucial characteristics and serves as the foundation for current semiconductor theory and application. P-N junctions can be found in the majority of semiconductor devices. The ability of a P-N junction to conduct current solely in one direction is its most crucial feature. It offers a very high resistance in the opposite direction.

P-N Junction Formation: By mixing acceptor and donor impurities into the single crystal as it formed, P and N regions have been grown into the germanium block. It's called a grown junction. It is important to note that the grown type of P-N junction comprises of P and N layers in a single piece of germanium rather than being a sandwich created by joining a P block to a N block.

A pellet of an acceptor impurity, such as indium, is placed on one face of a wafer of N-type germanium, and the two components are heated to melt the impurity, creating the diffused junction. A little amount of the impurity metal will diffuse into the wafer under the right temperature and time circumstances, forming an area of P-type germanium in close proximity to W-type bulk. Because some pellet material alloys with the germanium in this junction, it is also known as an alloyed junction or fusion-alloy junction. Here, the face of an N-type germanium wafer is pressure-contacted by a thin, pointed wire (catwhisker). After assembly, the device is electroformed by briefly applying a high current spike across the Wafer and Whisker connection. A tiny volume of germanium immediately beneath and around the point becomes P-type as a result of the heat produced during the brief interval driving a few electrons from the atoms in the area of the point contact, leaving holes.

Similar techniques are used to create silicon P-N junctions. The silicon has typically been treated in a way that makes it P-type. In order to form the junction, N-type material must either be introduced at the appropriate time during the crystallization process or—in the diffused, junction process—subsequently incorporated into the P-type wafer's body. Similar to germanium diodes, silicon diodes can be made using junction or point contacts.A P-N

junction right after it forms and without any external voltage. The P-N junction is not electrically coupled to any external voltage. The following processes start because P-type material has a large concentration of holes and N-type material has a high concentration of free electrons:

(i) At the junction, free electrons from the N area and holes from the P region both diffuse into each other. Dispersion is the name of this procedure. In the N-region, holes unite with the free electrons, whereas in the P-region, electrons combine with the holes.

(ii) The diffusion of holes from the P region to the N region and electrons from the N region to the P region across the junction occurs due to their haphazard movement caused by thermal energy and also because there is a difference in their concentrations (The P region has more holes while the N region has more free electrons) in the two regions.

(iii) Positive donor ions are exposed, or robbed off free electrons, as the free electrons migrate across the junction from N-type to P-type. Because of this, the N-side of the connection develops a positive charge. At the same time, the free electrons traverse the circuit and close the holes to reveal the negative acceptor ions. Therefore, the P-side of the connection develops a net negative charge. Further diffusion is halted when a enough number of donor and acceptor ions are exposed. It's because there is currently a hurdle in the way of additional charge carrier movement. This is referred to as a junction barrier or potential barrier. The potential barrier ranges between 0.1 and 0.3 volts. Further diffusion is stopped once there are enough donor and acceptor ions exposed. This is due to the fact that positive charge (ions) on the N-side now prevents holes from crossing from P-type to N-type and repels free electrons from entering from N type to P type. As a result, there is a potential difference between the two parts, which prevents additional electron-hole combinations at the junction.

(iv) The depletion zone is the area across the P-N junction where the potential shifts from a positive to a negative value. This section is around $6 \ 10^{-8}$ metres wide.

This region is also known as the space-charge zone because it contains immobile (fixed) ions that are electrically charged.

The material is still neutral on both sides of the connection outside of this area.

(v) The potential barrier for a germanium P-N junction is roughly 0.3 V, compared to about 0.7 V for a silicon P-N junction.

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A P-N junction right after it forms and without any external voltage. The P-N junction is not electrically coupled to any external voltage. The following processes start because P-type material has a large concentration of holes and N-type material has a high concentration of free electrons:Fig. 1 when P-N junction just formed.

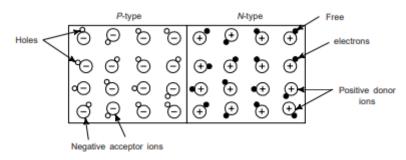


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(iv) The depletion zone is the area across the P-N junction where the potential shifts from a positive to a negative value. This section is around $6*10^{-8}$ meters wide. This region is also known as the space-charge zone because it contains immobile (fixed) ions that are electrically charged. The material is still neutral on both sides of the connection outside of this area.

(v) The potential barrier for a germanium P-N junction is roughly 0.3 V, compared to about 0.7 V for a silicon P-N junction. The potential barrier prevents most carriers from diffusing over the junction. Minority carriers, such as the few free electrons in the P area and the few holes in the N region, are aided in crossing the junction by the potential barrier. Thermal energy continuously produces the minority carriers. However, since no circuit has been linked to the P-N junction, electric current cannot flow.

CONCLUSION

For the advancement of numerous technical disciplines, the research of materials' electrical and magnetic properties is essential. We have learned critical lessons about the behavior of materials in electric and magnetic fields as a result of our work. We have discovered that a material's intrinsic qualities, such as the quantity and mobility of charge carriers, determine its electrical conductivity and resistance. Semiconductors are essential in many applications due to their special characteristics.

The field of electronics has the most widespread applicability. Transistors, which are essential parts of computers, communication devices, and integrated circuits, are built on semiconductors. Electrical signals can be amplified and switched thanks to semiconductors' capacity to control the flow of electrons. The alignment and interaction of magnetic moments also results in a variety of magnetic behavior in materials, such as ferromagnetism, paramagnetism, and diamagnetism. The development of electronic gadgets, power systems, and magnetic materials may be affected by these results.

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CHAPTER 6

APPLICATIONS OF SUPERCONDUCTIVITY AND SUPERCONDUCTING MATERIALS

Dr. Usman Pasha, Associate Professor, Department of Physics, Presidency University, Bangalore, India, Email Id-mahaboobpasha@presidencyuniversity.in

ABSTRACT

When materials are chilled below a critical temperature, a remarkable phenomenon known as superconductivity occurs where there is zero electrical resistance. Superconducting materials' characteristics and uses are examined in this study. We examine the processes that lead to Cooper pairing and the creation of the energy gap, two of the mechanisms underlying superconductivity. In addition, we investigate the critical temperature, critical magnetic field, and critical current density, which are fundamental superconducting parameters. We learn more about the behavior of superconducting materials and their potential for many technological applications, such as energy transfer, magnetic resonance imaging (MRI), and particle accelerators, using experimental methods and theoretical models. When chilled below a threshold temperature, certain materials exhibit zero electrical resistance and the expulsion of magnetic fields, which is known as superconductivity. This abstract gives a general review of superconductivity and superconducting materials, emphasizing its characteristics, uses, and importance in the advancement of science and technology. Superconductors are substances that can carry electric current without experiencing any resistance, allowing electrons to move freely without losing any energy. Cooper pairs, pairs of electrons with opposing spins that develop at low temperatures, are responsible for this peculiar behavior. There is no resistance because these Cooper pairs, connected by phonons, can flow through the substance without dispersing. A distinguishing feature of superconductors is the critical temperature, commonly referred to as the transition temperature. A material goes through a phase transition and develops superconductivity when it is cooled below its critical temperature. The critical temperature for each material varies, ranging from a few millikelvins to more than liquid nitrogen's boiling point (-196 degrees Celsius).

KEYWORDS

Current, State, Superconducting, Superconductors, Temperature.

INTRODUCTION

A significant range of metals and alloys can conduct electric current without resistance when chilled to sufficiently low temperatures. It is obvious that these particular materials go through a phase transition to a new superconducting state, which is characterized by the total loss of dc. Resistance below a precisely determined critical temperature, T_c . Thus, at all temperatures below a critical temperature (= 0 for any T= T_c), infinite conductivity (zero resistivity, = 0) is observed in a superconductor. Superconductivity, however, vanishes if we pass a current greater than the critical current density Jc. This has an impact on the maximum current that the material can support and is a significant issue for superconducting material applications. The transition temperature (TC), for elements, is often lower than 10 K. Resistance lowers quickly to an immeasurably small value at the transition temperature, TC. Usually abrupt, the change from the normal to the superconducting phase takes place between 10-2 and 10⁴ K. This trend supports the existence of a physically distinct superconducting state and contrasts sharply with the continuously diminishing resistance of non-

superconducting metals. Within a temperature range of 1 mK, the zero-resistance state can be reached in pure metals. The transition to the superconducting state may be significantly widened in the case of impure metals. For impure tin, a transition width of 0.05 K was noted. As far as is measurable, a superconductor has zero resistance to direct current.

According to the estimates, the resistivity in the superconducting phase is less than 4 10-25 - m, which is practically nil. Inducing a current around a small ring of a superconducting metal is an impressive approach to show zero resistance. There have been experiments where a "persistent current" has operated for more than 2.5 years without experiencing any discernible degradation. I(t) = I0 e-t/, where I0 is the starting value of the current and t is the amount of time that has passed since the super-current was produced, gives the time dependency of the current I in the loop. The superconducting loop's self-inductance L to resistance R ratio affects the time constant for the current's decay. The metal is in its natural state above the critical temperature TC, and resistance is proportional to T5. The exponent in several metals ranges from 2 to 6, which is significantly different from the value of 5 that Bloch theory predicts.

The critical temperature, or TC, varies from superconductor to superconductor, although for metals and metal alloys it ranges from below 1 K to roughly 20 K. Up until 1986, a niobium, aluminum, and germanium alloy was found to have the highest TC. Recent research has shown that several intricate cuprate oxide ceramics have critical temperatures above 100 K. Currently, HgBa2Ca2Cu3O8+, a mercury-based cuprate oxide, has the highest known TC of 133 K. The start of TC rises to 164 K when this compound is subjected to high pressure (30 GPa). The tremendous evolution of critical temperatures that has been seen since its discovery in 1911 by K. Ones is depicted. Cuprate oxides and some other recently discovered superconductors with TC > 25 K are referred to as high temperature superconductors (HTSC), whereas superconductors with TC 25 K are known as conventional or low TC superconductors. The superconducting state is characterised by perfect diamagnetism, or B =0 inside the superconductor, in addition to resistance less current transmission. When a superconductor is cooled below TC under a weak external magnetic field, the magnetic inductance inside the superconductor is zero because the magnetic flux is evacuated from the inside of the superconductor. The Meissner-Ochsenfeld effect is the final practical test for every new material and is named for its discoverers. It is important to remember that there is always a critical field, Hc, over which superconductivity vanishes. If a magnetic field outside of the material is applied, superconductivity vanishes and the material returns to its normal state (Hc)[1]–[4].

Super conducting Materials

Superconducting elements are primarily found in metallic elements. Typically, their TC ranges from a few to a few hundred Kelvin. Niobium has the highest critical temperature of all the pure elements among metals, with a TC = 9.2 K. Noble metals like copper, silver, and gold, as well as alkaline metals like sodium and potassium, are great electrical conductors at room temperature, but they aren't superconductors until very low temperatures, if at all. Metallic substances that are magnetic do not have superconductivity. Si and Ge, the two most well-known semiconductors, turn into superconductors at a pressure of 2 K bar and temperatures of 7 and 5.3 K, respectively. Under pressure, the following elements also turn into superconductors: P, As, Se, Y, Sb, Te, Ba, Bi, Ce, and U.

Binary Alloys and Compounds: The critical temperatures are typically a little higher for most alloys and compounds. Nb compounds like Nb3Sn, Nb3Ge, and especially Nb-Ti are of interest in technology. While the maximum current density that can be passed through a standard water-cooled copper wire at 300 K is approximately 2000 A-cm2, a wire made of a Nb-Ti alloy can pass extremely high current densities of up to 104 A-cm2 in high magnetic

fields of 10 Tesla at 4.2 K without losing its superconductivity. This makes it possible to create strong super-magnets that serve as the foundation for a number of large-scale applications, such as energy storage or the levitation of trains, etc[5], [6].

DISCUSSION

Intermetallic Compounds

The most advantageous group of intermetallic superconductors is that based on the A3B compound. Six binary compounds with TC over 17 K are found in the cubic A-15 structure. The Nb3Ge material stabilized with traces of oxygen or aluminum produces the highest known TC before 1986, which is close to 23 K and displays an upper critical field of 38 T. In around 70 binary compounds, the A-15 structure is present. For A-15 superconducting compounds, the 2 Hc (T) values are extremely high. 2 Hc (O), the upper critical field values for A-15 compounds are similarly extremely high as the temperature approaches 0 K, for example, 44 tesla for a composition of Nb79 (Al73Ge27)21, 32 T for Nb3Al, 39 T for Nb3Ge, 23 T for Nb3 Sn, 21 T for V3Ga, and 25 T for V3Si. materials. ThPd3B3C (TC = 21 K) and YPd5B3C (TC = 23 K) are intermetallic compounds that have just been identified.

Fullerene Superconductors: Graphite and diamond are the first two pure carbon compounds, and fullerene is a stable, cage-like compound. C60 is the typical fullerene. Superconductivity is seen when C60 is doped with alkaline metals at TC = 18 K, 30 K, 33 K, and 40 K for K3C60, Rb3C60, RbCs2C60, and Cs3C60, respectively. Recently, it was shown that hole doped C60 (for C60/CHBr3 with 3 to 3.5 holes per C60 molecule) may super-conduct with a temperature coefficient (TC) as high as 117 K. However, due to the nature of the experiment, the super-currents were restricted to the surface of the C60 crystal, rather than exploring the bulk.

Superconductors made of heavy fermions Fewer uranium compounds, such as UBe13, UPt3, URu2Si2, UNi2Al3, and UPd2Al3, as well as one Ce compound, CeCu2Si2, show superconductivity with TC 1 K. big volumes of the linear coefficient of the electronic specific heat (Ce = T), which can reach values of up to 1 J mol-1 K-2, and a correspondingly big electron mass (m* 102 -103 me, where me is the free electron mass), are characteristics of these compounds. The majority of these systems show that superconductivity and antiferromagnetism can coexist.

Itinerant Electron Ferromagnetic Superconductors: It has been demonstrated that the intermetallic compound Y9Co7 displays an intriguing interaction between extremely weak ferromagnetism and some type of superconductivity. Below 6–8 K, the system exhibits ferromagnetism, and at a lower temperature (3 K), superconductivity takes hold. Recently, superconductivity in UGe2 below 1 K on the edge of weak ferromagnetism has been reported.

Quantum Spin Ladder Materials: These substances are composed of ladders with S = 1/2 AFM chains connected by interchain AFM connections. Sr2Cu2O5 is a 3-leg ladder material, whereas SrCu2O3 and LaCuO2.5 are 2-leg materials. Under pressure of TC 12 K at 3 GPa, superconductivity has reportedly been found in the ladder material Sr0.4 Ca13.6 Cu24O41.84.

Magnesium Diboride (MgB2): Superconductivity at 39 K in the straightforward binary ceramic compound MgB2 was recently found. This is likely the greatest TC for a bulk non-copper oxide superconductor that has been determined to date. Similar to the HTSC cuprates La2-x MxCuO4 (M = Ba, Sr, Ca, and Na), Sr2RuO4 is a superconducting compound. Despite having a very low transition temperature (TC) of 1 K, Sr2RuO4 is a very interesting compound since it is the only multilayer perovskite superconductor that is free of copper.

High Temperature Cuprate Superconductors: Up until 1986, metals and alloys accounted for the majority of superconducting substances. Even so, the transition temperatures of a few oxide superconductors were only moderately high. The fundamental cause of this was the dearth of carriers in the metallic state. With TC 13 K, LiTi2O4 and BaPbBiO3 were two examples of exceptions. Given that they had relatively low carrier densities, this was quite remarkable. The crucial discovery was made in 1986 by J.G. Bednorz and K.A. Muller in a mixed phase copper-oxide ceramic containing La2-xBaxCuO4, setting a new record for superconductivity with an onset of 35 K. With the discovery of the rare-earth metal oxide Yttrium barium copper oxide, or YBa2Cu3O7, which has a critical temperature of roughly 92 K, the years 1986 and 1987 were distinguished by the synthesis of these compounds. This was a noteworthy development because it signaled the first time that a superconductor with a TC higher than liquid nitrogen (boiling point 77 K) had been discovered. Helium is substantially more expensive than nitrogen, which is also far more plentiful. Helium is also used in liquid nitrogen cryogenic systems. The development of hybrid microelectronic technology (semiconductor-superconductor devices), which can be customized to work better at liquid nitrogen temperatures, is one application that could benefit from nitrogen cooling[7], [8].

HtscCuprate Materials Characteristics

(i) Highly anisotropic, layered structures: All HTSC oxides are layered perovskites, with the exception of one substance (isotropic, cubic Ba1-x KxBiO3). The existence of CuO2 planes in the layered, perovskite-like crystal structures of all cuprates is one of their key properties. The CuO2 planes are thought to be the main residence of the mobile charge carrier, which can be electrons but is typically holes. Naturally, the majority of these systems' characteristics are dominated by the existence of CuO2 layers.

(ii) Metallic Oxides: HTSC cuprates exhibit metallic behaviour, whereas the majority of oxides are insulating substances. Many of these cuprates can be made superconducting by doping them with charge carriers and substituting the right components into the insulating parent combination. In the antiferromagnetic insulator La2CuO4, for instance, the substitution of divalent Sr for trivalent La dopes the CuO2 planes with mobile holes and results in superconductivity in La2-xSrxCuO4 with a maximum TC of 40 K at x 0.17. Similar to this, the antiferromagnetic insulating compound Nd2CuO4 appears to dope the CuO2 planes with electrons when tetravalent Ce is substituted for trivalent Nd. This results in electron doped superconductivity in Nd2-x CexCuO4-y with a maximum TC of about 25 K at x 0.15 for y 0.02.

La2-x SrxCuO4 and YBa2Cu3O7, the original materials, were synthesised by their discoverers as ceramic pellets. One makes a pallet by mixing the right proportions of the constituent oxides, grinding and sintering them, and then cooling it in oxygen after calcination (at about 950°C). Like typical ceramics, HTSC oxides have holes, twins, grain boundaries, and other flaws. Even the best thin films often contain microscopic grains; they are typically harmful to the high critical current densities needed for applications. It is important to note that even the best HTSC cuprate single crystals frequently have numerous flaws and faults such oxygen vacancies, twins, contaminants, etc. These flaws are not only crucial to their fundamental thermodynamic (meta) stability. We may see that different flaws present in HTSC crystals are inherent to these materials.

Characteristic Properties of Superconductors

(i) Infinite Conductivity, or Zero Resistivity: a superconductor's electrical resistance at zero frequency and all temperatures below a threshold point In fact, TC is 0. The transition has been classified as an electronic phase transition because, in the first approximation, it is not accompanied by a change in the structure or properties of the crystal lattice.Pure metals show

a clear transition from the normal to the superconducting state, although some impure, deformed, and HTSC oxides do not. The chemically intricate materials known as cuprates based on Bi, Tl, and Hg may have many superconducting phases in a single specimen. At least two superconducting phases can be seen in a two-step transition. A single-phase and multi-phase high temperature superconductor's resistance as a function of temperature. For single-phase high temperature superconductors, the TC transition width is typically 1 K. Achieved in epitaxial YBa2Cu3O7 films are TC values as low as 0.3 K.

(ii) Meissner-Ochsenfeld (ii) Effect (inside the superconductor, B = O): When a superconductor cools under a weak external field, the magnetic inductance inside the superconductor is zero. The Meissner-Ochsenfeld effect is the name of the phenomenon. If the sample had been cooled while an external field was being applied or if the field had been added after the sample had been cooled below TC, the sample's final condition would have been different. The field would have remained within the sample in the first scenario, but it would have been zero in the second.

(iii) Thermal Properties of Superconductors

(a) Entropy

All superconductors experience a significant reduction in entropy upon cooling below TC. The decrease in entropy in a superconductor indicates that the superconducting state is more ordered than the regular state because entropy is a measure of how disorderly a system is. In the superconducting state, the portion of electrons that is thermally stimulated in the normal state acquires order.

(b) Thermal Conductivity

The thermal conductivity of superconductors continuously varies between the two phases, and is typically lower in the superconducting phase and close to zero at very low temperatures. This implies that the electronic contribution decreases and that superconducting electrons may not contribute to heat transfer at all. Tin (TC = 3.73 K) has a thermal conductivity of 16 W cm-1 K-1 for the superconducting phase and 34 W cm-1 K-1 for the normal phase at 2 K.

(c) Thermoelectric Properties

The Peltier effect, which is the foundation of how thermocouples used for temperature monitoring work, is a combined thermal and electric effect of interest and practical significance. Electrical current is driven around a loop made of two distinct metals if the two junction regions are kept at different temperatures. Due to the presence of some 'normal' electrons at any non-zero temperature, this current is significantly weaker in the superconducting state. The normal thermoelectric voltage is "shorted out" by the presence of superconductivity.

Acoustic Attenuation: When a sound wave travels through a metal, the minuscule electric fields caused by the ions' displacements may give electrons close to the Fermi level energy while depleting the wave's own energy.

High Frequency Electromagnetic Properties: The electromagnetic response in the superconducting state is equal to the response in the normal state at all frequencies significantly higher than the frequency corresponding to the energy gap, Eg = hv, where v is the frequency in Hz. One may easily comprehend that the change in the frequency response happens at v 10¹¹ and 10¹² Hz in the conventional and HTSC oxides, respectively, if they keep in mind that 1 eV 10¹⁴ Hz. Superconductors' electromagnetic properties at high frequencies are distinct from their zero- or low-frequency behavior. The resistance of the

superconductor to current flow is not zero in the radio- and microwave-frequency ranges $(10^8 - 10^{11} \text{ Hz})$. The resistance is still rather low, as is the energy loss that goes along with it.

Experimental research has shown that both TC and Hc are marginally altered when a superconducting material is mechanically stressed. The critical field strength depends on the difference in the free energies of the two states, and it is clear that many mechanical aspects of the superconducting and normal states are thermodynamically related to these states' respective free energies. When a normal material turns superconducting, there is a very little change in volume, and the bulk modulus of elasticity and thermal expansion coefficient must also fluctuate slightly between the superconducting and normal states. The results, nevertheless, are incredibly minimal.

Absence of effects:As we've seen, the shift to the superconducting state has a significant impact on the majority of a superconductor's electrical properties while having little to no impact on many other aspects. These include, among other things, the density, tensile strength, and mechanical and elastic properties.

Properties of HTSC oxides

The major characteristics of elemental or conventional superconductors, such as zero resistivity, the Meissner effect, flux quantization, the Josephson effect, etc., are shared by all HTSC oxides. The transport properties of HTSC oxides in the normal state differ significantly from those of normal metals due to their (i) highly anisotropic layered structures (ii) short zero temperature coherence length (=10), and (iii) strongly anisotropic resistivity, anomalous magnetoresistance, pseudogap, etc. HTSC oxides are referred to as unconventional superconductors for this reason. We succinctly list the HTSC oxides experimental findings:

(i) All of the HTSC oxides have a two-dimensional CuO2 network and have layered crystal structures.

(ii) In HTSC oxides, the coordination of copper in Cu-O sheets is square planar.

Cu-O bonds (iii) have a bond distance of almost 1.9 and are very covalent.

(iv) The HTSC oxides have extremely anisotropic normal state transport characteristics. With a very small extrapolated residual resistivity ab(0), the electrical resistivity ab(T) in the abplane of many hole-doped cuprate superconductors near optimal doping has a linear temperature dependence between TC and high temperatures 1000 K, where ab(T) 0 and the value of c are comparable across different classes of cuprate materials. However, the c-axis resistivity (c) exhibits semiconducting (c T-1) dependency for samples with less oxygen and metallic (c T) dependence for samples with sufficient oxygen. c/ab 30 at room temperature. The cotangent of the Hall angle H = RH/ changes as T2, i.e., cot (H) xx/xy = AT2 + B. The Hall coefficient, RH, is inversely proportional to T. RH has a positive sign, which denotes that holes are the charge carriers. RH is significantly lower for H parallel to the ab-plane than for H parallel to the c-axis.

(v) The pseudogap in the charge and spinexcitation spectra of under-doped cuprates is perhaps the most amazing characteristic of the normal state. A number of transport, magnetic, and thermal measurements, such as ab(T), RH(T), and thermoelectric power, S(T), among others, have shown characteristics from which the pseudogap has been deduced.

(vi) La2-xSrxCuO4 has a large positive Seeback coefficient, S(T), while YBa2Cu3O7- has a tiny positive value for S(T). The in-plane, Sab(T), exhibits temperature independence while Sc(T) exhibits a linear temperature change. Anistropy in S(T) has been reported.

(vii) A significant variation in coherence length between directions that are parallel to the caxis and those that are not makes large anisotropy obvious. The bismuth superconductor is believed to have the highest anisotropy, with coherence lengths of 40 in the transverse direction and 2 along the c-axis. Our results for YBa2Cu3O7 are ab (15) and c (4.0).

(viii) The coherence length () of typical superconductors is 10-4 cm. It is equal to 10-40 in HTSC oxides, which is comparable to the size of the unit cell, but it is thousands of times smaller there. We can see that c is less than the equivalent unit cell length and nearly equal to the interlayer distance. All material-related features are dominated by these incredibly low coherence lengths, which also result in a complicated mixed state. Short coherence length also suggests that type II superconductors with extremely high 2 Hc are present in HTSC oxides.

(ix) The relationship between TC and charge carrier concentration is not monotonic. The greatest value of TC is reached at a comparatively low charge carrier density of 1021 cm-3. In traditional superconductors, the TC increases monotonically as concentration increases[9], [10].

(x) For YBa2Cu3O7, estimates of the upper critical field 2 11 Hc (0) and 2 Hc (0) provide 120 T and 510 T, respectively. The highest critical fields are undoubtedly anisotropic as well.

(xi) Different values are obtained from measurements of the energy gap in the one-particle spectrum of a novel superconductor using the tunnelling and infrared radiation absorption and reflection methods. The tunnelling method yields a greater gap measurement. Tunnelling parallel to the plane results in values of 2 (0)/KBTC that are in the range of 5.8 to 6.0, while tunnelling perpendicular to the plane has lesser values in the range of 3.8 to 4.

(xii) The isotope impact in HTSC oxides is substantially smaller than what the BCS theory based on the electron-phonon interaction predicted.

Applications of Superconductivity

As old as superconductivity itself, ideas about its technological applications have been around. Onnes himself made an effort to investigate the possibilities of a condition of zero resistivity for electrical uses. However, he was unable to construct electromagnetic coils using pure superconducting metal wires, such as lead or indium. In mild external magnetic fields (B 0.1 T), these metallic superconductors readily lose their superconducting characteristics. Additionally, they could only transport flimsy electric currents. It was soon discovered that the Type-II superconductors of interest for strong current applications—those that can withstand extremely high magnetic fields—are typically fairly complex materials, such as Nb compounds, Chevrel phases, or cuprate oxides.

Superconducting magnets have now been designed and produced in every conceivable size and geometry. The superconducting magnet is considerably smaller than its typical counterpart constructed of copper wires for equal power and upper field. As was the case in the 1960s, superconducting magnets are now used in solid state physics, high energy physics, and other fields. Controlled thermonuclear fusion, superconducting motors with several kilowatts of output, energy storage facilities, and the magnetic suspension of trains (leviation trains) are already in the design stages. Supermagnets are strong superconducting magnets that are also utilised in medicine for diagnostic purposes, such as nuclear spin tomographs.

High-intensity, homogenous magnetic fields are produced by superconducting magnets with little noise. Several manufacturers currently offer 20-T superconducting magnets with bore sizes ranging from 50 nm to 100 nm. There are currently efforts on to design and build solenoidal magnets with fields that are close to 25 T using novel superconducting materials, such as HTSC oxides. Superconducting magnets appear more complex than electromagnetic

ones, particularly given the low temperature needed to maintain the magnetic solenoid's superconducting condition. The usage of superconducting magnet technology dispenses with the requirement for electromagnets' kilowatt or megawatt power supplies in order to generate extraordinarily high magnetic fields. Users can quickly detach superconducting magnets from their power source and they will continue to be powered, which considerably lowers electricity expenditures.

However, superconducting magnets are not the only large-scale applications for which superconductivity is taken into account. For the generation and transmission of electric power, superconductivity is being used with a lot of effort. Storage components and superconducting cables will have significant benefits. Although the use of superconductors in measuring technology is not novel, it does give us the chance to attain orders of magnitude greater sensitivity for many measurements than we could with conventional conducting circuitry. Under some circumstances, superconducting circuit and memory components could improve massive computers. The most significant significantly application of superconductivity-based technology is typically thin film applications in electronics, along with superconducting magnets. The majority of these applications rely on the Josephson phenomenon, which makes it possible to build Josephson junctions, the fastest nanoscopic switches, and other related device structures called SQUIDs (superconducting quantum interference devices). A superconducting loop study reveals that the magnetic flux that can thread the loop is quantized in quantum units of flux, which have a value of 2-15 Weber. SQUIDs explore these delicate quantum interference effects. SQUIDs are appropriately processed superconducting loops that are highly sensitive magnetic flux detectors that can be included into the most advanced precision instruments at the forefront of meterology.

We can use the superconductors made from HTSC oxides at temperatures as high as liquid nitrogen (TB = 77 K) or even higher.

Although the general application of HTSC cuprate superconductors in technology has not yet been achieved, over the past 15 years, significant and consistent development has been made in this direction. According to recent advances, HTSC cuprates will start to have a big impact on technology within the next 5 to 10 years. In superconducting electronics, SQUIDs, NMR (nuclear magnetic resonance) coils, wireless communications subsystems, MRI cols and NMR microscopes, and diagnostic equipment are anticipated to be realised on this time frame. Applications including power transmission lines, motors and generators, transformers, current limiters, magnetic energy storage, magnetic separation, research magnetic systems, and current leads in the field of superconducting wires and tapes look to be possible within this same time frame.

The creation of flexible superconducting ribbons made of deposits of YBCO on textured substrates, which have critical current densities Jc 106 A/cm2 in fields up to 8 T at 64 K, a temperature that can be reached by pumping on liquid nitrogen, is an example of recent advancements in the field of superconducting wires and tapes.

These prototype conductors perform better than NbTi and Nb3Sn, which are already utilised in commercial superconducting wires at liquid helium temperatures in a comparable field range, in strong magnetic fields. It is undeniable that HTSC oxides have created new possibilities for superconductivity's technological uses.

But it's also a given that a lot more research and development will be required before we have conductors that are adequate for use in, say, magnet manufacturing or microcircuitry. In the beginning, passive microwave devices and SQUIDs will be the main applications where HTSC oxides will have some influence. Future wires and cables may be built on mixes of HTSC oxides and silver, which may give somewhat enhanced characteristics. Here, economic issues will be of utmost importance.

CONCLUSION

Several technical sectors hold significant promise for the development of superconductivity and superconducting materials. Insights into the basic mechanics of superconductivity, such as Cooper pairing and the creation of the energy gap, have been gained as a result of our research.

These processes allow electrical current to flow freely and generate special electrical properties as a result. The critical temperature, which establishes the temperature below which a substance becomes superconducting, is one of the crucial elements of superconductivity. Scientists have been able to reach greater critical temperatures thanks to developments in material engineering and cooling methods, making superconductivity more accessible and useful for a variety of applications. Superconductors are substances that can carry electric current without experiencing any resistance, allowing electrons to move freely without losing any energy.

Cooper pairs, pairs of electrons with opposing spins that develop at low temperatures, are responsible for this peculiar behavior. There is no resistance because these Cooper pairs, connected by phonons, can flow through the substance without dispersing. A distinguishing feature of superconductors is the critical temperature, commonly referred to as the transition temperature.

A material goes through a phase transition and develops superconductivity when it is cooled below its critical temperature. The critical temperature for each material varies, ranging from a few millikelvins to more than liquid nitrogen's boiling point (-196 degrees Celsius).

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CHAPTER 7

EXPLORING THE ORGANIC MATERIALS: POLYMERS AND ELASTOMERS

Dr. VeerabhadrappaJagadeesha, Assistant Professor, Department of Physics, Presidency University, Bangalore, India, Email Id-jagadeeshaangadi@presidencyuniversity.in

ABSTRACT

Organic materials, including polymers and elastomers, are adaptable substances with a wide range of uses in different sectors of the economy. This investigation focuses on polymers and elastomers as it examines the characteristics and applications of organic materials. We look into their chemistry, mechanical operation, and thermal characteristics. We also examine how they are used in industries including packaging, building, automobiles, and biomedicine. We obtain insights into the special qualities and potential of organic materials through experimental characterization and theoretical models, underlining their significance in contemporary technology and daily life.Due to their diverse qualities and simplicity of processing, organic materials, particularly polymers and elastomers, are essential in a variety of applications. This abstract gives a general introduction of organic materials, highlighting polymers' and elastomers' properties, production techniques, and key uses. The big molecules known as polymers are made up of monomers, which are repeating units. Based on their structural characteristics, they can be divided into many categories, such as linear, branching, and crosslinked polymers. Polymers are excellent for a variety of applications because they have a wide range of characteristics, including flexibility, toughness, low density, and electrical insulation.

KEYWORDS

Atoms, Carbon, Chain, Materials, Molecules, Polymers.

INTRODUCTION

Organic materials are derivatives of carbon that have chemically combined hydrogen, oxygen, or any other non-metallic molecule, and their structures are typically quite complicated.Organic materials can be prepared or produced artificially and can be either natural or synthetic. Wood, natural rubber, coal, petroleum, food items, and other organic materials are examples of naturally occurring organic materials. Plastics, lubricants, rubber, soap oils, synthetic fibers, and others are examples of synthetic organic materials. Given that there are hundreds of hydrocarbon compounds and their derivatives, it is clear that the range of organic molecules is exceedingly broad.

Common engineering materials with industrial significance include wood and wood products, plastics, and synthetic rubbers known as polymers. The non-crystalline character of the organic materials distinguishes them. However, since organic materials are made up of organized atoms arranged in various sub-units, their non-crystalline solid formations are not entirely random.

All non-crystalline materials have features that allow the sub-unit arrangements to tangle entirely and very quickly in the liquid state itself. However, they cannot be separated after they have solidified.

Due to entanglement, such materials develop into three dimensional networks or long chain molecules. These organic non-crystalline substances are typically referred to as amorphous solids and can be either elements or compounds. One such illustration of these materials is

glass. Another type of amorphous material is SiO2 (silica). Polymers are the most significant amorphous materials.

Polymers

Polymer characteristics are tightly linked to the material's structural components, just like they are with metals and ceramics. The majority of polymers have an organic origin and are based on hydrocarbons, which are made up of hydrogen and carbon. The intramolecular bonds are also covalent. In contrast to hydrogen atoms, which only have one covalent bonding electron, carbon atoms have four potential covalent bonding electrons. When each of the two bonding atoms contributes one electron, as in the case of methane a single covalent link is formed. The sharing of two and three pairs of electrons, respectively, results in double and triple bonds between two carbon atoms. Ethylene's structural formula (C2H4) is displayed. It is important to notice that the two carbon atoms in ethylene are doubly bound to one another as well as singly bonded to two hydrogen atoms on either side. The symbols for single and double covalent bonds are - and =, respectively. A triple bond can be seen in acetylene (C2H2).Unsaturated organic molecules are those that have double and triple bonds; as a result, each carbon atom in these compounds is not bound to the maximum number of four other atoms, leaving room for the attachment of an additional atom or group of atoms to the original molecule. For a saturated hydrocarbon, on the other hand, all bonds are single ones, meaning that no new atoms may be linked without first removing those that are already bonded. Even though saturated organic compounds are three dimensional structures, they are for convenience represented using a two dimensional structural formula.

The majority of polymers are organic (carbon-based) substances made of molecules with different ratios of hydrogen, oxygen, nitrogen, and carbon. These four substances are among the most frequently occurring ones in organic polymers. The remaining components attach to the carbon, which serves as the "spine" of the polymer chain. These polymer chains entangle and coil iniquitously, adding to their strength. Some of this entanglement is organic, while it can also be brought on by additions and deliberate methods. The majority of polymers are made from hydrocarbons, where the interaction between the components carbon and hydrogen, CnH2n+2, results in predictable combinations of the two elements. These petrochemical intermediates are made from paraffin's found in petroleum and natural gas, and they are then used to create polymer goods.

Methane (CH4), ethane (C2H6), propane (C3H8), and butane (C4H10) are among the paraffin molecules that resemble chains. These hydrocarbons have relatively low melting and boiling temperatures because only weak hydrogen and Van der Waals interactions, not strong covalent connections, connect molecules inside each molecule. boiling point does, however, grow with molecular weight. Most rubber and polymer products start with these intermediates as their foundation. Coal is used to make intermediates as well. Among these intermediaries, ethylene is the most significant. These are referred to as olefin intermediates and include butadiene, acetylene, propylene, butylene, and isobutylene. The majority of these are utilized in the creation of rubbers. Butadiene is used to make nylon, whereas acetylene is used to make polyvinyl chloride. Benzene, toluene, and xylene are examples of the aromatic intermediates. Aromatic organic compounds are those which are generated from benezene (C₆H₆) by substituting various groups of atoms for the hydrogen atom. Benezene has a ringshaped structure with the hydrogen atoms connected to each carbon atom outside the ring and the carbon atoms grouped in a regular hexagon. In the structure, a single line between two carbon atoms denotes a covalent link, while a double line denotes a double covalent bond. Obviously, the location of the double bond in the ring is different between the two structures (a) and (b) Typically, the benezene ring or structure is depicted as a straightforward hexagon; the carbon and hydrogen atoms are not visible in the structure. Any group that has been used in place of hydrogen atoms is displayed next to the relevant hexagonal corner[1]–[4].

Cyclohexane is the most significant intermediate in the napthenic category, which is another group of intermediates utilized to make nylon. Insecticides, detergents, rocket fuel, films, medicines, explosives, alcohols, and other similar items are made from intermediates made of aromatic, napthenic, and olefin compounds. In place of oil, coal, or gas, wood is used to make cellulosic plastics.

The following list of general polymer features can be distilled:

(i) The lengthy chain architectures of polymers. A polymer's one molecule can contain hundreds of smaller molecules that are all covalently bound together, making it incredibly massive.

(ii) Carbon, which further forms bonds with hydrogen, nitrogen, halogens, or other organic or inorganic elements, is a component of all polymers.

At room temperature, polymers are typically non-crystalline solids, while their structure may be crystalline in basic materials. During their synthesis, polymers undoubtedly go through a viscous phase.

(iv) Polymers can be easily produced and shaped, and they are lightweight. They have limited thermal conductivity and poor electrical conductivity. The polymers are also resistant to chemical attack and deterioration.

Broad Classification

Typically, polymers fall into one of three major categories: (i) plastics, (ii) fibers, or (iii) elastomers. Additionally, polymers can be divided into groups based on their composition, formability, geometric structure, and molecular structure. Thermoplastic resins, sometimes known as plastics, have the feature of increased plasticity, or the capacity to deform plastically as temperature increases. They are made of a lengthy chain construction. Thermosetting resins, on the other hand, feature a three-dimensional network of main bonds. They don't become soft when heated. They harden when heated because any lingering polymerization reactions are finished. At high temperatures, they breakdown as a result of their interaction with atmospheric air. Degradation is the term used to describe the breakdown of thermosetting plastic. Plastics have several key characteristics, including: (i) low softening temperature; (ii) non-crystalline structure; (iii) ease of complex shape formation; (iv) resistance to chemical reaction, with some exceptions; (v) poor conductor of electricity and low thermal conductivity; and (vi) viscoelastic behavior.

Typically, naturally generated materials like saps and extracts are covered in natural resin. Natural resins can be obtained directly from specific trees' excretions or indirectly via insects that consume the trees' sour juices. Paints, varnishes, enamels, soaps, inks, glues, and other polymeric products all use natural resins as plasticizers. These include copal resins, rosins, and shellacs.

A thermoplastic substance called shellac is employed as a base in a wide range of chemical solvents, as a tough covering for glass, and as a bonding agent. However, it is still employed in the production of abrasive inks and lacquers. Its use has decreased in favor of less fragile materials. Turpentine is a byproduct of the production of rosin, which is a distillate of pine tree sap. Paints, varnishes, soap, paper, and ink all employ rosins. Paints, varnishes, and lacquers use copal resins. Copal resins and celluloid combine to create a tough, abrasion- and moisture-resistant film. Long-chain molecules that are aligned roughly in the longitudinal direction of the fiber make up fibers. With strength throughout the length being more than ten times that across the length, the alignment exhibits extremely directed behavior. Elastomers are long-chain molecules as well, but they have the special quality of having high elasticity.

Basic concepts of polymer science

Polymer: A big molecule made up of many small, basic chemical building blocks. In some instances, repetition is linear, much as how links in a chain are added together. In some situations, chains are connected to one another or branched to create three-dimensional networks. The monomer, or initial substance from which the polymer is created, is often equivalent to or substantially equivalent to the repeat unit of the polymer. Vinyl chloride is the monomer of poly (vinyl chloride), and CH2 equals CHCl in the repetition unit.

Polymerization Process: During polymerization, or the combining of large molecules known as monomers, smaller molecules are joined together to form longer molecular chains by taking advantage of the valence of the carbon atoms partially filled outer shell (which has a valence of 4). The carbon atom can be swapped out for an atom of oxygen, sulphur, silicon, or nitrogen. polymerization to take place, two requirements must be met: (i) A molecule needs at least two places where it has bonds that aren't satisfied but can still combine with other molecules. Starting with a molecule that has a double bond, like carbon, is necessary to meet this criteria. Each bond in the carbon molecule is a pair of shared electrons because the molecule has a double bond. One bond remains if the bond between the carbon atoms breaks, leaving the other two electrons available for sharing with other atoms. A chain can be created if a second carbon atom that has broken a double bond passes by and joins it. This process, known as polymerization, keeps going and creates a polymer chain. As long as the second need is satisfied, the process proceeds.

The presence of at least two open spots following each reaction is the second prerequisite for polymerization. Polymers can build a lot of chains. These chains create threads that intertwine to strengthen one another. Cross-linking can strengthen polymers. When the double bonds connecting atoms in a chain are broken, the atoms or molecules in the chain form or link up with the atoms next to them. The chain is strengthened by this bond, which also lessens molecule-to-molecule slippage. Slippage happens when a load causes the polymer threads to move past one another. Both the molecule's structure and its composition have an impact on the properties of polymers. Propyl (1-propanol) and isopropyl (2-propanol) alcohol are two examples of molecules with the same content that can create two alternative configurations with distinct characteristics. Isomers are the name for these variations. Condensation, copolymerization, or addition polymerization are all methods of polymerization. A huge unit molecule, the monomer, is combined with another monomer during the polymerization process to create a long chain, the polymer (referring to many parts), which has a number of repeated units, or mers. The smallest recognizable units in the chain are mers. The quantity of repeating units with identical structural characteristics that make up the polymer's chain defines its degree of polymerization. There is only one kind of mer involved in addition polymerization.

(iii) The distribution of molecular weight the length of a chain is entirely governed by random events in both chain polymerization and stepwise polymerization. The local availability of reactive groups at the growing chains' ends governs the chain length in step reactions. Chain length in radical polymerization is determined by the amount of time the chain grows before it diffuses near another free radical and the two react. The polymeric product contains molecules with a wide range of chain lengths in either situation. There are reports of extremely large molecular weights in polymers with very long chains (also known as "molecular mass," and "relative molar mass"). Not all polymer chains will develop to the same length during the polymerization process, which creates these huge macromolecules from smaller molecules; this results in a variety of chain lengths or molecular weights. The specification of an average molecular weight typically involves the measurement of a number of different physical characteristics, such as viscosity and osmotic pressure.

(iv) Molecular Structure: Polymers are made up of several molecular chains that may all bend, coil, and kink As a result, nearby chain molecules get entangled and thoroughly intertwined. The huge elastic extensions exhibited by rubber materials and other essential properties of polymers are caused by these random coils and molecular entanglements.

Certain mechanical and thermal properties of polymers are a result of chain segments' capacity to rotate in reaction to external loads or thermal vibrations. We may observe that rotational flexibility depends on the mer's structure and chemistry; for example, the double-bonded (C = C) portion of a chain segment has a hard rotation. Additionally, adding a bulky or big side group of atoms limits rotational motion. For instance, polystyrene molecules with a phenyl side group resist rotational motion better than polyethylene chains.

DISCUSSION

It has been discovered that a polymer's physical properties depend not only on its molecular weight and shape but also on variations in the architectures of its molecular chains. Polymers feature a variety of molecular architectures, including linear, branched, cross-linked, and network, in addition to different isomeric configurations. Modern polymer synthesis processes provide for a great deal of control over a variety of structural options. As was already noted, linear polymers are made up of mer units that are linked together in single chains rather than end to end. Because of their flexibility, these lengthy chains could be compared to a spaghetti-like mass. The fluorocarbons, nylon, polyethylene, polyvinyl chloride, polystyrene, and poly-methyl methacrylate are a few typical examples of polymers that form with linear architectures. There may be significant hydrogen and Vander Waals bonding between the chains of these linear polymers. When heated, these linear polymers melt. A polymer's mechanical strength rises when its chains become entangled with one another due to molecular interweaving. Interestingly, linear polymers are produced by bifunctional monomers, such as ethylene's production of polyethylene[5]–[7].

Branched Polymers

Some polymers feature branched chains as opposed to the linear chain molecules, frequently as a result of side reactions during polymerization. It is possible to create branched polymers by connecting the side branch chains to the main ones. The development of side branches lowers the polymer density by decreasing the chain packing efficiency. Branching is another possibility for the polymers that create linear structures. Thermoplastic polymers that are branched and linear have grown in importance in industry. The temperature can be changed to harden branching polymers.

Cross Linked Polymer

These polymers contain covalent connections that connect adjusted linear strands at various points. During synthesis or by a non-reversible chemical process that often takes place at a high temperature, crosslinking can be achieved. Usually, additional atoms or molecules that are covalently bound to the chains carry out crosslinking. The mechanical properties are significantly impacted, and the mobility of neighbouring chains is severely constrained. Crosslinking is common in rubber elastic materials.

In order to make natural rubber stronger and less plastic, this is done. This procedure is referred to as vulcanization. The crosslinking process in elastomers known as vulcanization is accomplished through an irreversible chemical reaction that typically takes place at a high temperature. In several vulcanizing reactions, sulphur compounds are added to the heated elastomer. Chains of sulphur atoms bond with adjusted polymer backbone chains to form crosslinks, as shown in the reaction shown below, where two crosslinks are visible that are made up of m and n sulphur atoms. Carbon atoms that were doubly bound before vulcanization but are now singly bonded as a result of vulcanization are the main crosslinking

sites. Unvulcanized rubber, or rubber that has not yet been vulcanised, is sticky and squishy and has a low resistance to abrasion. This method improves the tensile strength, modulus of elasticity, and resistance to oxidation-induced deterioration. The number of anchoring sites is determined by the sulphur content.

Ageing of Polymers

We should also be aware that cross-linking might occasionally be bad. Rubber is cross-linked with oxygen in the air over an extended length of time by sunlight's catalytic action. This is referred to as polymer ageing. Rubber that has been cross-linked becomes less elastic and flexible. Cross-linkages should be as few as necessary to maintain the structure. Excessive cross links make the interior structure rigid enough to damage the springy condition.

Network Polymers

Three-dimensional networks are created by tri-functional mer units, which have three covalent linkages. Network polymers are what they are. We should be aware that a heavily cross-linked polymer may be categorized as a network polymer. These polymeric materials exhibit unique mechanical and thermal characteristics. Epoxies and phenol-formaldehyde are just two examples of the materials that fall within this category.

(v) Aspects of Polymer Texture: In a polymer chain, there are two categories of atom geometric arrangements: Configurations: Configurations are defined as arrangements that are established by chemical bonding within the molecule, such as cis and trans isomers or d and l forms. Without breaking and re-forming chemical bonds, this cannot be changed. Conformations: Sets of arrangements brought about by rotation about single bonds, including the primary fold shapes that a polymer chain might take when dissolving. They're referred to as conformations[8]–[10].

Thermo-Plastic and Thermo-Setting Polymers

These are the two broad categories into which polymers are divided:

(i) Thermoplastic polymers: These polymers frequently have ductile, plastic characteristics. Without altering the polymer's characteristics, they can be shaped at high temperatures, cooled, re-melted, and then reshaped into a variety of shapes. To avoid material decomposition, the heat utilized to melt and remelt the thermoplastic must be carefully regulated. The majority of linear polymers and those with flexible chains in some branching topologies are thermoplastic. Usually, heat and pressure are applied together to create these materials. The mechanism used to connect the polymer chains together determines the materials' qualities; in thermoplastic polymers, these bonds are weak secondary bonds, such Vander Waals forces. These bonds can be broken and the materials can be altered by applying heat and pressure. The thermoplastic materials reharden in the new shape after the heat and pressure are released. Acrylic, nylon (polyamide), cellulose, polystyrene, polyethylene, fluorocarbons, and vinyl are examples of common thermoplastic polymers. These are utilized for plastic lenses, floor and wall tiles, fluorescent lighting, etc.

(ii) Thermosetting Polymers: These are frequently created by condensation polymerization and feature robust primary bonds. These have uniformly strong primary bonds, and their structure mimics that of a single, sizable molecule. Their characteristics are the result of chemical alterations that take place during processing, under heat, or when a catalyst is applied. Due to the loss of a portion of the molecule (a chemical byproduct) during the curing process, these polymers are permanently hardened when heat is applied and do not soften or reconfigure following subsequent heating. Once cured, a thermosetting substance will char, burn, or degrade if exposed to more heat. As the polymer chains become entangled and crosslinked during curing, the thermosetting polymers will become hard and intractable. In most cases, there is considerable cross-linking, with 10% to 50% of the chain mer units being crossed linked. Thermoset polymers often have superior dimensional stability, are tougher and stronger than thermoplastics. Typical thermosetting polymers include polyesters, epoxies, alkyds, polyesters, aminos, and phenolics. The majority of thermosetting cross-linked, phenolic, and polyster resins.

Co-polymers

New polymer materials that can be quickly and cheaply synthesised and manufactured and have improved qualities or better property combinations that are supplied by homopolymers are always being sought after. Different types of mers can react to form a chain to produce polymers, which can have more than one type of mer in the chain. Copolymers are the name given to such resultant polymers. Copolymerization is the term for the process used to create copolymers. Depending on the type of monomers and the synthesis method, various forms of copolymers can be created.

The following types of copolymers exist:

(i) Random Copolymer: This kind contains a chain with a random distribution of different mers. When M and R stand for two distinct mers, the random copolymer. Naturally, two unique units are scattered at random along the chain.

(ii) Alternating Copolymer: As the name implies, the two mer units switch places along the chain.

(iii) Block Copolymer: Along the chain, identical mers are grouped in blocks.

(iv) Grafted Copolymer: This copolymer allows for the grafting of homo-polymer side branches of one type onto homo-polymer main chains made of a different kind.

Better mechanical and physical qualities are seen in copolymers. Copolymerization is quite similar to the metallurgical alloying process. Similar to alloys, different copolymers can be synthesised with the appropriate characteristics. Many times, synthetic rubbers are copolymers. Automobile tyres are made from the common random polymer known as styrene-butadiene rubber (SBR). Another random copolymer made of acrylonitrile and butadene is nitride rubber (NBR). NBR is extremely elastic and doesn't swell when exposed to organic solvents. NBR is used to create fuel hoses.

Polymer Crystallinity

Super-molecular structures can range from a well-ordered crystalline form to one that is entirely amorphous due to the complexity of the polymers' molecular structure.

The packing of molecular chains to create an ordered atomic array is what is meant by polymer crystallinity. We are aware that unit cells, which are frequently rather complicated, can be used to specify the crystal structure. This polyethylene unit cell has orthorhombic shape. The chain molecules, however, also go beyond the unit cell. Water and methane are two examples of molecular substances with tiny molecules that are typically either completely crystalline (as solids) or completely amorphous (as liquids). Due to their size and complexity, polymer molecules are frequently only partially crystalline (or semi-crystalline), with crystalline areas scattered throughout the remaining amorphous material. For a polymer, both the chain arrangement and the rate of cooling during solidification affect the degree of crystallinity. The capacity of a polymer to crystallise is also influenced by its molecular chemistry. Additionally, polymers made up of chemically intricate mer structures, such as polyisoprene, do not support crystallization.

For linear polymers, crystallization is simple because there are hardly any constraints that would hinder chain alignment. However, because the side branches prevent crystallization, branched polymers are never very crystalline. Nearly all network and cross-linked polymers are amorphous. Some cross-linked polymers, however, are partially crystalline. Due to the irregular and random arrangement of the mer, copolymers have a higher propensity to produce non-crystallinity.Obviously, the degree of crystallinity has some impact on the physical characteristics of polymeric materials. We should highlight that crystalline polymers are typically more resilient to heat-induced softening and disintegration.

Defects in Polymers

Due to the chain-like macromolecules and peculiar properties of the crystalline form for polymers, the point defect notion in polymers differs from that in metals and ceramics. However, crystalline portions of polymeric materials have been discovered to have point defects, such as vacancies and interstitial atoms and ions, that are comparable to those found in metals. Due to their chemical differences from regular chain units and the presence of vacancies, chain ends are also thought of as defects. Additionally, interstitials, which are impurity atoms or ions or groups of atoms or ions, may be included in the molecular structure. They could serve as brief side branches or be connected to main chains. Chainfolded layer surfaces are regarded as interfacial flaws. The boundaries between two adjacent crystalline areas are regarded as flaws in a similar way.

Mechanism of Deformation

Plastic Deformation Mechanism: Slip between adjacent polymer material molecules causes plastic deformation. Because the molecules are only held together by weak attraction forces, the slide happens quite frequently. Where molecules are lined up in a linear pattern, plastic deformation is dominant. Instead of intermolecular bonds breaking, slippage at the weaker sites between the molecules causes plastic deformation. While network polymers do not exhibit high deformation and are therefore brittle, linear polymers with crosslinking exhibit high levels of plastic deformation. The interactions between lamellar and intervening amorphous regions in response to an applied tensile force best reflect the mechanism of plastic deformation.

Polymer types

Plastics: These are organic materials that can be easily moulded or shaped through mechanical, chemical, or thermal action. It goes without saying that a plastic is a permanently moldable or deformable material.

This category includes the most varieties of polymeric materials perhaps. This group includes fluorocarbons, epoxies, phenolics, polyesters, polyethylene, polypropylene, polyvinyl chloride, polystyrene, and polyvinyl chloride. Plastics can have a wide range of different qualities together. While some plastics are flexible and deform both elastically and plastically in response to stress, other polymers are more rigid and brittle and occasionally experience enough deformation to shatter.

Any degree of crystallinity and any molecular configuration (such as linear, branching, isotactic, etc.) are feasible in polymers that belong to this family of materials. Thermoplastic and thermosetting are further classifications for plastic materials. The characteristics and typical applications for certain plastics are compiled. The following characteristics of plastic:

(i) Plastics have low specific gravities and densities, making them lightweight materials.

(ii) They exhibit remarkable resistance to corrosion-causing chemical attacks.

(iii) When made from dies, they have a particularly smooth surface finish.

(iv) They have excellent electrical and thermal insulation.

(v) They have lower strength and elastic modulus values compared to metals.

(vi) Plastic has a lower thermal deterioration and softening temperature than metals.

In especially when it's humid, plastics have mediocre to fair dimensional stability.

(ii) Elastomers: These substances resemble polymers in terms of their characteristics. These materials may be repeatedly stretched or elongated, and upon cessation of the force causing the elongation, they will revert to their initial state. Unlike polymers, which have more plastic properties, they behave in an elastic way. Rubber and compounds that resemble rubber fall under this category. There is a contrast between rubber and elastomers. Rubber must be able to elongate by 200% and quickly shrink back to its original size.

Resilience is the ability of a material to recover from elastic deformation. It lists a few popular elastomers' features and uses. A polymer must satisfy a number of requirements in order to be considered elastomeric: (i) It must crystallise easily. We may observe that elastomeric materials are amorphous and have naturally coiled and kinked molecular chains in their unstressed form. For coiled chains, chain bond rotations must be relatively free so that they can react quickly to an applied force. For elastomers, the start of the plastic deformation must be delayed in order to experience reasonably significant elastic deformations. This goal is accomplished by preventing chains from passing one another by crosslinking. Chain slippage is avoided thanks to the crosslinks, which serve as anchor points between the chains. Vulcanization, a method used to crosslink several elastomers, requires that they be above their glass transition temperature. An elastomer becomes brittle below its glass transition temperature. The lowest temperatures at which rubber like behaviour endures for a good number of typical elastomers are between -50 and -90°C.Common elastomers have characteristic qualities that depend on the degree of vulcanization and if reinforcement is applied, among other factors. Natural rubber still receives a lot of use and has an exceptional blend of desired qualities. The most significant synthetic elastomer, however, is SBR (styrene butadiene copolymer), which is used mostly in car tyres and reinforced with carbon black. Another typical synthetic elastomer that is extremely resilient to swelling and degradation is acrylonitrile butadiene copolymer (NBR).

Even vulcanised rubbers' mechanical qualities, such as tensile strength, abrasion and tear resistance, and stiffness, fall short in many applications, such as car tyres. By using chemicals like carbon black, one can enhance these qualities. Silicon rubbers are widely employed in many applications nowadays. In these substances, the backbone carbon chain is swapped out for a chain that alternates between silicon and oxygen atoms, where R and R stand for side-bonded atoms like hydrogen or groups of atoms, like CH3. Polydimethylsiloxane, for instance, has the mer structure shown. These compounds are definitely crosslinked and act as elastoners. The silicone elastomers have a high degree of elasticity at low temperatures (-90°C), but they are stable at temperatures as high as 250°C. They also withstand weathering and lubricating fluids. Some silicone rubbers (RTV rubbers) vulcanize at room temperature, which is a more desirable property.

CONCLUSION

Due to their wide range of qualities and uses, organic materials, particularly polymers and elastomers, are essential components in many different industries. We have investigated the chemical composition, mechanical properties, and thermal characteristics of these materials in our study. Large molecules consisting of repeating subunits are known as polymers, and their properties can be adjusted by changing their chemical make-up and molecular make-up. Polymers are useful for a wide range of applications due to their versatility. For instance, because of their light weight, flexibility, and barrier qualities, they are widely utilized in packaging materials like plastic films and bottles. Coatings, adhesives, and insulation materials made of polymers are used in the building sector. Polymers are essential for producing lightweight components, improving fuel economy, and lowering pollutants in the automotive industry.Numerous techniques, such as addition polymerization, condensation polymerization, and copolymerization, are used to create polymers and elastomers. While condensation polymerization includes the production of polymers through the removal of tiny molecules like water or alcohol, addition polymerization takes place when monomers react to form a polymer chain. In order to create polymers with specific properties, copolymerization mixes two or more distinct monomers.

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CHAPTER 8

EXPLORING THE FEATURES OF COMPOSITES: A COMPREHENSIVE REVIEW

Dr. Krishnappa Venkatesharaju, Assistant Professor, Department of Environmental Science And Engineering, Presidency University, Bangalore, India, Email Id-venkateshraju.k@presidencyuniversity.in

ABSTRACT

Materials called composites are made of two or more different components together to create a brand-new material with improved qualities. Due to their excellent strength, light weight, resistance to corrosion, and adaptability, they have attracted substantial interest and found use in a variety of industries. An overview of composites, their varieties, production methods, and major benefits is given in this abstract. It also demonstrates the variety of uses they have in fields including sports, construction, automobile, and aerospace. The abstract's conclusion highlights composites' enormous potential for improving technology and solving a variety of engineering problems.Composites are substances that mix two or more distinct components, each with a unique set of features, to produce a substance with improved performance qualities. This summary gives a general review of composites, emphasizing their composition, methods of manufacture, characteristics, and notable uses. Composites are made up of reinforcement materials that improve particular attributes like strength, stiffness, or durability as well as a matrix material that provides the structure and holds the components together. The reinforcement materials are often fibers, particles, or additives, whereas the matrix material can be a polymer, metal, ceramic, or a combination of these.

KEYWORDS

Composites, Concrete, Fibers, Materials, Matrix, Strength.

INTRODUCTION

Many current technologies, such as those used in the aircraft, submarine, and transportation industries, need for materials with uncommon combinations of attributes that cannot be provided by metals, typical metallic alloys, ceramics, or polymeric materials. engineers, for instance, in the aviation industryare constantly looking for structural materials that have low densities, are sturdy, stiff, resistant to abrasion and impact, and do not corrode readily. Clearly, this is a fairly potent confluence of qualities. Strong materials are often quite dense, and increasing their stiffness or strength typically causes them to lose some of their impact strength. As a result, in composites, the whole is more effective than the individual parts (synergy). Examples of natural composites, which are made when two materials unite to strengthen and bind together, include wood, celery, bamboo, and maize. Prior chapters covered composites of a certain type, including multiphase metal alloys, ceramics, and polymers. Any multiphase substance that demonstrates a sizable amount of the traits of its two constituent phases such that a better synergy of traits is realised is referred to as a composite. The term "principle of combined action" refers to this. This idea states that better combinations can be created by carefully combining two or more different elements.

In general, all composites share the same components: a matrix or binder and a reinforcing substance. A composite, obviously, comprises of a matrix substance that contains one or more phases of another material dispersed throughout it. The substance is referred to be an advanced composite if the fibres are continuously orientated in one direction. One excellent example of a composite material is reinforced concrete. When steel rebar is used to reinforce concrete, the reinforced concrete acts as a matrix around the rebar. Products made of reinforced fibre glass, like fishing poles, are another illustration. Glass fibres are fixed in a

matrix of thermosetting resin. This results in a fishing rod that is sturdy, light, and flexible. Aside from aramid (Kevlar and Nomex), boron, carbon, graphite, and ultrahigh-molecularweight polyethylene (spectra), other fibres can be made from these materials. These materials often have thermosetting epoxy resin as their matrix. When compared to steel, these materials' mechanical characteristics might sometimes improve three to six times. Steels made of pearlite are another type of composite material. Layers of -ferrite and cementite alternate in this material's microstructure. Cementite is hard and extremely brittle, whereas the ferrite phase is soft and ductile. When compared to either of the constituent phases, the total mechanical properties of this composite, or pearlite (relatively high ductility and strength), are superior. Combinations of fiber-resin, fiber-ceramic, carbon-metal, metal concrete, metal resin, and wood plastic are other popular types of composites. The majority of modern sophisticated composites are made from glass, kevlar (an aramid), or one of the different kinds of graphite fibers. An essential subgroup of this class of engineering materials is fiber composites. Evidently, a composite is a multiphase material that is manufactured purposely as opposed to one that naturally arises. In addition, the constituent phases of a composite must have unique interfaces and differ chemically. This is why many ceramics and the majority of metallic alloys do not suit this description because their various phases are a result of natural phenomena.

Making composites is done for a variety of purposes. For example, adding fibers to fragile ceramics results in a composite with increased toughness. Fillers, like the inclusion of aggregate in concrete, lower the product's overall cost while also enhancing compressive strength. Additionally, the second phase could be a gas, as in the production of low density foamed goods. Fibre reinforced composite materials may not be superior to metals of comparable strength on the basis of strength and stiffness alone, but when the specific modulus (i.e., modulus per unit weight) and specific strength are taken into account, their use implies that the weight of components can be decreased. This is a crucial element in all modes of transportation, as weight loss leads to greater energy savings.

Scientists and engineers have cleverly blended diverse metals, ceramics, and polymers while building composite materials in order to create a new generation of exceptional materials. Composite materials can be categorized using the straightforward system. Particle reinforced, fiber-reinforced, and structural composites are the three basic categories. We see that each primary division has at least two subdivisions. The dispersion phase for fiber-reinforced composites has the geometry of a fiber, whereas the dispersed phase for particle-reinforced composites is equi -axed (i.e., particle diameters are roughly the same in all directions). (i.e., a great ratio of length to diameter). Composites and homogeneous materials are combined to form structural composites. Examples of these three types of composites include plywood, which is made up of alternating layers of laminate veneers, fiber glass, which is a mixture of glass fibers embedded in a resin matrix, and concrete, which is a mixture of cement and aggregate[1].

General Characteristics

(i) In terms of specific strength and stiffness, high temperature strength, fatigue strength, and other qualities, composite materials outperform all other structural materials now in use. A certain material's manufacturing process can be customized in advance to achieve the appropriate mix of attributes. Furthermore, the material can be molded in this process to resemble the form of finished items or even structural components as closely as feasible.

(ii) Composite materials are complex materials whose constituent parts have defined borders, are mutually insoluble or only marginally soluble, and differ significantly from one another in terms of their properties.

(iii) The manufacturing process for composites is based on a natural process. Bones from humans and other animals, as well as plant branches and trunks, are examples of natural composites. Plastic lignin bonds the cellulose fibers in wood, while plastic collagen binds the phosphate fibers, which are strong and thin, in bones. The physico-mechanical characteristics of composites' components and the strength of the bonds holding them together determine most of their characteristics. The benefits of each component are completely utilized in composite materials, which is a distinguishing property of these materials. Composite materials might develop useful qualities that aren't present in the component parts. The components of composites are chosen to have very diverse but complementary qualities in order to achieve the best results. Composites' foundation, or matrix, can be made of ceramics, polymers, carbon, or metals or alloys (for non-metallic composites).

In composites, the matrix essentially serves as the binding and shaping element. Its features heavily influence the manufacturing processes for composite materials as well as key operating characteristics like working temperature, fatigue strength, environmental resistance, density, and specific strength. A mixed matrix found in some composites is made up of alternating layers (two or more) of various compositions. Multi-matrix or multi-layer composites are terms used to describe composites with mixed matrix. A larger range of practical characteristics can be used to describe multi-matrix composites. For instance, adding titanium to aluminum may improve a composite material's strength in directions perpendicular to the fibers. Aluminum layers in a matrix cause composite materials to become less dense. Fillers, or other components, are evenly dispersed throughout a matrix. These are known as "strengtheners" because they are helpful in the strengthening of composite materials. High values for strength, hardness, and elastic modulus should be included in fillers. These qualities ought to be noticeably better than those of the matrix. The equivalent qualities of a composite material likewise increase with an increase in the elastic modulus and ultimate strength of a filler, but not to the same extent as the filler. Another name for fillers is reinforcing components. This is a more general phrase than "strengthener," because it does not indicate the specific role of filler in strengthening, which may be utilised to enhance other aspects of a composite.

The form (geometry), size, concentration, and distribution of the filler (reinforcement pattern) can all affect a composite material's characteristics. Fillers are categorized into three primary classes based on their shape: zero-dimensional, one-dimensional, and two-dimensional. Composite materials are categorized into three types based on their reinforcement patterns: uniaxial, biaxial, and tri-axial reinforcement.Fillers of various shapes can be employed to increase a specific property of a composite material or to acquire a wider range of qualities. For instance, the addition of a zero-dimensional filler (particles of asbestos, silicon carbide, etc.) might strengthen the binding between one-dimensional filler elements (glass or carbon fibers) and a polymer matrix. Reinforcing a composite material using fillers of the same shape but different composition might serve the same goal. For instance, extra reinforcement with boron fibers can raise the elasticity modulus of composite materials having a polymer matrix reinforced by glass fibers[2]–[5].

DISCUSSION

Particles-Reinforced Composites

These can be further divided into two subgroups: (i) big particle composites, and (ii) composites reinforced by dispersion. The distinction between these is made depending on the mechanism for strengthening or reinforcing. The term "large" denotes the impossibility of treating particle-matrix interactions at the atomic or molecular level and instead calling for continuum mechanics. For the majority of these composites, the particulate phase is stiffer and harder than the matrix. These reinforcing particles have a tendency to impede the flow of

the matrix phase close to each particle. The particles, which carry a smaller portion of the load, are obviously subject to some stress transfer by the matrix. It's important to note that the strength of the bonding at the matrix-particle contact determines how much the mechanical behavior is reinforced or improved. Normal particle sizes for dispersion-strengthened composites range from 0.01 to 0.1 m in diameter. On the atomic or molecular level, particle-matrix interactions take place and result in strengthening. We can observe that the strengthening mechanism is comparable to the precipitation mechanism. The majority of the applied load is carried by the matrix, whereas the movement of the dislocations is hindered or impeded by the small distributed particles. It goes without saying that when plastic deformation is constrained, yield and tensile strengths as well as hardness increase.

Concrete

The matrix and disperse phases of this typical large-particle composite are made of ceramic materials.Concrete, in general, denotes a composite material made of an aggregate of particles that are joined in a solid body by a binding agent, such as cement. The two types of concrete with gravel and sand as the aggregate that are the most well-known are those created with portland and asphaltic cements. While portland cement concrete is widely employed as a structural building material, asphaltic cement is largely used as a paving material on a larger scale.

Portland Cement Concrete

A fine aggregate (sand), a coarse aggregate (gravel), and water are the components of portland cement concrete. Since aggregate particles are inexpensive and cement is more expensive, they serve as a filler material to lower the overall cost of concrete products. To acquire the best strength and workability of the concrete mixture, the materials must be added in the proper amounts. Having particles of two distinct sizes allows for dense packing of the aggregate and strong interfacial contact. The vacant spaces between the gravel particles should be filled with the tiny sand particles. These aggregates often make about 60% to 80% of the total volume. The cementitious bonding will not be complete if there is not enough cement-water paste to completely coat the sand and gravel particles. This is a crucial building material. Concrete made of portland cement can be poured into a desired location and will set up even when submerged in water and at room temperature. It is discovered to be exceedingly brittle and somewhat weak as a structural material, with a tensile strength that is roughly 10 to 15 times lower than its compressive strength. Large concrete structures can also experience significant thermal contraction and expansion with temperature changes. Water also enters external pores, which can result in severe cracking due to freeze-thaw cycles in colder climates[6]–[8].

Reinforced Concrete

By adding more reinforcement, portland cement concrete can be made stronger. This can be accomplished by embedding steel rods, wires, bars (rebar), or mesh into the freshly mixed, uncured concrete. The reinforcement makes the toughened structure capable of withstanding higher tensile, compressive, and shear loads, which is obvious. Even when cracks appear in the concrete, substantial reinforcing is kept in place. Steel is an appropriate reinforcement since its coefficient of thermal expansion is almost identical to that of concrete. Additionally, steel does not corrode quickly in a cement environment and forms a reasonably strong adhesive bond with the curved concrete. By incorporating curves onto the surface of the steel part, one can improve this adhesion. This enables a higher level of interconnecting.

Portland cement concrete can also be strengthened by adding high-modulus fibres, such as those made of glass, nylon, steel, and polyethylene, to freshly-mixed concrete. However, some fibre materials quickly deteriorate in a cement environment, thus caution must be used when utilizing this kind of reinforcement. There is still another method of concrete reinforcing. In order to accomplish this, residual compressive stresses must be applied to the structural part. Pre-stressed concrete is the resulting substance. This method makes use of the brittle ceramics' property that they are stronger in compression than in tension. It should go without saying that for a pre-stressed concrete member to fracture, the applied tensile stress must be greater than the pre-compressive stress's magnitude. In one pre-stressed method, high-strength steel wires are placed into the empty moulds and stretched with a high tensile strain that is kept constant. The strain is released when the concrete has been placed and has had time to set. Because the stress is transferred to the concrete through the wire-concrete bond that forms as the wires shrink, this puts the structure in a state of compression.

Posttensioning is another method that exists. In this method, stresses are added after the concrete has dried and hardened. The interior of the concrete forms, around which the concrete is cast, is lined with sheet metal or rubber tubes that run through them. After the cement has dried and become solid, the resulting holes are filled with steel wires, and tension is applied to the wires using jacks that are fastened to the faces of the building. Additionally, the jacks impose a compressive load on the concrete piece. Finally, a grout is used to fill the open spaces inside the tubing to prevent corrosion of the wire. It is important to remember that pre-stressed concrete is typically utilized for highway and railway bridges.

Dispersion- Strengthened Composite

Small particles or dispersions are present in this kind of composite, which strengthens it by preventing dislocations from moving. Typically, the dispersoid is a stable oxide of the parent substance. Sintered aluminum powder (SAP) is a typical illustration. Al2O3 (up to 14 percent) is present in the aluminum matrix of SAP. The powders are combined, crushed at high pressures, and sintered together to create this composite using the powder metallurgy method. Sintering is the process of heating a substance until the constituent particles come together. The majority of the time, only the edges of the particles are joined together; the entire particle does not melt. Sintered ceramics are a robust, stiff, brittle material that has high melting temperatures, good heat resistance, and good compressive strength. Ag-CdO, used as an electrical contact material, Pb-PbO, used in battery plates, and Be-BeO, utilised in nuclear reactor and aircraft components, are a few examples of dispersion-strengthened composites.Addition of roughly 3 volume percent of finely dispersed thoria (ThO2) can greatly improve the high-temperature strength of nickel alloy. The name of this substance is thoria-dispersed nickel (TD)[9], [10].

Fibre- Reinforced Composites

These are robust fibres that are incorporated into a softer matrix to create goods with excellent strength-to-weight ratios. The load is transferred to the fibres in the matrix material, which then absorbs the stress. The fibre-matrix link breaks at the fibre ends in response to applied stress, producing a matrix deformation pattern. Some critical fibre length is necessary for the composite material to be effectively strengthened and stiffened. This critical length lc is influenced by the fibre diameter d, its ultimate (or tensile) strength, and the bond strength between the fibres and the matrix, also known as the matrix's shear yield strength.For a variety of glass and carbon fiber-matrix combinations, the critical length, lc, is on the order of 1 mm and varies between 20 and 150 times the fibre diameter.

Clearly, the connection between the reinforcing fibres and the matrix is what gives these composites their strength. The aspect ratio, or length-to-diameter ratio, of the fibres used as reinforcement affects the composite's characteristics. The strength of the composite increases with aspect ratio. Therefore, for composite construction, long, continuous fibres are preferable than short ones. Continuous fibres, however, are more challenging to generate and

integrate into the matrix. Although they are simpler to insert into the matrix, shorter fibres provide inadequate reinforcing. When shorter, discontinuous fibres are employed with aspect ratios greater than a predetermined minimum value, there is some trade-off. The strength of the composite increases with the number of fibres. This is accurate up to around 80% of the composite's volume, after which the matrix can no longer entirely enclose the fibres. While fibres with lengths shorter than this are referred to as discontinuous, those with $l \gg lc$ (often l > 15 lc) are known as continuous fibres. A discontinuous fibre with a length smaller than lc causes the matrix to deform in such a way that there is almost no stress transmission and very little reinforcing from the fibre. These are essentially the already discussed particle composites. The fibres must be continuous in order to significantly increase the composite's strength.

Continuous and Aligned Fiber Composites

The stress-strain characteristics of the fibre and matrix phases, the phase volume fractions, and the direction of the applied stress or load all affect how this type of composite behaves mechanically. Additionally, the qualities of a composite with aligned fibres are highly anisotropic, meaning that they rely on the direction in which the property is measured. First, let's look at the scenario depicted in Fig. 1 (a), in which the stress is applied in the longitudinal direction, which is the direction of alignment.

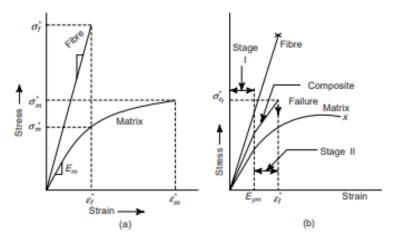


Fig. 1 (a) Stress-strain curve for brittle and ductile matrix materials. (b) Stress strain curve for an aligned fiber-reinforced composite.(newagepublishers.com)

Laminar Composites

Aligned layers that are attached together one on top of the other at different orientations are typically used when multidirectional stresses are produced inside a single plane. Laminar composites are what these are. The typical purpose of these is to offer great strength and low cost at a lighter weight.

Plywood is a well-known laminar composite in which the veneers are connected by adhesives, usually phenolic or amine resins. The odd number of individual piles are anchored so that each layer's grain runs perpendicular to the layers above and below it. This method provides plywood that is both sturdy and reasonably priced. Some safety glass has a laminated structure, which prevents flying glass when it breaks by sandwiching an adhesive like polyvinyl butyral between two outer layers of glass. Another popular laminate for countertops is Formica. The bonding of two or more layers is necessary for laminates. Additionally, fabric materials like cotton, paper, or woven glass fibers embedded in a plastic matrix may be used to create laminations. A laminar composite is obviously quite strong in a variety of directions in the two-dimensional plane.

Sandwich Structures

These have low density materials, or combcore, such as polymer foam or expanded metal structures, over thin layers of face materials. Corrugated cardboard is a well-known sandwich-structured composite material. Two faces of thin paper on the corrugated paper core are covered. This sort of structure's front material holds the inner core firmly in place. The power comes from the core. Aluminium alloys, fiber-reinforced polymers, titanium, steel, and plywood are examples of common face materials. The core has two structural functions: (i) it separates the faces and prevents deformations along to the face plane; and (ii) it offers a certain amount of sheer rigidity along planes parallel to the faces. For cores, materials and structures such as foamed polymers, synthetic rubbers, inorganic cements, balsa wood, etc. are employed. Lower strength and stiffness in the core. Another common core has a "honeycomb" structure, which is often used in sectors like the aircraft industry where greater strength and lighter weight are crucial considerations. Thin foils that have been shaped into interlocking hexagonal cells with an axis perpendicular to the face panels make up the honeycomb structure. The substance may resemble the material on the face. These structures can be filled to offer sound and vibration absorption, and they are low weight, stiff, and sturdy.

The Fiber Phase

The fact that a tiny diameter fibre is significantly stronger than the bulk material is one of the key properties of most materials, especially brittle ones. According to what we've read, as specimen volume decreases, the likelihood of a significant surface imperfection that can cause fracture decreases. The fiber-reinforced composites take advantage of this property of materials. Additionally, the substances employed to reinforce fibres have high tensile strengths. Based on their diameter and characteristics, fibres can be divided into three categories: whiskers, fibres, and wires. Due to how difficult and impracticable it is to insert whiskers into a matrix, and also due to how hardly used they are as a reinforcement medium. Aluminium oxide, silicon nitride, and graphite silicon carbide are a few materials used in whiskers.

The Matrix Phase

A fibrous composite's matrix phase could consist of a polymer, ceramic, or metal. Because a certain degree of ductility is preferred, metals and polymers are typically employed as matrix materials. The reinforcing element is added to ceramic-matrix composites to increase their fracture toughness. For fiber-reinforced composites, the matrix phase performs a number of tasks:

(i) It ties the fibres together and serves as a conduit for the distribution and transmission of an externally applied stress to the fibres. However, the matrix phase can only support a very small amount of the given load. Additionally, the matrix material must to be ductile. The fiber's elastic modulus should be significantly higher than the matrix's.

(ii) The matrix must guard against surface damage to the individual fibres brought on by mechanical abrasion or chemical reactions with the environment. These interactions could result in surface imperfections that could crack, which could induce failure at low tensile stress levels. Finally, the matrix divides the fibres and prevents the spread of brittle cracks from fibre to fibre, which might lead to catastrophic failure, because of its relative softness and plasticity. It goes without saying that matrix phase acts as a stopgap for crack growth.

It is conceivable for some of the individual fibres to fail, but total composite fracture won't happen until a critical number of nearby fibres cluster together after one of them fails. It is crucial that the adhesive bonding forces between the fibre and matrix be strong in order to reduce fibre pull-out. In actuality, bonding strength has a significant role in the selection of

the matrix-fibre combination. The strength of the composite as a whole greatly depends on the strength of this link. Adequate bonding is crucial to maximizing the stress transmission from the weak matrix to the strong fibres.

Poly-matrix Composites

These materials are made of fibres as the reinforcement medium and a polymer resin (here defined as a high-molecular weight reinforcing plastic) as the matrix. These PMCs are employed in the widest range of composite applications and in significant quantities due to their room-temperature characteristics, simplicity of production, and low cost. Following are numerous classifications of PMCs according to the type of reinforcement (glass, carbon, or aramid), as well as their uses and the various polymer resins that are employed:

Composites made of Glass Fibre Reinforced Polymer (GFRP) Glass fibres, which may be continuous or irregular, are the main component of the composite known as fibreglass, which is composed of a polymer matrix. As 'E' glass, which stands for electrical, draws well and has good strength and rigidity, it is frequently used to create them. Molten glass is gravity fed into a series of platinum bushings, each of which contains hundreds of holes in its base and has a typical composition (Wt %) of 52SiO2, 17CaO, 14Al2O3, and 10Ba2O3. As the glass leaks from the holes, fine glass filaments are mechanically pulled and coiled onto drums at speeds of several thousand meters per minute. The surface damage caused by the glass fibres rubbing against one another during processing determines how strong the fibres will be. Because 'Griffith' cracks are less likely to occur when a size coating is applied early in the manufacturing process, this property degradation is minimized. The size, which is a polymer emulsion in water, serves to bind the fibres together for ease of processing as well.

Composites made of carbon fiber-reinforced polymers: These are made up of tiny graphite crystallites (for information on crystal structure, see chapter 3). Weak Vander Waals forces exist between the layers and very strong covalent bonds hold the atoms in the basal planes together. The layer planes of graphite must be parallel to the axis of the fibre in order to achieve high modulus and high strength, and the degree of perfection of atom plane alignment determines the modulus of carbon fibres. This varies significantly depending on the specific production method used; there are three primary options:

Polymer PAN (polyacrylonitride), which shares many molecular similarities with polyethylene, is first transformed into a fibre and then stretched to cause alignment of the molecular chains along the fibre axis. White is heated in oxygen to create cross-links between ladder molecules while it is still under tension. After that, it is chemically reduced to produce (at very high temperatures) a graphic structure. The maximum stiffness but relatively low strength of the fibres (Type-I fibres) or the maximum strength (Type-II fibres) are determined by the ultimate graphitisation temperature. Another method for creating fibres is by spinning molten pitch. The opening causes the planar molecules to line up as they are spinning. It is then processed at temperatures up to 2000 C to create the necessary grains of graphite while being held under stress to preserve its preferred orientation.During the graphitization stage, it is also feasible to stretch either of the aforementioned fibre types, further ensuring that the layers are oriented parallel to the fibre axis.Of all reinforcing fibre materials, carbon fibres have the highest specific strength and specific modulus.

At high temperatures, carbon fibres maintain their high tensile modulus and great strength. High temperature oxidation, however, can be an issue. At room temperature, carbon fibres are unaffected by moisture, a wide range of solvents, acids, or bases. Because carbon fibres have a variety of physical and mechanical properties, composite materials made with them can have unique technical qualities.Carbon fibres can be divided into four groups based on their tensile modulus: standard, moderate, high, and ultrahigh. The typical range for fibre sizes is 4 to 10 m. There are accessible versions of these fibres in both continuous and

chopped forms. Additionally, a protective epoxy coating that is often applied to carbon fibres enhances adherence with the polymer matrix.Fishing rods, golf clubs, filament-wound rocket engine cases, pressure vessels, and structural parts of fixed-wing and rotary-wing aircraft are just a few examples of the numerous applications for carbon-reinforced polymer composites in sports and recreation equipment.

Aramid Fiber- Reinforced Polymer Composites

High-strength, high-modulus materials like aramid fibres are particularly desired because of their better strength-to-weight ratios than those of metals. This class of polymers is known chemically as poly paraphenyleneterephthalamide. Many different aramid materials exist. Kevlar and Nomex are trade names for two of these most used materials. Kevlar comes in a number of grades (namely Kevlar 29, 49, and 149) with various mechanical properties. These fibres exhibit longitudinal tensile strengths and tensile moduli that are higher than those of other polymeric fibre materials yet they compress rather poorly. Additionally, this substance is renowned for its resilience to impacts, toughness, and resistance to fatigue and creep failure. Aramids are thermoplastics, however despite this, they are combustibleresistant and stable at relatively high temperatures. The temperature range between -200 and 200°C is where aramids maintain their outstanding mechanical characteristics. Strong acids and bases can degrade aramides, but they are generally inert in other solvents and chemicals. Usually, composites with polymer matrix use aramid fibres. Epoxies and polyesters are frequently used as matrix materials. Fibres made of aramid are slightly flexible and relatively flexible. In addition to replacing asbestos in automobile brake and clutch linings and gaskets, aramid composites are also utilised in sporting goods, tyres, ropes, missle cases, pressure levels, and ballistic items (bullet-proof vests).

CONCLUSION

By providing a special mix of qualities that go beyond those of individual materials, composites have revolutionised the world of materials research and engineering. Composites have been carefully crafted to satisfy specific performance criteria by the careful selection and arrangement of ingredients, making them highly adaptable in a variety of applications. The excellent strength-to-weight ratio of composites is one of their key benefits. Composites can achieve extraordinary structural integrity while being lightweight by fusing lightweight matrix with materials with high strength fibres, like carbon or glass.

Composites are incredibly important in sectors like aerospace and automotive where weight reduction is crucial. Additionally, composites have exceptional corrosion resistance, resulting in long-term dependability and durability. In tough locations like chemical processing machinery and marine constructions, this quality has found applications.Depending on the required qualities and the kinds of materials used, different composites are manufactured using different techniques. Lay-up, where layers of reinforcement materials are stacked and impregnated with the matrix material, filament winding, where fibers are wound onto a mandrel and impregnated with resin, and injection molding are common techniques.

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CHAPTER 9

APPLICATIONS OF AN OVERVIEW OF THE NANOSTRUCTURED MATERIALS

Ms. Meenakshi Jhanwar, Assistant Professor, Department of Environmental Science, Presidency University, Bangalore, India, Email Id-meenakshi@presidencyuniversity.in

ABSTRACT

Nano-materials are a subclass of materials that typically have unique properties between 1 and 100 nanometers in size. Due to their high surface area-to-volume ratio and quantum confinement effects, nanostructured materials differ from their bulk counterparts in terms of their physical, chemical, mechanical, and optical characteristics. An overview of nanostructured materials, their methods of synthesis, and important characteristics are given in this abstract. Their numerous uses in industries including electronics, electricity, medicine, and environmental cleanup are also highlighted. In highlighting the revolutionary potential of nanostructured materials in advancing technology and addressing societal concerns, the abstract comes to a close. A class of materials known as nanostructured materials has distinct characteristics and tiny structures. This abstract gives a general review of nanostructured materials, emphasizing their properties, production processes, and key applications. Due to their high surface-to-volume ratio and nanoscale dimensions, nanostructured materials display unique features. These materials have structural elements such thin films, nanowires, nanotubes, and nanoparticles, which typically have sizes between 1 and 100 nanometers.

KEYWORDS

Atoms, Carbon, Graphite, Materials, Nanotubes, Structure.

INTRODUCTION

A new field of study in physics, chemistry, and material science has emerged as a result of the discovery of fullerenes and carbon nanotubes. Materials that contain clusters, crystallites, or molecules with diameters between 1 and 100 nm are said to be nanostructured materials. Nanoclusters are groups of atoms that are typically hundreds to thousands in size and are measured in nanometers (nm). Generally speaking, these compact collections of atoms are referred to as nanoparticles, nanocrystals, quantum dots, and quantum boxes. Over the past ten years, significant research has been done in the fields of nanostructured materials and nanotubes.

The remarkable changes in fundamental electrical, optical, and magnetic properties that take place as one moves from a "infinitely extended" solid to a material particle made up of a countable number of atoms are what have caused the explosion in academic and industrial interest in these nanomaterials over the past ten years. Nanostructured materials have produced novel basic scientific phenomena and a number of short-, medium-, and long-term applications. Examples include, but are not limited to, nanoelectronic components, quantum wires, electron field emitters for ultra-thin TV screens, nanoprobes, high resolution tips for scanning and atomic force microscopes, sensors, ultrahigh strength composites, gas storage, nanodevices, and components of nanomachines. Fullerenes and other carbon-based nanomaterials and nanostructures, such as nanotubes, are becoming more and more common in nanoscale research and technology.In order to fully explore the enormous potential of carbon nanotubes for several applications in nanoelectronics, as actuators and sensors, researchers are now studying them to better understand their new structural, electrical, and mechanical properties. Carbon nanotubes and fullerenes resemble curved graphite particles. Another polymorph of carbon is graphite[1]–[4].

Graphite

In addition to being more stable than diamond at room temperature and pressure, graphite has a crystal structure that is distinctly different from that of diamond. Carbon atoms are arranged in flat hexagonal layers and spaced 3.35 apart to produce graphite. The structure's C-C distance is 1.42 and its lattice constants, a = 2.46 and c = 6.71, place it in the P 63 mc space groups. Graphite is a highly anisotropic solid with an inter-planer spacing (3.35) that is significantly larger than the in-plane interatomic spacing (1.42) fundamentally. Physically, it is quite stiff along the plane due to strong bonding, while Vander Waal's force causes it to be weak in the other direction. The layers of hexagonally organized carbon atoms that make up the graphite structure are held together by strong covalent interactions between each carbon atom and its three coplanar neighbor atoms. When carbon is sp2 hybridized, it forms three strong bonds that are aligned in a triangle with a bond angle of 120° and one weak bond that runs perpendicular to the plane. A continuous sheet of carbon is created when each carbon atom in the plane establishes a covalent bond with three other carbon atoms in the plane through the strong bonds of sp2 hybridization. A weak Vander Waals type of bond exists between the layers, in which the fourth bonding electron takes part.

These inter-planar connections are weak, which makes inter-planar cleavage easy and contributes to the remarkable lubricative characteristics of graphite. Additionally, in crystallographic orientations parallel to the hexagonal sheets, the electrical conductivity is relatively high. Graphite is semiconducting perpendicular to the plane and metallic conductivity along the plane. Conductivity has an anisotropy of around 10³. High strength and good chemical stability at high temperatures and in non-oxidizing atmospheres, high thermal conductivity, a low coefficient of thermal expansion and a high resistance to thermal shock, high gas absorption, and good machinability are additional qualities of graphite that are desirable. Graphite is frequently used in electrical furnace heating elements, AC welding electrodes, metallurgical crucibles, ceramic and metal alloy casting moulds, high temperature refractories and insulations, rocket nozzles, chemical reactor vessels, electrical contacts, brushes and resistors, battery electrodes and air purification equipment[5]–[7].

Other layered materials can also take on curvature in order to produce new nanomaterials with inventive applications. The nonosized powders of silicon, silicon-nitride (SiN), and silicon carbide (SiC), as well as their thin films, are further forms of nanostructured materials that have been taken into consideration for use in optoelectronic devices and quantum-optic devices. Because of how certain of these nanomaterials, like SiC and SiN, become stronger and tougher as the grain size decreases, they are also used as sophisticated ceramics with controlled microstructures.Fig. 1 depicts structure of graphite.

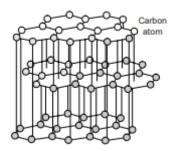


Fig.1 Depicts structure of Graphite(newagepublishers.com)

Fullerenes

Due to the existence of pentagonal rings in the hexagonal graphite sheet in the case of fullerenes, the graphite gains curvature. The discrete molecular form of fullerenes is represented by the symbol C60 and consists of a hollow, spherical cluster of sixty carbon

atoms. Each molecule is made up of clusters of carbon atoms that are linked together to form geometric shapes called hexagons (which contain six carbon atoms) and pentagons (which contain five carbon atoms). One such molecule is discovered to be made up of 12 pentagons and 20 hexagons, which are arranged so that no two pentagons share a common side, giving the molecular surface a soccer ball-like symmetry. A molecule known as buckminsterfullerene, which has sixty carbon atoms arranged in a network of sp2 bonds to form a spherical structure, is said to be almost "custom built for nanoscience" from a variety of angles.

The fullerene cage diameter is 0.71 nm, and the intermolecular space in fullerite, the bulk crystal, is 1.004 nm. C60, discovered in 1985 by Kroto et al., is approximately 1 nm in diameter. It is of crucial importance because its physical and chemical properties can be tuned by adding a variety of elemental and molecular species to the fullerene lattice, to the fullerene cage, or within the cage. The category of materials made of this kind of molecule is referred to as fullerene. An Indian football-like arrangement of hexagonal and pentagonal carbon rings makes up fullerenes.

We currently discover the existence of fullerenes (C60), C36, C70, C80, C100, as well as a small number of members of the geometrically allowed fullerene family. The quantity of hexagonal rings in these fullerene molecules varies. As the quantity of carbon atoms varies, the structure of this molecule changes. The C70 resembles a rugby ball, while the C120 assumes the form of a dumbbell. The carbon atoms in diamond and graphite all make primary bonds with nearby atoms over the entirety of the solids, making them what are known as network solids. The most popular way to produce synthetic graphite is in composite forms. In this method, coal tar pitch and petroleum coke are blended into a paste that is heated to a temperature between 120 and 1400 degrees Celsius. This process removes all volatile components from the petroleum coke. This mixture graphitizes into a totally graphitic structure when heated further to temperatures between 2500 and 3000 °C.

Because it is now possible to make C60 molecules in huge quantities, research into this type of carbon is progressing in all areas. In contrast, the carbon atoms in buckminsterfullerene combine to create these spherical molecules by a strong covalent connection. The C60 units pack together in a face-centered cubic array in the solid state and take the form of a crystalline structure. The carbon atoms in diamond and graphite all make primary bonds with nearby atoms over the entirety of the solids, making them what are known as network solids. The most popular way to produce synthetic graphite is in composite forms. In this method, coal tar pitch and petroleum coke are blended into a paste that is heated to a temperature between 120 and 1400 degrees Celsius. This process removes all volatile components from the petroleum coke. This mixture graphitizes into a totally graphitic structure when heated further to temperatures between 2500 and 3000 °C. Because it is now possible to make C60 molecules in huge quantities, research into this type of carbon is progressing in all areas. In contrast, the carbon atoms in buckminsterfullerene combine to create these spherical molecules by a strong covalent connection. The C60 units pack together in a face-centered cubic array in the solid state and take the form of a crystalline structure[8]–[10].

DISCUSSION

Carbon Nanotubes

Recent research has revealed yet another molecular form of carbon with intriguing and technologically interesting characteristics. The production of carbon nanotubes was initially reported by Ijiyama of NEC Japan in 1991. Along with the shot particles gathered in his tests on the arc discharge between graphite electrodes, there were some fine tube-like structures. They are carbon nanotubes (CNTs), according to a rigorous study. Its structure is made up of a single sheet of graphite that has been wrapped into a tube and has C60 fullerene

hemispheres on both ends. The tubes' ends can be left open or capped with a half-spheroidal fullerene at either one or both ends. The diameter and helical structure of a nanotube are totally determined by what is known as a roll up vector. A nanotube can have metallic or semiconducting properties depending on its roll-up vector.

Carbon Nanocones

Graphitic cones were expected to form, according to theoretical studies. Later, carbon condensation on a graphite substrate and the pyrolysis of heavy oils were used to create isolated graphitic cones. Laser ablation of graphite targets has more recently been used to create single walled aggregates of conical graphitic structures. Additionally, by reacting boron oxide vapors with multi-walled CNTs, conical structures made of other layered materials, such as BN, have also been created. The pyrolysis of palladium precursors is said to always result in conical nano-fibers, according to recent reports. Since the fiber is made up of a stack of cones that can be opened (like a lamp shade) or closed (like a shade), this novel type of nanostructure is distinguished by the fact that Vander Waals forces hold it together. Anocones may be effective electron field emitters, according to theory. According to calculations of the electrical characteristics of nanocones, there is a charge accumulation towards the tip and localized states close to the Fermi level. These characteristics make them appropriate as field emitters.

Haeckelites

The electrical characteristics of fullerenes are altered by defects like pentagons and heptagons. Graphene sheets of a novel hypothetical form that permit pentagons, heptagons, and hexagons have been proposed. It is noted that the number of heptagons and pentagons should be equal in order to account for the negative curvature of heptagons and the positive curvature of pentagons. Haeckelites is the term used to describe these arrangements. At the Fermi level in the local density of states, they all show a sizable signal.

It should go without saying that all of these systems exhibit metallic behaviour. It is therefore feasible to roll up haeckelites to create nanotubes, which will be conductors regardless of the diameter and helical configuration. Another characteristic of haeckelite tubes is that they retain the rigidity of conventional graphite nanotubes made just of hexagons; the Young's modulus of haeckelite tubes is close to 1.0 Tera Pa, which is on par with conventional carbon nanotubes. Due to the local bending caused by heptagons and pentagons, Haeckelites also show local rugosity. The production of heptagon-pentagon pairs (rugosity) in SWCNT by electron irradiation experiments is conceivable.

Production methods for CNTS

Four alternative processes can be used to produce CNTs: (i) arc discharge (ii) pyrolysis (iii) laser vaporisation and (iv)electrolysis. In Fig.2, the electric arc discharge setup is depicted. With two key exceptions, this approach is quite similar to the one used to produce fullerenes: first, the pressure is higher here—around 500 torr—whereas for fullerenes, it is closer to 100 torr; second, the nanotubes are found deposited in the cathode rather than the soot. Well-ordered MWCNT with sizes ranging from 2 nm to 30 nm are produced using this technique. Around 3.4, which is quite near to graphite's 3.35 and corresponds to turbostratric graphite, is the distance between graphite layers. These nanotubes can reach lengths of up to 30. The use of currents creates the ideal conditions for producing nanotubes with this technique. With this technique, the best circumstances for producing nanotubes include employing currents of 150 amps, voltages of 25 volts, and graphite electrodes with diameters between 6 and 8 mm and a distance between them of 1 mm while in a helium atmosphere. Controlling the formation process is exceedingly challenging because the electric arc reaction is excessively violent.

The pyrolysis process involves heating a hydrocarbon or a carbon-containing precursor in the presence of a catalyst made of iron, nickel, or cobalt. It was generally known that carbon fibres could be produced using pyrolytic techniques and hydrocarbons before the discovery of C60. Because of their larger width and numerous flaws and impurities, carbon fibres must be distinguished from nanotubes. However, carbon fibres are used extensively and exhibit strength on par with steel.Fig. 2 shows pyrolysis set-up.

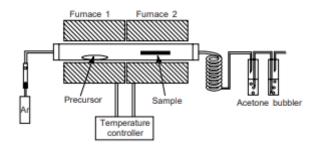


Fig. 2 Shows pyrolysis set-up.(newagepublishers.com)

Ajayan et al. discovered in 1994 that aligning carbon nanotubes in a polymer allowed for the creation of a composite material. When the polymer was cut, scientists noticed nanotubes arranged in a straight line. In this situation, laser ablation of cobalt thin films followed by pyrolysis with an organic precursor such 2-amino 4, 6-dichloro-S-tryazine is a preferable choice. The resulting nanotubes have sizes between 30 nm and 50 nm and are arranged in bundles that can grow up to 40 nm in diameter.

The laser vaporization technique includes directing a powerful laser beam at a target made of graphite within a furnace heated to 1200° C. The production of the nanotubes is caused by the condensation of material produced by the laser. Single-walled carbon nanotubes (SWCNT) are produced when nickel or cobalt are added to a graphite target. The SWCNT exhibit diameters about 14 and a lattice constant of 17, creating a two-dimensional crystal. SWCNT arrangements can also be created using electric arc discharge with carbon, nickel, and ytrium combinations. Utilizing graphite electrodes in a molten salt, such as lithium chloride (700°C) while in an argon environment is the basis of the electrolysis method. Nanotube content ranges from 20% to 30%, depending on the situation. When creating nanotubes, the cathode depth and current (3–10 amps) are crucial factors.

Boron Nitride Curved Nanostructures (BNNTs)

Another layered substance is hexagonal boron nitride (h-BN), which has a structure very similar to graphite with hexagonal ring layers spaced apart by 3.33. In this compound, every boron is bonded to three nitrogen atoms and vice versa, and the B-N distance is 1.44. Every boron between the layers engages in a Vander Waal's force interaction with a nitrogen atom. In terms of its electronic characteristics, h-BN has a band gap of 5.8 eV, making it an insulator, whereas graphite has a band overlap of 0.04 eV, making it a semi-metal. The first BN nanotubes were created utilizing an electric arc discharge with BN powder inside the anode and electrodes made of high melting point metals (such as tantalum and tungsten, for example). Loiseau et al. reported in 1996 that HfB2 electrodes working in an inert atmosphere might produce BN nanotubes. This method mostly produced single- and double-walled BN tubes.

According to a report, BN nanotubes' tips are squared, which suggests that the structure is made up of squares of BN rather than pentagonal rings to close it. This makes sense because a pentagon will have unstable B-B or N-N bonds, which will change the relative amounts of B and N. Therefore, squares should be present in BN cages. In terms of curvature, BN admits squares for positive curvature and octagons for negative curvature with good stability.

Calculations of functionally tight binding reveal that nitrogen excess cages containing B and N are stable. According to theoretical research, BNNTs are semiconductors with a band gap of 5.5 eV, which is less than that of bulk BN. This characteristic of BNNTs is unaffected by the chirality, number of walls, or tube diameter. These BNNTs should have high Young's moduli and could be very resistant to oxidation. As a result, ceramics may benefit greatly from the application of BNNTs.

Carbon nanotubes exposed to a mixture of B2O3, V2O5, and M0O3 in a nitrogen atmosphere at high temperatures can also form BNNT bundles. Other methods for producing BNNTs and other BN nanostructures include (a) thermolysis of borozine (B3N6H6) over nickel boride catalyst particles at 1000–1100°C, (b) thermal annealing of powdered boron and h-BN mixtures at 1200°C in lithium vapour, (c) plasma jets, and (d) ball milling of h-BN followed by thermal annealing at 1300°C.

It is currently necessary to create innovative composites and nanoscale components using BNNTs, which seem to be particularly resistant to oxidation. The Young's modulus of BNNTs measured experimentally (Y or $E = 1.22 \ 0.24 \ TPa$) matches well with the values calculated theoretically, indicating that BN tubes are extremely crystalline and may be the strongest insulating nanofibres. New opportunities for innovative nanomaterials of the kind BxCyNz have been made possible by graphite and h-BN. Melamine pyrolysis tests have proven to be particularly beneficial in the creation of CxNynanofibres.

By using an electric arc discharge with h-BN inside the graphite anode, boric acid doped carbon nanotubes have been produced. Carbon nanotubes are found to be extremely long (around 20) and highly graphitic during this experiment. It was discovered that zig-zag chirality was favoured and that B was situated near the tips of the nanotubes. According to calculations made from scratch, boron was preventing the closure of the zigzag tubes by acting as a surfactant. Boron-doped nanotubes can also have conducting qualities. According to reports, nitrogen doped carbon nanotubes can also display intriguing characteristics like piridine-like bonding in the graphitic mesh, which results in an LDOS peak that is rather near to the Fermi level. The zig-zag, armchair, and all of these nanotubes are discovered to be conductors. To promote conductivity, nitrogen is undoubtedly providing electrons to the nanotube structure.

Mechanical and Electronic Properties of Carbon Nanotubes

CNTs are remarkably flexible, as demonstrated by high resolution transmission electron microscopy (HRTEM). For instance, they can be mechanically bent using a polymeric resin, an ultrasonic bath, or mechanical machining. This flexibility is predicted by theoretical simulations. When Treacy et al. employed HRTEM to detect the amplitudes of the vibrating tubes in order to indirectly calculate the Young's modulus, that was the first attempt to estimate the stiffness of carbon nanotubes. They discovered that MWCNTs have a higher Young's modulus than ordinary carbon fibres (Ca 800 Giga Pa), of the order of 1.8 Tera Pa (1 Tera Pa = 1 1012 Pascals). The Young's modulus of MWCNTs was directly measured using atomic force microscopy (AFM), and it is around 1.28 Tera Pa. Due to their robust structure, nanotubes have a high Young's modulus. Building a nanotube-based super-strong material is still a difficult task.

The resistance varies with temperature, and the tubes were semi-metallic between 2 K and 300 K, according to the first tests of the electrical conductivity of CNTs utilizing gold micro contacts affixed to the CNTs by lithographic processes. Measurements of the conductivity of aligned MWCNTs demonstrate the material's behaviour as a nanoconductor. Additionally, it has been established that carbon nanotubes can function as semiconductors or conductors depending on their diameter and helicity. SWCNTs with a diameter of 14 show quantum conductivity. We should be aware that the geometry of the structure—the atomic

arrangement—determines the mechanical and electrical properties of CNTs. Nanocrystals have been created in modern times We should remark that SWCNT can coalesce at high temperatures (about 800 °C) and high electron irradiation levels. Tight binding simulations indicate that the vacancies produced by electron knock-on are what initiate the coalescence. Additionally, for coalescence to occur, the tubes must have the same chirality; otherwise, tube polymerization may occur.

Nanostructures in Motion

A new "micro-revolution" is being ushered in by micromechanics, micro-machines, and moving nanostructures. However, the ideas behind silicon micromachining and micromechanics are not new. For both internal industrial use and the open market, a range of commercial devices, including accelerometers, pressure transducers, thermal print heads, and ink jet nozzle arrays, have been created. Micro-meters, movable linkages, gears, microturbines, electrical motors, and micro-weezers have all been added to the ever-expanding collection of micromechanical devices since 1982, significantly broadening the subject of micromechanics.

Nanomaterial Advantage

Three-dimensional solids known as nanocrystalline materials are made up of crystallites with a size of less than a nanometer. These materials have extraordinary fundamental properties that could be used to create "next-generation" superstrong materials because of their distinctive structure, which is characterised by ultrafine grains and a relatively high density of crystal lattice defects. The fundamental mechanical characteristics of any material are strength and ductility. The physical characteristics of plastic deformation, which in typical, coarse-grained metals is mostly carried by dislocations-line faults of regular crystal lattice—within individual grains, determines their characteristics. However, research suggests that the mechanism of plastic deformation in nano-crystalline materials may be distinct, which might result in novel mechanical features.Numerous nanoparticles have already been found to have high strength or hardness. However, these nanomaterials often have very low ductility, failing when their shape is altered. Some even become brittle in the presence of a force or deforming stress. The relationship between strength and ductility is typically antagonistic: the stronger the strength, the lower the ductility, and vice versa. This association is related to the nature of plasticity: any crystalline substance is stronger but brittle and less ductile the harder it is for dislocations to develop and move.

It is reported their accomplishment in creating a novel nanocrystalline material that combines strength and ductility, two useful qualities that are sometimes mutually exclusive. By rolling the metal at a temperature below 77 K and then heating it to about 450 K, they produced a copper nanostructure. The end result was a "bimodel" structure with micrometer-sized grains embedded within a matrix of nanocrystalline grains (at a volume fraction of about 25%). Despite exhibiting extraordinarily high ductility, the material kept its high strength. The cause of this phenomenon appears to be that while the nano-crystalline grains offer strength, the bigger grains incorporated into the material stabilize its tensile deformation.

Enhancing the strength and ductility of nanoparticles can increase their fatigue resistance. Fatigue is the main factor now limiting the lifespan and, consequently, the variety of uses of many modern materials.Nanomaterials offer several advantages that make them highly attractive in various fields of science and technology. Here are some key advantages of nanomaterials:

Enhanced Properties: Nanomaterials exhibit unique properties compared to their bulk counterparts due to their nanoscale dimensions. These properties include increased surface area, quantum confinement effects, improved mechanical strength, enhanced electrical and

thermal conductivity, and exceptional optical properties. These enhanced properties enable the development of advanced materials with superior performance in applications such as electronics, energy storage, catalysis, and biomedical devices.

Customizability: Nanomaterials can be precisely engineered and tailored to achieve desired properties and functionalities. The size, shape, composition, and surface characteristics of nanomaterials can be controlled during synthesis, allowing for the design of materials with specific properties for targeted applications. This customizability enables researchers and engineers to optimize performance, efficiency, and compatibility in a wide range of applications.

Increased Surface Area: Nanomaterials possess a large surface area-to-volume ratio due to their small size and high surface-to-volume ratio. This high surface area allows for greater interaction with surrounding environments, facilitating improved reactivity, efficient catalytic activity, enhanced adsorption capacity, and better sensing capabilities. Nanomaterials with high surface area are particularly valuable in applications such as catalysts, sensors, and drug delivery systems.

Improved Strength and Durability: Nanostructured materials often exhibit superior mechanical properties, including increased strength, hardness, and toughness. The small grain sizes and unique crystalline structures at the nanoscale contribute to these improved mechanical characteristics. This advantage has significant implications for applications that require lightweight and high-strength materials, such as aerospace, automotive, and structural engineering.

Versatility and Multifunctionality: Nanomaterials can serve multiple functions simultaneously. They can be engineered to possess specific properties, such as electrical conductivity, magnetism, and luminescence, allowing for their integration into multifunctional devices and systems. This versatility enables the development of compact, efficient, and integrated technologies in various fields, including electronics, photonics, and biotechnology.

Energy Efficiency: Nanomaterials have the potential to enhance energy efficiency in various applications. For example, nanomaterials can improve the performance of energy storage devices, such as batteries and supercapacitors, by increasing charge storage capacity and reducing charging time. They can also enhance the efficiency of energy conversion devices, such as solar cells and fuel cells, by optimizing light absorption and electron transfer processes.

Environmental Benefits: Nanomaterials can contribute to environmental sustainability. They can enable the development of more efficient pollution control systems, water purification technologies, and environmental remediation strategies. Additionally, nanomaterials can be utilized in lightweight materials for transportation, reducing fuel consumption and emissions.

CONCLUSION

By providing unheard-of control over a material's properties at the nano-scale, nanostructured materials have revolutionized the field of materials research. The structure, content, and morphology of nanostructured materials can be precisely engineered to produce specific and enhanced qualities that enable a diverse variety of applications. The high surface area-to-volume ratio of nanostructured materials is one of their distinguishing features. The higher reactivity made possible by the greater surface area makes them particularly well suited for use in sensors, energy storage devices, and catalysis. Additionally, quantum confinement phenomena in nanostructured materials cause their electrical and optical characteristics to become size-dependent. Applications for this feature can be found in fields including solar energy harvesting, electronics, and photonics. Since the manufacturing of nanostructured

materials has advanced dramatically, it is now possible to precisely control their size, content, and shape. The manufacture of nanostructured materials with certain desired qualities has been made easier by methods including template-assisted synthesis, chemical vapor deposition, and sol-gel processes. Several techniques, including top-down and bottom-up ones, are used to create nanostructured materials. Top-down approaches use lithography, etching, and milling processes to carefully reduce bulk materials to the nanoscale. On the other hand, bottom-up approaches utilize molecular-level manipulation, chemical synthesis, and self-assembly to assemble and produce nanoscale parts, such as nanoparticles.

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CHAPTER 10

APPLICATIONS OF AN ELABORATION OF MECHANICAL PROPERTIES OF METALS

Dr. Krishnappa Venkatesharaju, Assistant Professor, Department of Environmental Science And Engineering, Presidency University, Bangalore, India, Email Id-venkateshraju.k@presidencyuniversity.in

ABSTRACT

The mechanical properties of metals play a key role in evaluating their applicability for various technical applications. This study attempts to investigate and analyze the mechanical properties of metals, including their strength, elasticity, plasticity, toughness, and hardness. Through experimental testing and analysis of numerous metallic samples, this research analyses the relationship between these attributes and the underlying microstructural characteristics of metals. Additionally, the effects of alloying elements, heat treatment, and other factors on the mechanical behavior of metals are explored. The findings of this study add to a better knowledge of the mechanical properties of metals and provide useful insights for material selection and design in engineering applications. Understanding and forecasting how metals will behave under various loading conditions depends on their mechanical characteristics. The mechanical characteristics of metals, such as their strength, ductility, toughness, hardness, and fatigue resistance, are elaborated upon in this abstract. A metal's strength, a fundamental mechanical characteristic, determines how well it can sustain external stresses without permanently deforming or failing. The yield strength, tensile strength, and compressive strength of a metal are frequently used to measure its strength. Tensile strength is the highest stress a material can endure before breaking, while yield strength represents the stress at which a material starts to show plastic deformation. The ability of a substance to withstand being compressed or squeezed is known as its compressive strength.

KEYWORDS

Atoms, Carbon, Graphite, Materials, Nanotubes, Structure.

INTRODUCTION

When in use, many materials are subjected to stresses or forces; two examples are the steel in an automotive axle and the aluminium alloy used to make an aeroplane wing. In these circumstances, it is essential to understand the material's properties and design the member from which it is constructed so that any ensuing deformation won't be severe and fracture won't take place. A material's response or deformation in relation to an applied load or force is reflected in its mechanical behaviour. Strength, ductility, toughness, hardness, and stiffness are important mechanical design characteristics. By conducting meticulously planned laboratory experiments that as closely as possible mimic the service conditions, the mechanical characteristics of materials are determined. The type and duration of the imposed load, as well as the environmental circumstances, are factors that need to be taken into account. The load may be tensile, compressive, or shear, and its magnitude may remain constant throughout time or continuously fluctuate. The length of the application process might range from a few hundredths of a second to many years. The temperature of the service could be crucial. Many parties with various interests are interested in mechanical properties, including material producers and consumers, research organisations, and government authorities. As a result, it is critical that there be some consistency in both the execution of tests and the interpretation of their outcomes. By adopting standardised testing methods, this uniformity is achieved. Professional associations sometimes coordinate the creation and publishing of these standards. The American Society for Testing and Materials (ASTM) is the

most active organisation in the United States. Numerous volumes of the Annual Book of ASTM Standards (http://www.astm.org) are published and updated each year; a significant portion of these standards deal with mechanical testing methods. In this chapter and following chapters, a number of these are mentioned in the footnotes. Determine stresses and stress distributions inside members that are subjected to well-defined loads is the responsibility of structural engineers. This can be achieved through theoretical and mathematical stress calculations, as well as experimental testing methods. Traditional texts on stress analysis and material strength include these subjects. However, the focus of materials and metallurgical engineers is on manufacturing and developing materials that will meet service requirements that are projected by these stress studies. Understanding the connections between materials' internal features, or microstructure, and their mechanical properties is a prerequisite for doing this. Materials with suitable combinations of mechanical properties are typically used for structural purposes. The current topic is mostly focused on the mechanical behavior of metals; polymers and ceramics are discussed separately because of how mechanically unlike they are to metals. This chapter looks at other significant mechanical qualities as well as the stress-strain behavior of metals and the associated mechanical properties[1]–[3].

Concept of stress and strain

A straightforward stress-strain test, which is most frequently performed for metals at room temperature, can determine the mechanical behavior of a member if a load is static or varies relatively slowly over time and is applied uniformly over a cross section or surface of a member.

Stress-strain behavior

The amount of induced stress determines how much a structure will bend or strain. Stress and strain are proportional to one another for the majority of metals that are stressed in tension and at relatively modest levels because to the relationship between

This is known as Hooke's law, and the Young's modulus, or the modulus of elasticity, is the constant of proportionality E (GPa or psi)⁶. The value of this modulus varies between 45 G Pa $(6.5*10^6 \text{ psi})$ for magnesium and 407 G Pa $(59*10^6 \text{ psi})$ for tungsten for the majority of common metals. The slope of this linear segment corresponds to the modulus of elasticity E. This modulus may be thought of as stiffness, or a material's resistance to elastic deformation. The larger the modulus, the stiffer the material, or the lower the elastic strain that arises from the application of a given stress. The modulus is a significant design parameter for computing elastic deflections. Elastic deformation is nonpermanent, which implies that when the applied force is released, the item returns to its original shape.

Application of the load corresponds to travelling from the origin up and along the straight line. Upon release of the load, the line is travelled in the opposite direction, back to the origin. There are several materials (i.e., gray cast iron, concrete, and many polymers) for which this elastic component of the stress-strain curve is not linear; consequently, it is not possible to derive a modulus of elasticity as discussed previously. For this nonlinear behavior, either the tangent or secant modulus is generally utilized. The tangent modulus is considered as the slope of the stress-strain curve at some specified level of stress, whereas the secant modulus is the slope of a secant drawn from the origin to some given point of the σ - ε curve.On an atomic scale, macroscopic elastic strain is represented as tiny changes in the interatomic spacing and the stretching of interatomic bonds.

As a consequence, the size of the modulus of elasticity is a measure of the resistance to separation of nearby atoms, that is, the interatomic bonding forces.

Anelasticity

To this point, it has been assumed that elastic deformation is time independent—that is, that an applied stress causes an instantaneous elastic strain that remains constant across the period of time the stress is sustained. It has also been assumed that upon release of the load, the strain is entirely recovered—that is, that the strain instantaneously returns to zero. In most engineering materials, however, there will also exist a time-dependent elastic strain component—that is, elastic deformation will continue after the stress application, and upon load reduction, some limited time is necessary for complete recovery. This time-dependent elastic behavior is known as anelasticity, and it is owing to time-dependent microscopic and atomistic processes that are attendant to the deformation. For metals, the anelastic component is generally modest and is often overlooked[4]–[7].

DISCUSSION

Elastic Properties of Materials

When a tensile tension is imposed on a metal specimen, an elastic elongation and corresponding strain εz result in the direction of the applied stress (arbitrarily considered to be the z direction), .As a result of this elongation, there will be constrictions in the lateral (x and y) directions perpendicular to the applied force; from these contractions, the compressive strains εx and εy may be derived. If the applied stress is uniaxial (just in the z direction) and the material is isotropic, then $\varepsilon x = \varepsilon y$. A parameter termed Poisson's ratio v is defined as the ratio of the lateral and axial strains.For practically all structural materials, εx and εz will be of opposite sign; hence, the negative sign is added in the above expression to ensure that v is positive.7 Theoretically, Poisson's ratio for isotropic materials should be 1 4; furthermore, the highest value for v (or the value for which there is no net volume change) is 0.50.

E = 2G (1+v)

Plastic Deformation

For most metallic materials, elastic deformation persists only to stresses of around 0.005. As the material is distorted beyond this point, the stress is no longer proportional to strain (Hooke's equation, Equation 6.5, ceases to be valid), and permanent, non-recoverable, or plastic deformation occurs. The change from elastic to plastic is a gradual one for most metals; some curvature results at the outset of plastic deformation, which rises more rapidly with growing stress. From an atomic perspective, plastic deformation corresponds to the breaking of bonds with original atom neighbors and then the re-forming of bonds with new neighbors as large numbers of atoms or molecules move relative to one another; upon removal of the stress, they do not return to their original positions. The mechanism of this deformation is different for crystalline and amorphous materials. For crystalline solids, deformation is performed by means of a process termed slip.

Tensile Strength

Yielding and Yield Strength

Most constructions are intended to ensure that only elastic deformation will arise when a stress is applied. A structure or component that has plastically deformed—or experienced a permanent change in shape—may not be capable of functioning as planned. It is consequently desirable to know the stress level at which plastic deformation begins, or where the phenomena of yielding occurs. For metals that experience this gradual elastic–plastic transition, the point of yielding may be determined as the initial departure from linearity of the stress–strain curve; this is sometimes called the proportional limit, as indicated by point P, and represents the onset of plastic deformation on a microscopic level. The position of this

point P is difficult to measure exactly. As a consequence, a protocol has been formed by which a straight line is constructed parallel to the elastic component of the stress-strain curve at some predetermined strain offset, usually 0.002. The stress corresponding to the intersection of this line and the stress-strain curve when it bends over in the plastic area is defined as the yield strength $\sigma y.8$ The units of yield strength are MPa or psi.9 For materials containing a nonlinear elastic region, use of the strain offset approach is not possible, and the normal practice is to define the yield strength as the stress required to create some amount of strain (e.g., $\varepsilon = 0.005$). The elastic-plastic transition is very clearly defined and occurs abruptly in what is considered a yield point phenomena. At the top yield point, plastic deformation is commenced with an apparent drop in engineering stress. Continued deformation fluctuates slightly about some fixed stress value, termed the lower yield point; stress then rises with increasing strain. For metals that demonstrate this effect, the yield strength is considered as the average stress that is associated with the lower yield point since it is well defined and largely insensitive to the testing process.10 Thus, it is not required to utilize the strain offset approach for these materials. The magnitude of the yield strength for a metal is a measure of its resistance to plastic deformation. Yield strengths may range from 35 MPa (5000 psi) for a low-strength aluminum to greater than 1400 MPa (200,000 psi) for high-strength steels.

Ductility

Ductility is another significant mechanical feature. It is a measure of the degree of plastic distortion that has been sustained upon fracture. A metal that undergoes very little or no plastic deformation upon fracture is termed brittle.Ductility may be quantified quantitatively as either percent extension or percent reduction in area. Percent elongation (%EL) is the percentage of plastic strain at fracture, or

%EL = l_f - l_o/ l_o*100

Where l_f is the fracture length¹² and l_0 is the original gauge length as described earlier. Inasmuch as a considerable amount of the plastic deformation upon fracture is restricted to the neck area, the magnitude of %EL will depend on specimen gauge length. The shorter l0, the bigger the fraction of total elongation from the neck and, thus, the higher the value of %EL.

Resilience

Resilience is the capacity of a material to absorb energy when it is deformed elastically and then, upon unloading, to have this energy returned. The linked parameter is the modulus of resilience, Ur, which is the strain energy per unit volume necessary to stress a material from an unloaded condition up to the point of yielding. The units of resilience are the product of the units from each of the two axes of the stress–strain diagram. For SI units, this is joules per cubic meter (J/m3, equivalent to Pa), whereas with customary U.S. systems, it is inch-pounds force per cubic inch (in.-lb_f/in.³, equivalent to psi). Both joules and inch-pounds force are units of energy, and hence this area under the stress–strain curve indicates energy absorption per unit volume (in cubic meters or cubic inches) of material.

$$U_r = \frac{1}{2} σ €$$

Toughness

Toughness is a mechanical term that may be applied in numerous settings. For one, toughness (or more specifically, fracture toughness) is a quality that is indicative of a material's resistance to fracture when a crack (or other stress-concentrating defect) is present. Because it

is nearly difficult (as well as costly) to make materials with zero faults (or to prevent damage during service), fracture toughness is a major consideration for all structural materials. Another way of describing toughness is as the ability of a substance to absorb energy and plastically deform before fracture. For dynamic (high strain rate) loading conditions and when a notch (or point of stress concentration) is present, notch toughness is measured by using an impact test

True stress and strain

This is not at all the case; as a matter of fact, it is gaining in strength. However, the crosssectional area is decreasing fast within the neck region, where deformation is occurring. This leads in a reduction in the load-bearing capability of the specimen. The stress, as derived on the basis of the original cross-sectional area before any deformation and does not take into account this drop in area at the neck. Sometimes it is more meaningful to utilize a genuine stress-true strain strategy. True stress σT is defined as the load F divided by the instantaneous cross-sectional area Ai across which deformation is occurring (i.e., the neck, past the tensile point), or

$\sigma_{\rm T}$ = F/ A_T

Compressive, Shear and Torsional Deformations

Of course, metals may experience plastic deformation under the impact of applied compressive, shear, and torsional pressures. The ensuing stress–strain behavior into the plastic zone is identical to the tensile equivalent. However, for compression, there is no limit since necking does not occur; furthermore, the mode of fracture is different from that for tension.

Hardness

Another mechanical feature that may be significant to consider is hardness, which is a measure of a material's resistance to localized plastic deformation (e.g., a small dent or a scratch). Early hardness tests were based on natural minerals with a scale created simply on the ability of one material to scratch another that was softer.

A qualitative and somewhat arbitrary hardness indexing technique was established, named the Mohs scale, which varied from 1 on the soft end for talc to 10 for diamond.

Quantitative hardness techniques have been developed over the years in which a small indenter is driven into the surface of a material to be examined under controlled parameters of stress and rate of application. The depth or size of the resulting indentation is measured and connected to a hardness number; the softer the material, the greater and deeper the depression, and the lower the hardness index number. Measured hardnesses are only relative (rather than absolute), therefore caution should be given when comparing values produced by different procedures[8]–[11].

Hardness tests are performed more frequently than any other mechanical test for numerous reasons:

1. They are easy and economical—typically, no particular specimen should be produced, and the testing apparatus is relatively inexpensive.

2. The test is nondestructive—the specimen is neither shattered nor unduly deformed; a slight indentation is the only deformation.

3. Other mechanical parameters often may be approximated from hardness data, such as tensile strength.

Rockwell Hardness Tests

The Rockwell tests are the most common method used to determine hardness because they are so simple to execute and require no particular abilities. Several alternative scales may be employed from conceivable combinations of various indenters and varied loads, a process that permits the testing of practically all metal alloys (as well as some polymers).

Indenters include spherical and hardened steel balls having diameters of 1/16, 1/8, 1/4, and 1/2 in. (1.588, 3.175, 6.350, and 12.70 mm, respectively), as well as a conical diamond (Brale) indenter, which is used for the hardest materials.

With this system, a hardness number is established by the difference in depth of penetration resulting from the application of an initial minor load followed by a greater major load; employment of a minor load boosts test accuracy. On the basis of the magnitude of both main and minor loads, there are two types of tests: Rockwell and superficial Rockwell. For the Rockwell test, the minor load is 10 kg, whereas significant loads are 60, 100, and 150 kg. Each scale is represented by a letter of the alphabet; several are listed with the matching indenter and load. For superficial tests, 3 kg is the minor load; 15, 30, and 45 kg are the probable major load values. These scales are recognized by a 15, 30, or 45 (according to load), followed by N, T, W, X, or Y, depending on the indenter. Superficial examinations are routinely done on thin specimens.

When describing Rockwell and superficial hardness's, both hardness number and scale symbol must be specified. The scale is represented by the symbol HR followed by the relevant scale designation.14 For example, 80 HRB signifies a Rockwell hardness of 80 on the B scale, while 60 HR30W implies a surface hardness of 60 on the 30W scale. For each scale, hardness's may range up to 130; however, if hardness values reach above 100 or drop below 20 on any scale, they become inaccurate; because the scales have some overlap, in such a case it is advisable to utilize the next-harder or next-softer scale.

Inaccuracies also result if the test specimen is too thin, if an indentation is produced too near a specimen edge, or if two indentations are made too close to one another. Specimen thickness should be at least 10 times the indentation depth, whilst allowance should be given for at least three indentation diameters between the center of one indentation and the specimen edge, or to the center of a second indentation. Furthermore, testing of specimens piled one on top of another is not suggested. Also, accuracy is contingent on the indentation being produced into a smooth flat surface. The latest apparatus for making Rockwell hardness measurements is automated and very simple to operate; hardness is read directly, and each measurement requires just a few seconds. This device also offers a modification in the timing of load application. This variable must also be addressed in analyzing hardness data.

Brinell Hardness Tests

In Brinell testing, like in Rockwell measures, a hard, spherical indenter is driven into the surface of the metal to be tested. The diameter of the hardened steel (or tungsten carbide) indenter is 10.00 mm (0.394 in.). Standard loads range between 500 and 3000 kg in 500-kg increments; during a test, the load is held constant for a set time (between 10 and 30 s). Harder materials demand bigger applied loads. The Brinell hardness number, HB, is a function of both the magnitude of the load and the diameter of the resulting indentation. This diameter is measured with a special lowpower microscope using a scale that is inscribed on the eyepiece. The measured diameter is then translated to the appropriate HB number using a chart; just one scale is employed with this procedure.Semiautomatic procedures for measuring Brinell hardness are available. These employ optical scanning devices consisting of a digital camera attached on a flexible probe, which allows positioning of the camera over

the depression. Data from the camera are sent to a computer that analyzes the indentation, determines its size, and then calculates the Brinell hardness value. For this technique, surface finish standards are generally stricter than those for manual measurements. Maximum specimen thickness and indentation position (relative to specimen edges) as well as minimum indentation spacing parameters are the same as for Rockwell tests. In addition, a well-defined indentation is necessary; this needs a smooth, flat surface in which the depression is produced.

CONCLUSION

This study has provided vital insights into the mechanical characteristics of metals. Through experimental testing and analysis, it was revealed that the mechanical properties of metals are greatly impacted by their microstructural characteristics. Grain size, crystal structure, and the presence of impurities or flaws all contribute to the overall strength, elasticity, plasticity, toughness, and hardness of metals. Alloying elements can enhance certain attributes, such as boosting strength or improving corrosion resistance, depending on the intended application. Heat treatment procedures, including annealing, quenching, and tempering, have been discovered to considerably impact the mechanical characteristics of metals. These processes can modify the microstructure of metals, resulting in changes in their mechanical behavior. For example, quenching from high temperatures can generate a harder and more brittle material, whereas tempering can increase toughness and reduce brittleness. The link between the mechanical characteristics of metals and diverse. Understanding this link is critical for material selection and design in engineering applications. By choosing the appropriate metal with the specified mechanical properties, engineers may ensure the structural integrity and performance of components and structures.

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CHAPTER 11

EXPLORATION OF THE FAILURE ANALYSIS IN MATERIAL SCIENCE

Ms. Meenakshi Jhanwar, Assistant Professor, Department of Environmental Science, Presidency University, Bangalore, India, Email Id-meenakshi@presidencyuniversity.in

ABSTRACT

Failure analysis in material science is a crucial discipline that tries to understand the causes and mechanisms behind material failures. This study analyses the many forms of failure modes observed in materials, such as fracture, fatigue, creep, and corrosion. Through detailed investigation and examination of failed materials, this research tries to discover the underlying reasons that contribute to failure, including material faults, ambient conditions, loading circumstances, and design errors. By acquiring insights into failure mechanisms, this study gives significant knowledge for optimizing material selection, design, and maintenance strategies to better the reliability and durability of engineering components and structures.In order to comprehend and avoid the failure of materials and structures, failure analysis is a crucial component of materials science and engineering. The failure process is examined in this abstract, along with its causes, mechanisms, and analytical techniques. Failure is the failure of a substance or a construction to carry out its intended purpose under predetermined circumstances. It may happen as a result of a number of things, such as mechanical overloading, environmental deterioration, manufacturing errors, flawed designs, and incorrect maintenance. Failure can have serious repercussions, including life loss, property destruction, and monetary losses.

KEYWORDS

Brittle, Ductile, Failure, Fracture, Stress, Temperature, Transition.

INTRODUCTION

The breakdown of engineering materials is virtually always an undesired event for various reasons; they include placing human lives at peril, causing economic losses, and interfering with the availability of products and services. Even though the causes of failure and the behavior of materials may be recognized, prevention of failures is impossible to ensure. The usual causes are faulty materials selection and processing and inadequate design of the component or its usage. Also, deterioration can occur to structural parts during use, and regular inspection and repair or replacement are crucial to safe design. It is the role of the engineer to foresee and plan for possible failure and, in the event that failure does occur, to identify its cause and then take necessary preventive steps against future events. The following subjects are treated in this chapter: simple fracture (including ductile and brittle modes), fundamentals of fracture mechanics, fracture toughness testing, the ductile-to-brittle transition, fatigue, and creep. These discussions include failure mechanisms, testing procedures, and methods through which failure may be prevented or controlled.

Fundamentals of fracture

Simple fracture is the separation of a body into two or more parts in response to an imposed stress that is static (i.e., constant or slowly changing with time) and at temperatures that are low relative to the melting point of the material. Fracture can also arise from fatigue (when cyclic loads are produced) and creep (time-dependent deformation, normally at increased temperatures); the concepts of fatigue and creep are treated later in this chapter. Although applied stresses may be tensile, compressive, shear, or torsional (or mixtures of these), the

present study will be focused to fractures that originate from uniaxial tensile loads. For metals, two fracture modes are possible: ductile and brittle. Classification is based on the ability of a material to experience plastic deformation. Ductile metals often exhibit extensive plastic deformation with high energy absorption before fracture. However, there is generally little or no plastic deformation with poor energy absorption accompanying a brittle fracture.

Ductile and brittle are relative concepts; whether a specific fracture is one mode or the other depends on the situation. Ductility may be evaluated in terms of percent elongation and percent reduction in area. Furthermore, ductility is a function of temperature of the material, the strain rate, and the stress state.

Any fracture process involves two steps—crack creation and propagation—in response to an imparted stress. The mode of fracture is greatly reliant on the mechanism of crack propagation. Ductile fracture is characterized by substantial plastic deformation in the region of a developing crack. The process proceeds rather slowly as the fracture length is enlarged. Such a crack is generally said to be stable—that is, it resists any further extension unless there is an increase in the applied stress. In addition, there typically is evidence of considerable gross deformation at the fracture surfaces (e.g., twisting and ripping).

However, for brittle fracture, cracks may spread extraordinarily rapidly, with very little accompanying plastic deformation[1], [2]. Such fractures may be said to be unstable, and crack propagation, once started, proceeds spontaneously without an increase in magnitude of the applied stress. Ductile fracture is nearly always preferred to brittle fracture for two reasons:

First, brittle fracture occurs suddenly and catastrophically without any warning; this is a consequence of the spontaneous and rapid crack propagation. By contrast, in ductile fracture, the presence of plastic deformation gives notice that failure is near, allowing preventive actions to be implemented. Second, more strain energy is required to induce ductile fracture inasmuch as these materials are often tougher. Under the action of an applied tensile stress, many metal alloys are ductile, whereas ceramics are typically brittle, and polymers may display a range of behaviors.

Ductile Fracture

Ductile fracture surfaces contain specific properties on both macroscopic and microscopic levels. The configuration is seen for particularly soft metals, such as pure gold and lead at ambient temperature, and other metals, polymers, and inorganic glasses at elevated temperatures. These extremely ductile materials neck down to a point fracture, indicating practically 100% loss in area. The most typical type of tensile fracture profile for ductile metals is that represented, when fracture is preceded by only a minor amount of necking.

The fracture process generally happens in multiple stages. First, once necking begins, small cavities, or micro-voids, form in the interior of the cross section, as indicated. Next, as deformation proceeds, these micro-voids increase, join together, and combine to produce an oval fracture, which has its long axis perpendicular to the stress direction. The fracture continues to expand in a direction parallel to its primary axis by this micro-void coalescence process.

Finally, fracture ensues by the rapid propagation of a crack across the outside perimeter of the neck by shear deformation at an angle of about 45° with the tensile axis—the angle at which the shear stress is a maximum. Sometimes a fracture possessing this unique surface contour is named a cup-and-cone fracture because one of the mating surfaces is in the form of a cup and the other like a cone. In this sort of broken specimen the central inner portion of the surface has an uneven and fibrous appearance, which is indicative of plastic deformation.

Fractographic Studies

Much more extensive information regarding the mechanism of fracture is accessible from microscopic analysis, generally utilizing scanning electron microscopy. Studies of this type are termed fractographic. The scanning electron microscope is favored for fractographic exams because it has a significantly better resolution and depth of field than does the optical microscope; these characteristics are necessary to disclose the topographical aspects of fracture surfaces. When the fibrous core section of a cup-and-cone fracture surface is viewed with the electron microscope at a high magnification, it is observed to consist of numerous spherical "dimples" this structure is diagnostic of fracture resulting from uniaxial tensile failure. Each dimple represents one half of a micro void that formed and subsequently separated during the fracturing process. Dimples also appear on the 45° shear lip of the cup-and-cone fracture. However, these will be elongated or C-shaped. This parabolic shape may be symptomatic of shear failure. Furthermore, various tiny fracture surface features are also possible[3], [4].

DISCUSSION

Brittle Fracture

Brittle fracture takes place without any perceptible deformation and by fast crack propagation. The direction of crack motion is very nearly perpendicular to the direction of the applied tensile stress and gives a reasonably flat fracture surface. Fracture surfaces of materials that fracture in a brittle way have characteristic patterns; any traces of extensive plastic deformation are absent. For example, in some steel components, a series of V-shaped "chevron" markings may emerge towards the center of the fracture cross section that point back toward the crack start site. Other brittle fracture surfaces have lines or ridges that radiate from the beginning of the crack in a fanlike pattern. Often, both of these marking patterns are sufficiently coarse to be recognized with the naked eye. For exceptionally hard and finegrained metals, there is no apparent fracture pattern. Brittle fracture of amorphous materials, such as ceramic glasses, provides a comparatively glossy and smooth surface. For most brittle crystalline materials, crack propagation corresponds to the consecutive and repetitive breaking of atomic bonds along certain crystallographic planes such a process is termed cleavage. This form of fracture is known to be trans-granular (or trans crystalline) because the fracture cracks pass through the grains. Macroscopically, the fracture surface may have a grainy or faceted appearance as a result of changes in orientation of the cleavage planes from grain to grain. This cleavage characteristic is exhibited at a higher magnification in the scanning electron micrograph [5], [6].

Principle of Fracture Mechanics

Brittle fracture of typically ductile materials, such as that depicted in the chapter-opening has revealed the need for a greater knowledge of the mechanisms of fracture. Extensive research endeavors throughout the past century have led to the advancement of the area of fracture mechanics. This subject permit measurement of the relationships among material qualities, stress level, the presence of fracture-producing flaws, and crack propagation mechanisms. Design engineers are now more positioned to anticipate, and so prevent, structural breakdowns. The present talk emphasizes on some of the fundamental principles of the mechanics of fracture.

Stress Concentration

The reported fracture strengths for most materials are much lower than those predicted by theoretical predictions based on atomic bonding energies. This discrepancy is explained by the occurrence of microscopic faults or cracks that always exist under normal conditions at the surface and within the interior of a body of material. These flaws are a hindrance to the

fracture strength because an applied stress may be magnified or concentrated at the tip, the extent of this amplification depends on crack orientation and geometry. This phenomenon is depicted in a stress profile across a cross section with an interior crack. As illustrated by this graph, the magnitude of this localized stress diminishes with distance away from the crack point. At positions far removed, the stress is only the nominal stress σ_0 , or the applied load divided by the specimen cross-sectional area (perpendicular to this load). Because of their tendency to amplify an applied stress in their locale, these faults are frequently called stress raisers.

Fracture Toughness Testing

A variety of different standardized tests have been devised to measure the fracture toughness values for structural materials. In the United States, these standard test methods are created by the ASTM. Procedures and specimen setups for most tests are relatively complicated, and we will not attempt to provide thorough explanations. In brief, for each test type, the specimen (of defined geometry and size) contains a preexisting fault, usually a sharp crack that has been introduced. The test apparatus loads the specimen at a preset rate, and also measures load and crack displacement values. Data are subjected to analysis to ensure that they meet established standards before the fracture toughness levels are considered acceptable. Most tests are for metals, although some have also been designed for ceramics, polymers, and composite[6], [7].

Impact Testing Techniques

Prior to the introduction of fracture mechanics as a scientific study, impact testing techniques were devised to identify the fracture characteristics of materials at high loading rates. It was realized that the results of laboratory tensile tests (at low loading rates) could not be extrapolated to predict fracture behavior. For example, under particular situations, typically ductile metals shatter abruptly and with very little plastic deformation under high loading rates. Impact test conditions were chosen to represent those most severe relative to the potential for fracturenamely, (1) deformation at a relatively low temperature, (2) a high strain rate (i.e., rate of deformation), and (3) a tri-axial stress state (which may be introduced by the presence of a notch).

Two standardized tests, the Charpy and the Izod, are used to quantify the impact energy (often also termed notch toughness).

The Charpy V-notch (CVN) technique is most widely employed in the United States. For both the Charpy and the Izod, the specimen is in the shape of a bar of square cross section, into which a V-notch is machined. The load is applied as an impact blow from a weighted pendulum hammer discharged from a cocked position at a fixed height h. The specimen is positioned at the base as illustrated. Upon release, a knife edge attached on the pendulum impacts and fractures the specimen at the notch, which acts as a location of stress concentration for this high-velocity impact blow. The pendulum continues its swing, increasing to a maximum height h', which is lower than h.

The energy absorption, estimated from the difference between h and h', is a measure of the impact energy. The fundamental distinction between the Charpy and the Izod techniques resides in the mode of specimen support. These are termed impact tests because of the technique of load application. Several variables, including specimen size and form as well as notch configuration and depth, influence the test findings.

Both plane strain fracture toughness and these impact tests have been used to determine the fracture characteristics of materials. The former are quantitative in nature, in that a specific attribute of the material is determined (i.e., KIc).

The results of the impact tests, however, are more qualitative and are of little utility for design purposes. Impact energies are of importance mainly in a relative sense and for establishing comparisonsabsolute values are of little significance. Attempts have been attempted to connect plane strain fracture tough nesses and CVN energies, with only little success. Plane strain fracture toughness tests are not as straightforward to execute as impact testing; also, equipment and specimens are more expensive.

Ductile to Brittle Transition

One of the fundamental goals of the Charpy and the Izod tests is to identify whether a material suffers a ductile-to-brittle transition with decreasing temperature and, if so, the range of temperatures across which it occurs. As may be noticed in the chapter opening photograph of the cracked oil tanker for this chapter, extensively used steels can display this ductile-to-brittle transition with fatal effects. The ductile-to-brittle transition is connected to the temperature dependence of the measured impact energy absorption. At higher temperatures, the CVN energy is relatively large, leading to a ductile mode of fracture. As the temperature is dropped, the impact energy declines quickly over a very limited temperature range, below which the energy has a constant but small value—that is, the mode of fracture is brittle.

Alternatively, appearance of the failure surface is indicative of the form of fracture and may be used in transition temperature estimations. For ductile fracture, this surface appears fibrous or dull (or of shear character), as in the steel specimen, which was tested at 79°C. Conversely, completely brittle surfaces have a granular (shiny) texture (or cleavage feature)

Over the ductile-to-brittle transition, features of both types will occur, displayed by specimens tested at -12°C, 4°C, 16°C, and 24°C). For many alloys there is a range of temperatures across which the ductile-to-brittle transition occurs; this poses some difficulties in selecting a single ductileto-brittle transition temperature. No precise criterion has been established, and hence this temperature is frequently characterized as the temperature at which the CVN energy acquires some value (e.g., 20 J or 15 ft-lbf), or matching to some particular fracture appearance (e.g., 50% fibrous fracture). Matters are further complicated by the fact that a distinct transition temperature may be realized for each of these conditions. Perhaps the most conservative transition temperature is that at which the fracture surface becomes 100% fibrous; on this basis, the transition temperature is roughly 110°C (230°F) for the steel alloy. Structures manufactured from alloys that display this ductile-to-brittle characteristic should be used only at temperatures above the transition temperature to avoid brittle and catastrophic collapse. Classic examples of this type of failure were explored in the case study contained in Chapter 1. During World War II, a number of welded cargo ships away from combat abruptly split in half. The vessels were constructed of a steel alloy that possessed appropriate toughness according to room-temperature tensile tests. The brittle cracks occurred at relatively low ambient temperatures, at roughly 4°C (40°F), in the proximity of the transition temperature of the alloy. Each fracture crack originated at some location of stress concentration, possibly a sharp corner or fabrication flaw, and then travelled throughout the whole circumference of the ship[8]-[10].

In addition to the ductile-to-brittle transition, two other general forms of impact energyversus-temperature behavior have been observed; these are represented schematically by the upper and lower curves. Here it may be noticed that low-strength FCC metals (certain aluminum and copper alloys) and most HCP metals do not experience a ductile-to-brittle transition and retain high impact energies (i.e., remain tough) with decreasing temperature. For high-strength materials (e.g., high-strength steels and titanium alloys), the impact energy is similarly highly insensitive to temperature however, these materials are also very brittle, as shown by their low impact energies. The characteristic ductile-to-brittle transition is depicted by the middle curve. As indicated, this phenomenon is generally encountered in low-strength steels that contain the BCC crystal structure. For these low-strength steels, the transition temperature is sensitive to both alloy composition and microstructure. For example, decreasing the average grain size results in a lowering of the transition temperature. Hence, refining the grain size both strengthens and toughens steels. In contrast, increasing the carbon content, although it increases the strength of steels, also boosts their CVN transition.

Most ceramics and polymers also experience a ductile-to-brittle transition. For ceramic materials, the transition occurs only at elevated temperatures, generally in excess of 1000°C (1850°F).Fatigue is a form of failure that happens in structures subjected to dynamic and variable stresses (e.g., bridges, aircraft, machine components). Under these circumstances, it is possible for failure to occur at a stress level substantially lower than the tensile or yield strength for a static load. The term fatigue is chosen because this sort of breakdown generally occurs after a lengthy period of recurrent stress or strain cycling. Fatigue is essential inasmuch as it is the single main cause of failure in metals, believed to be involved in approximately 90% of all metallic failures; polymers and ceramics (save for glasses) are also prone to this form of failure. Furthermore, weariness is devastating and insidious, hitting very suddenly and without warning. Fatigue failure is brittle-like in nature even in ordinarily ductile metals in that there is very little, if any, extensive plastic deformation associated with failure. The process happens by the start and propagation of cracks, and normally the fracture surface is perpendicular to the direction of an applied tensile stress.

The S-N Curve

As with other mechanical qualities, the fatigue properties of materials can be determined using laboratory simulation testing. A test instrument should be constructed to reproduce as nearly as feasible the service stress circumstances (stress intensity, time frequency, stress pattern, etc.). The most typical type of test conducted in a laboratory setting involves a rotating– bending beam: alternating tension and compression stresses of equal magnitude are imposed on the specimen as it is simultaneously bent and turned. In this scenario, the stress cycle is reversed—that is, R = -1. Furthermore, predicted in-service conditions may necessitate for undertaking simulated laboratory fatigue tests that use either uniaxial tension– compression or torsional stress cycling instead of rotating–bending.

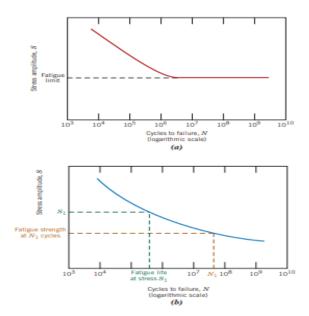


Fig. 1 Stress amplitude (S) versus logarithm of the number of cycles to fatigue failure (N) for (a) a material that displays a fatigue limit and (b) a material that does not display a fatigue limit.(www.wileyplus.com)

A series of tests is began by subjecting a specimen to stress cycling at a reasonably significant maximum stress (σ max), usually on the order of two-thirds of the static tensile strength; number of cycles to failure is tallied and recorded. This method is repeated on different specimens at progressively decreasing maximum stress values. Data are plotted as stress S vs the logarithm of the number N of cycles to failure for each of the specimens. The S parameter is generally taken as either maximum stress (σ max) or stress amplitude (σ a). Two unique types of S–N behavior are observed and are depicted schematically in Fig.1. As these charts illustrate, the higher the amplitude of the stress, the lower the number of cycles the material is capable of sustaining before failure. For some ferrous (iron-base) and titanium alloys, the S–N curve becomes horizontal at higher N values; there is a limiting stress level, called the fatigue limit (also often called the endurance limit), beyond which fatigue failure will not occur. This fatigue limit is the maximum value of variable stress that will not induce failure for virtually an unlimited number of cycles. For many steels, fatigue limits range between 35% and 60% of the tensile strength.

Most nonferrous alloys (e.g., aluminum, copper) do not have a fatigue limit, in that the S–N curve continues its downward trend at ever bigger N values. Thus, weariness finally develops regardless of the level of the stress. For these materials, the fatigue response is stated as fatigue strength, which is defined as the stress level at which failure will occur for some specified number of cycles (e.g., 107 cycles) Another key statistic that determines a material's fatigue behavior is fatigue life $N_{\rm f}$. It is the number of cycles required cause failure at a certain stress level, as taken from the S–N plot.

CONCLUSION

The study of failure in material science provides fundamental insights into the causes and mechanisms behind material failures. Through detailed investigation and examination of failed materials, it was revealed that failures can occur through many modes, including fracture, fatigue, creep, and corrosion.

Fracture failures often originate from high stress or load, leading to the separation of a material into two or more pieces. Understanding fracture behavior is critical in designing structures and components to prevent catastrophic failures. Fatigue failures, on the other hand, occur owing to recurrent cyclic loading, leading to increasing deterioration and eventual failure. Fatigue analysis is vital in forecasting the fatigue life of materials and assuring their reliability in applications subjected to cyclic loads. Creep failures occurs over time when a material suffers deformation under constant load or rising temperatures. The understanding of creep behavior is crucial in applications involving high temperatures and long-term exposure to continuous loads. Corrosion failures emerge from the chemical reactions between a material and its environment, resulting in the deterioration of material qualities. Preventive methods and material selection can be applied to mitigate corrosion-related failures.

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